

Table of Contents

Page	Title	Page	Title	Page	Title
01	Table of Contents	31	Debug mux	61	Discrete Load Switches
02	CHANGE HISTORY	32	Debug buttons	62	1.8VSB & Load SW
03	BLOCK DIAGRAM	33	SW Debug Conn	63	CHARGER
04	CLOCK DISTRIBUTION	34	EE Debug Connector	64	5V Load SW
05	SYSTEM POWER STATE DIAGRAM	35	SM BUS, DIAGNOSTIC CONN	65	3P3V Load SW
06	POWER DISTRIBUTION	36	Power Monitor	66	VCPU Controller
07	INPUT POWER DIAGRAM	37	SPI ROM UEFI	67	VCORE VCCSA
08	POWER SYSTEM/CONTROL DIAG	38	TPM	68	VCVGT
09	I2C MAP	39	Temp Sensor/System Fan	69	SL Power
10	CPU(1)_MISC,JTAG,DDI.EDP	40	REALTEK ALC3269 CODEC	70	BATT CONN, power input
11	CPU(2)_LPDDR3	41	Audio Jack/Spkr	71	Empty
12	CPU(3)_SKL POWER1	42	Audio Amplifier	72	LCD backlight/TB
13	CPU(4)_SKL POWER2	43	SSD page 1	73	Empty
14	CPU(5)_GND	44	SSD Page 2	74	Empty
15	CPU(6)_CFG RESERVED	45	USB3.0, TYPE A	75	Empty
16	LPDDR3(1)_MEMORY DOWN	46	SL HDMI MUX/3P3V_HPDP	76	TP's and Mech
17	LPDDR3(2)_MEMORY DOWN	47	SurfLink Connector		
18	XDP	48	BLADE		
19	LPDDR3(3)_CA/DQ Voltage	49	G5 touch circuitry		
20	PCH(1)_SD,HDA,RTC, CLK	50	Wi-Fi_BT		
21	PCH(2)_CLK,SMB,LPC, SPI	51	Empty		
22	PCH(3)_SYS PWR CONTR	52	Empty		
23	PCH(4)_CCI, HWID	53	mDP		
24	PCH(5)_PCIE,USB	54	Camera/Sensor Conn.		
25	PCH(6)_CPU,GPIO,MISC	55	eDP connector		
26	PCH(7)_POWER	56	3P3VA & Reset		
27	SAM_1, K22	57	VCCEDRAM & VCCEOPIO		
28	SAM_2, K22	58	PMIC 1		
29	SAM_3, K22	59	PMIC 2		
30	INSTANT_ON	60	PMIC 3		

MTP	MTE	bottom side, 22mil
TP	EE/SW debug	top side, 22mil
XDP_TP	Intel requested	don't care, 22mil
GTP	Unused IO and GPIO/ Possible for Future Removal	don't care, 22mil
PTP	Current Sensing	top side ( as close to resistor as possible), 22mil
MTP_BF	MTE big pads for FW, OS load, and RF.	bottom side, 31mil
MTTP_BF	MTE big pads for RF	top side, 31mil (if RF connector at the bottom side of the board)

CAD Note:

Default component footprint is SMD 0201, X5R, 1% resistors.

Property: BUILD-OPT  
DNP = Do Not Place

S or DB = Replace after Debug

Title: 01. Table of Contents		
Microsoft Confidential		Engineer: Surface
Size A3	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 1	of 79

# Schematics Change History

Schematics Change is maintained in spreadsheet, and would not fit on this page.

## CAD Note:

Default component footprint is SMD 0201, X5R, 1% resistors                      S = Short after design fixed

Property: BUILD-OPT

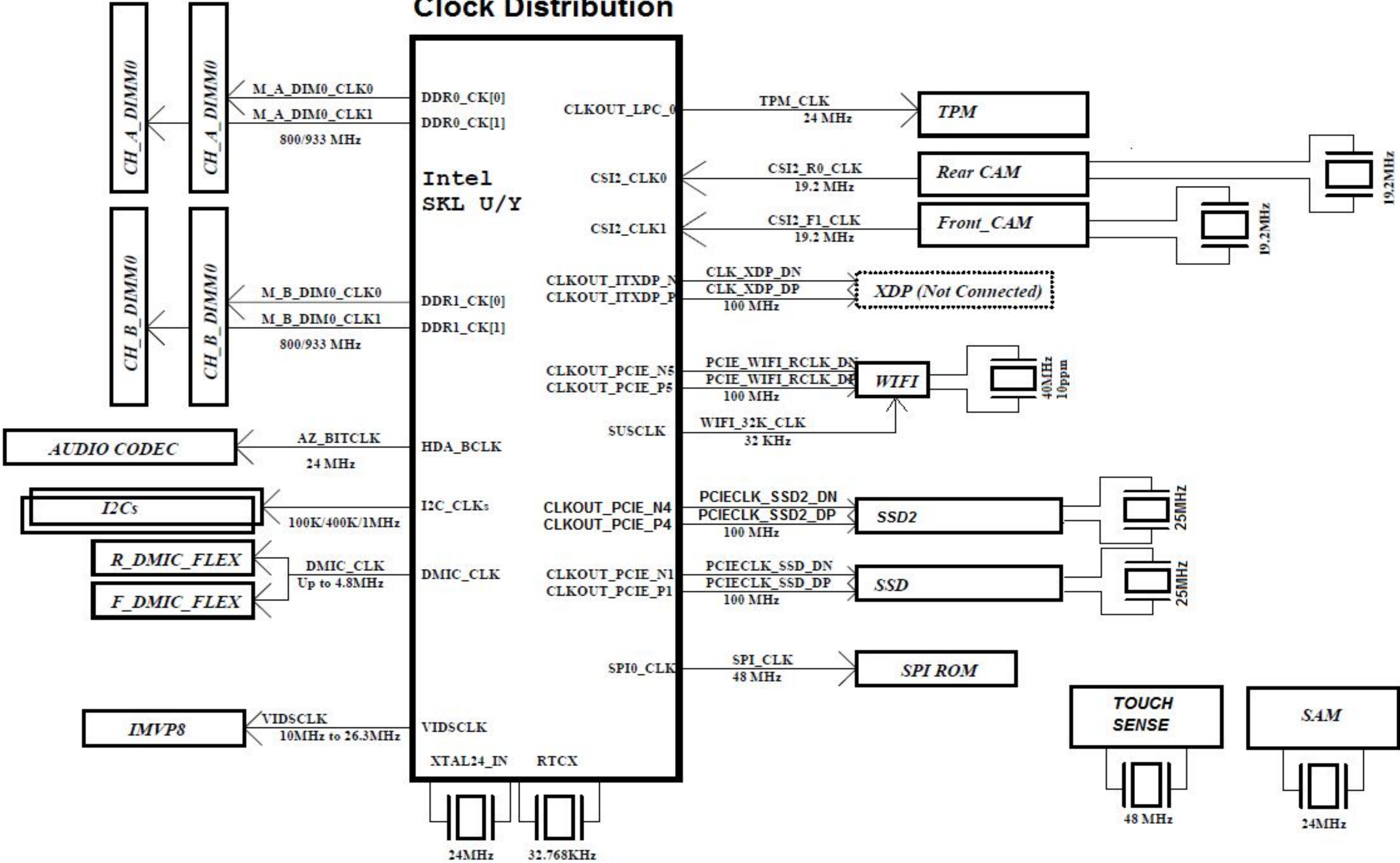
DNP = Not Installed Part.

Title: 02. CHANGE HISTORY		
Microsoft Confidential		Engineer: Surface
Size A3	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 2 of 79	



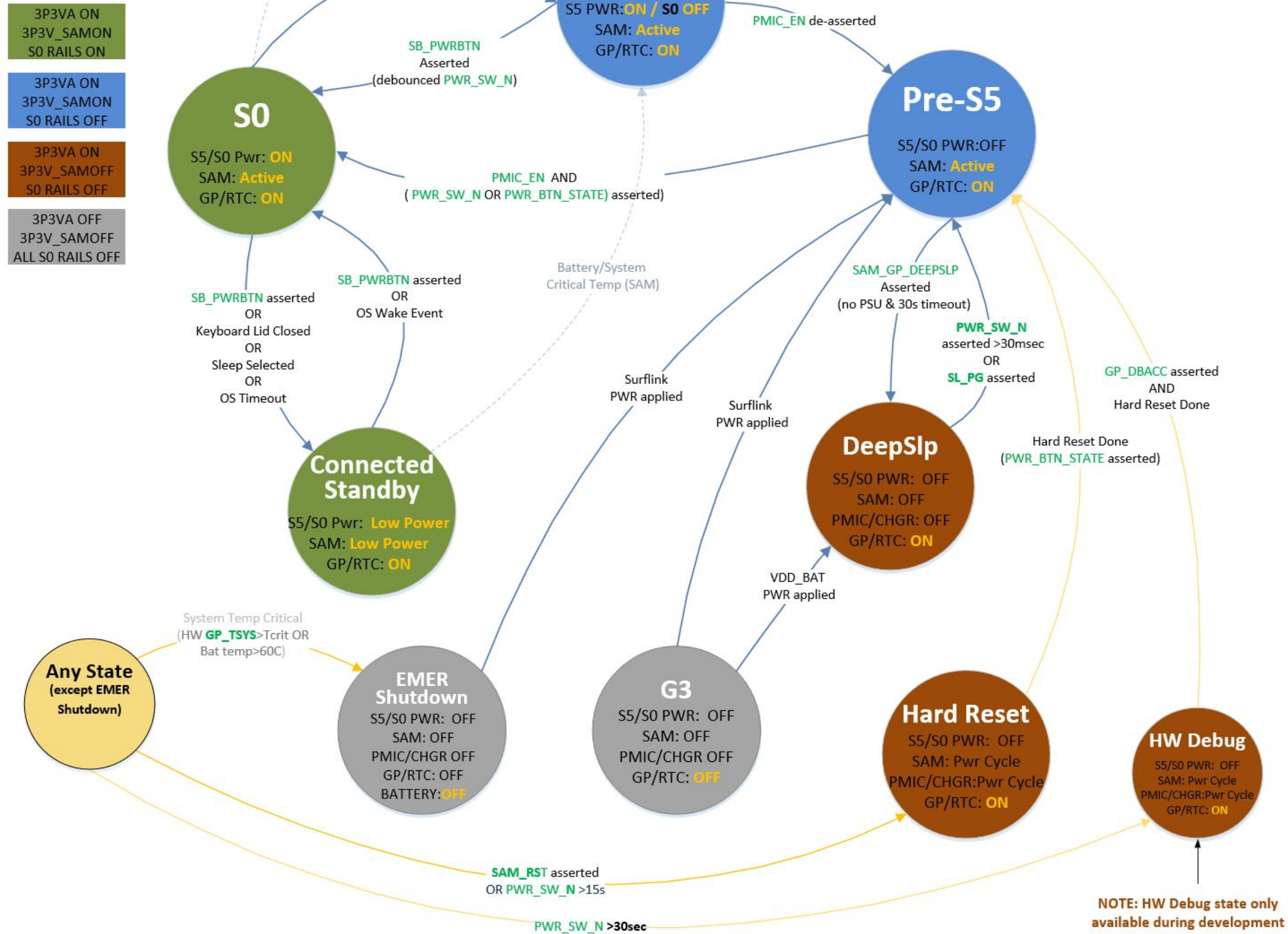


Clock Distribution

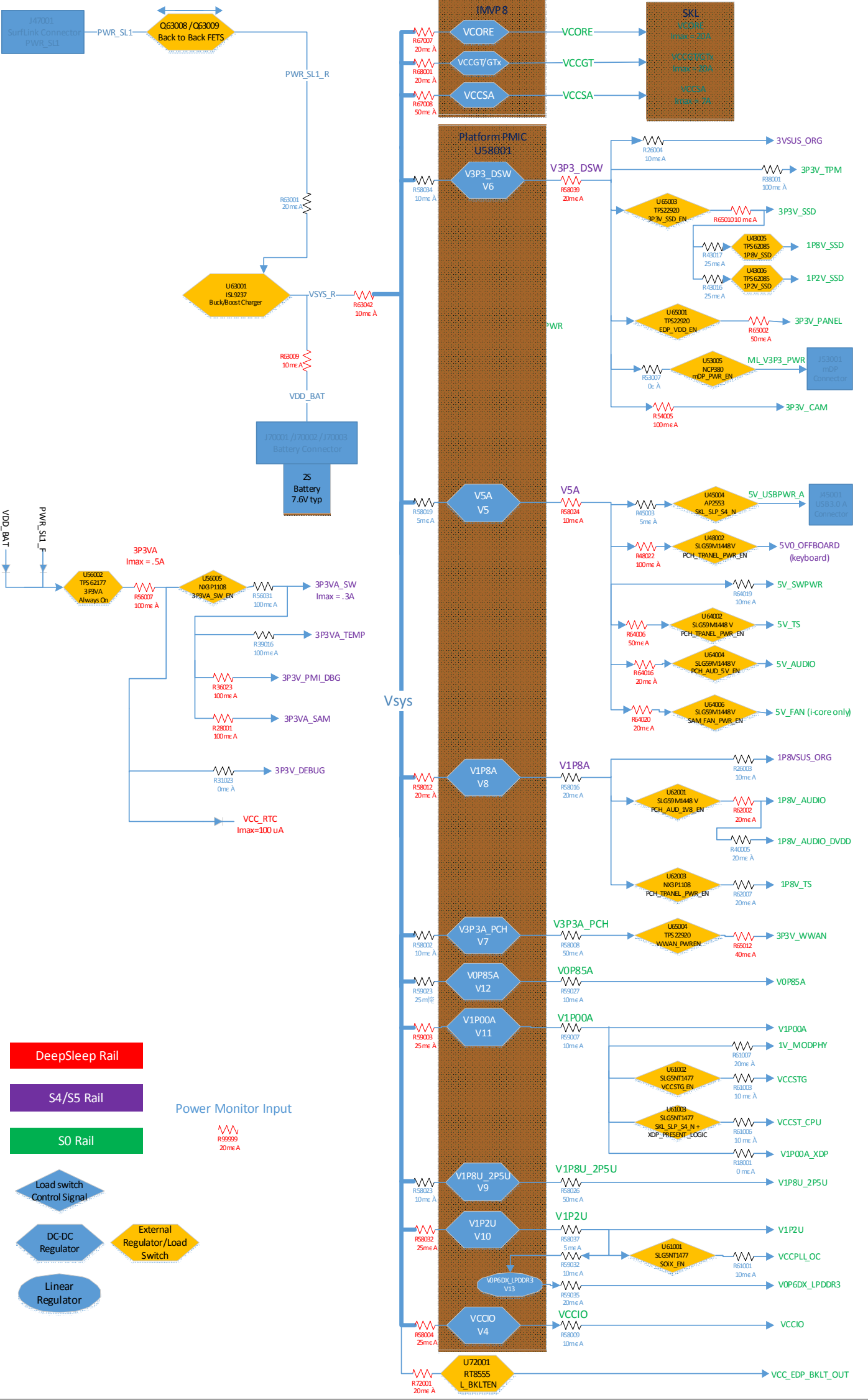


# System Power State Diagram

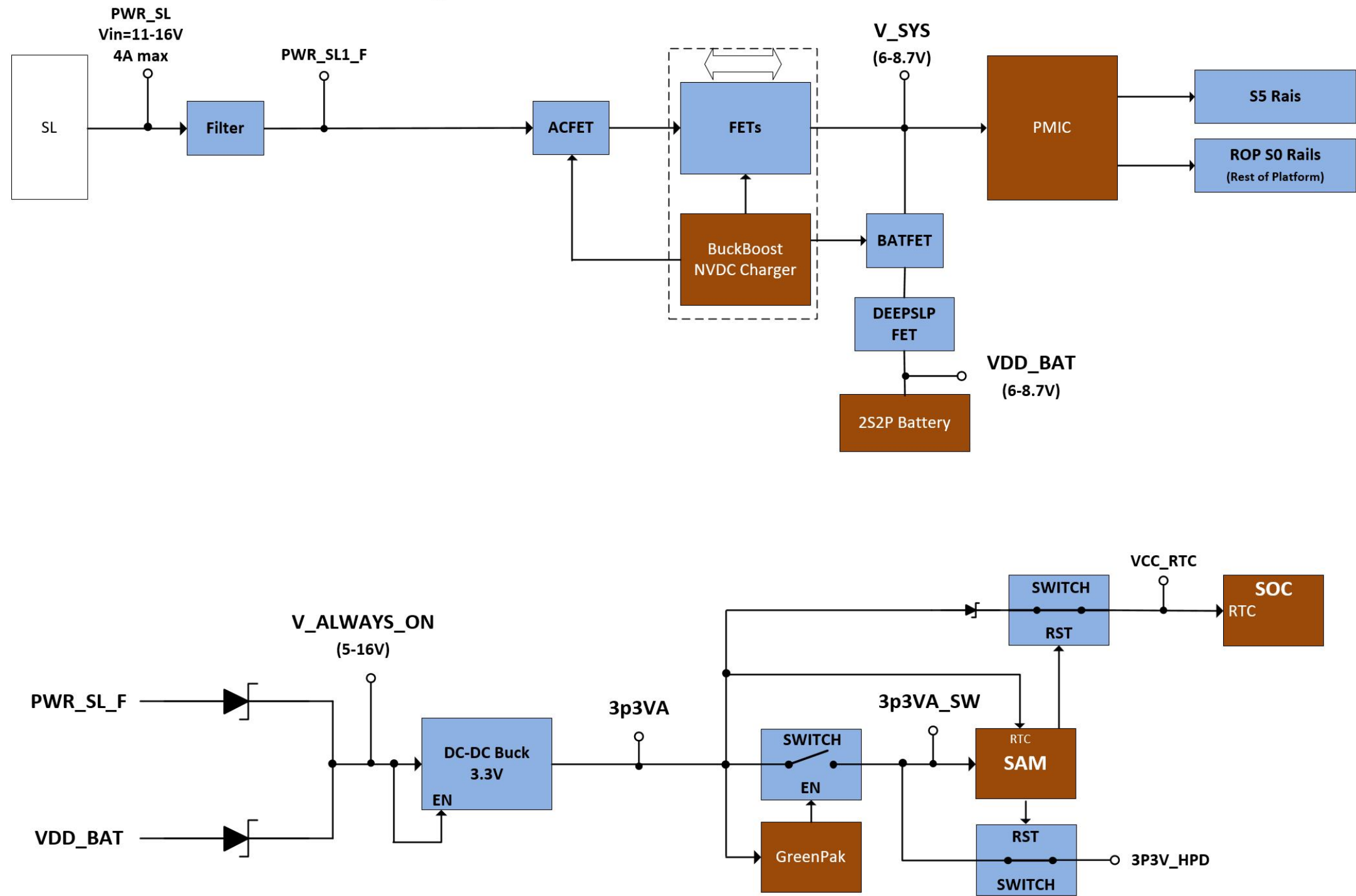
Microsoft Confidential



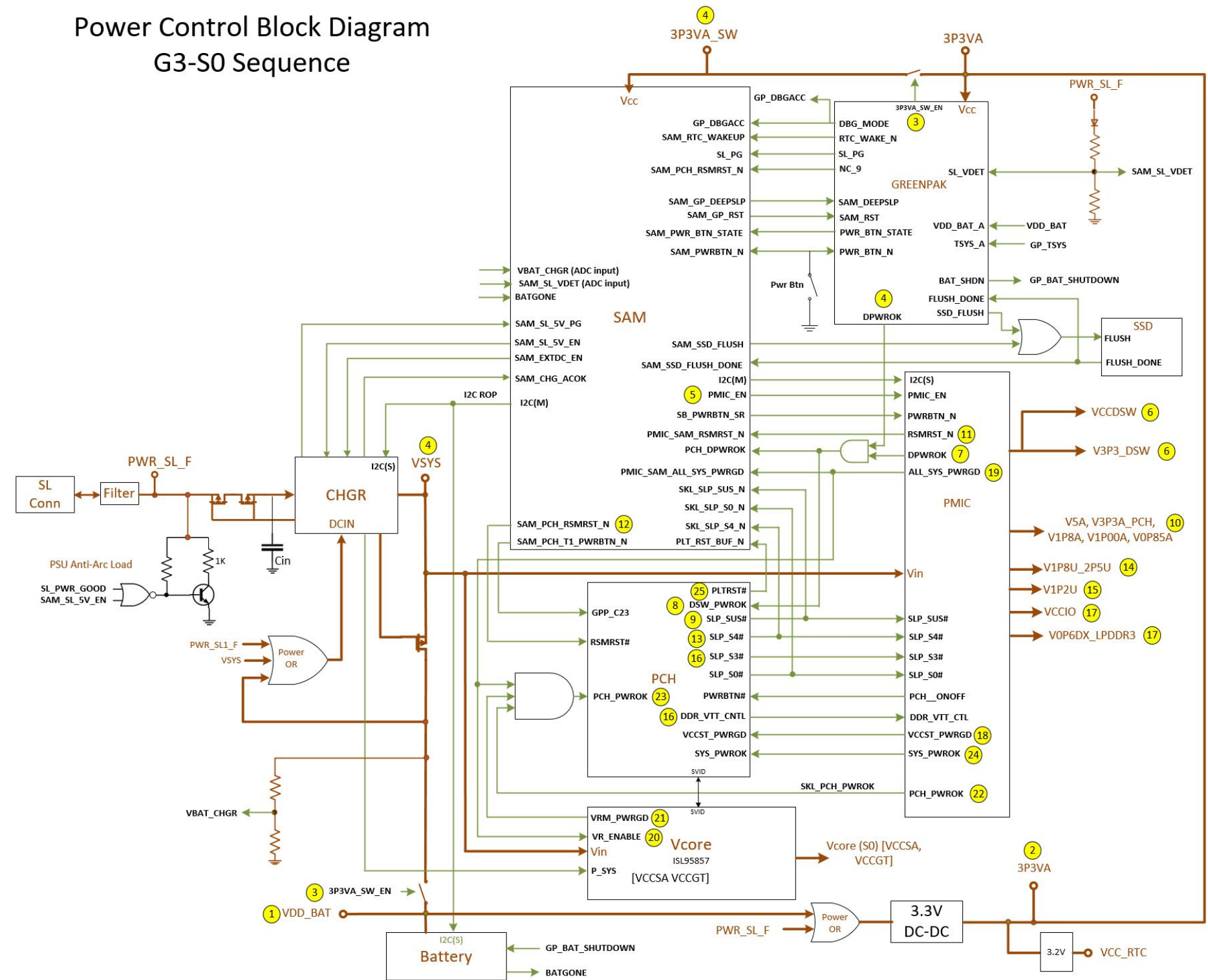




# Lynx SL INPUT POWER DIAGRAM



Power Control Block Diagram  
G3-S0 Sequence

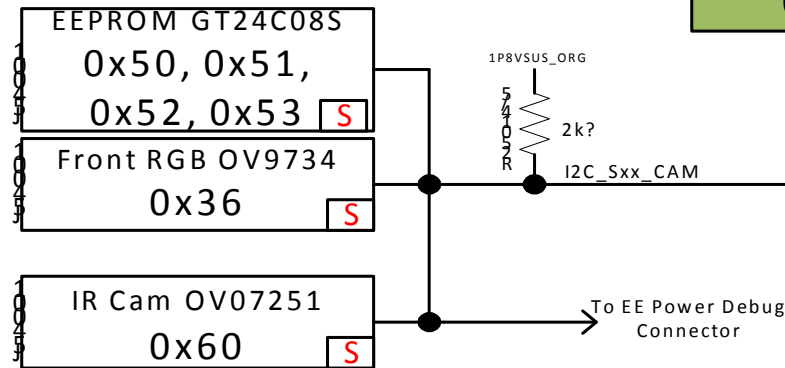




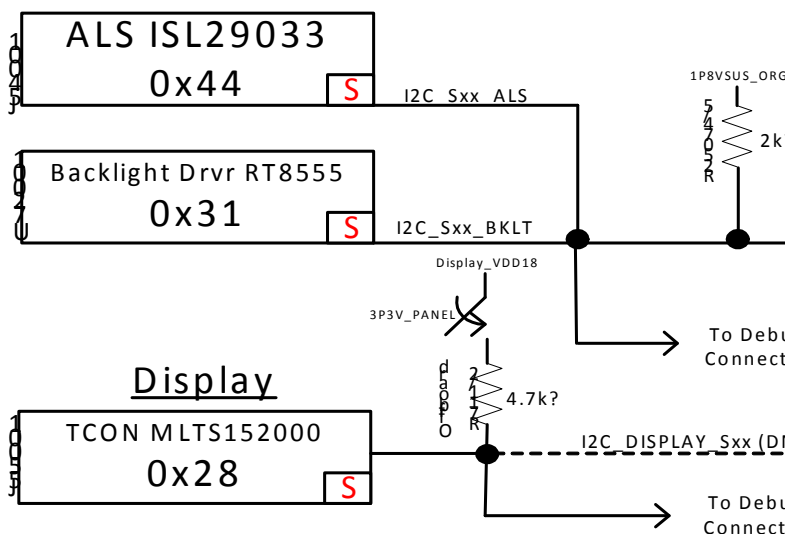
# I2C Map

7-bit slave addresses  
September 28, 2016

## Cameras

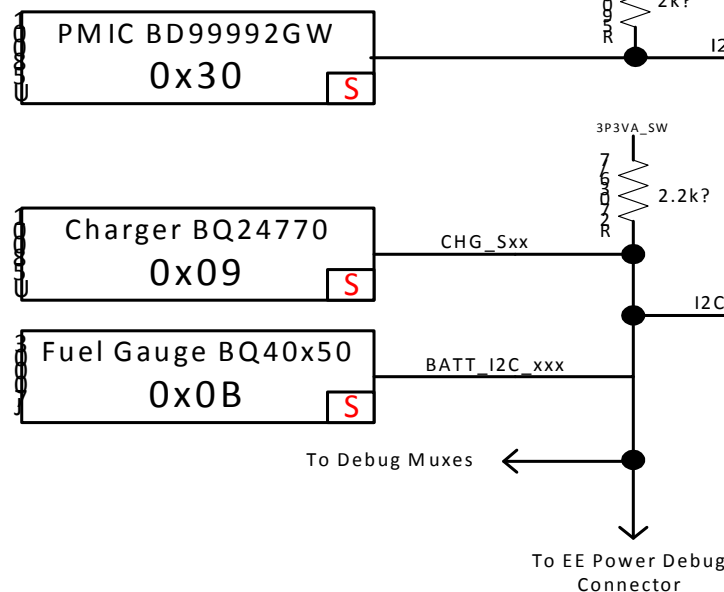


## Light Sensor and BKLT Controller

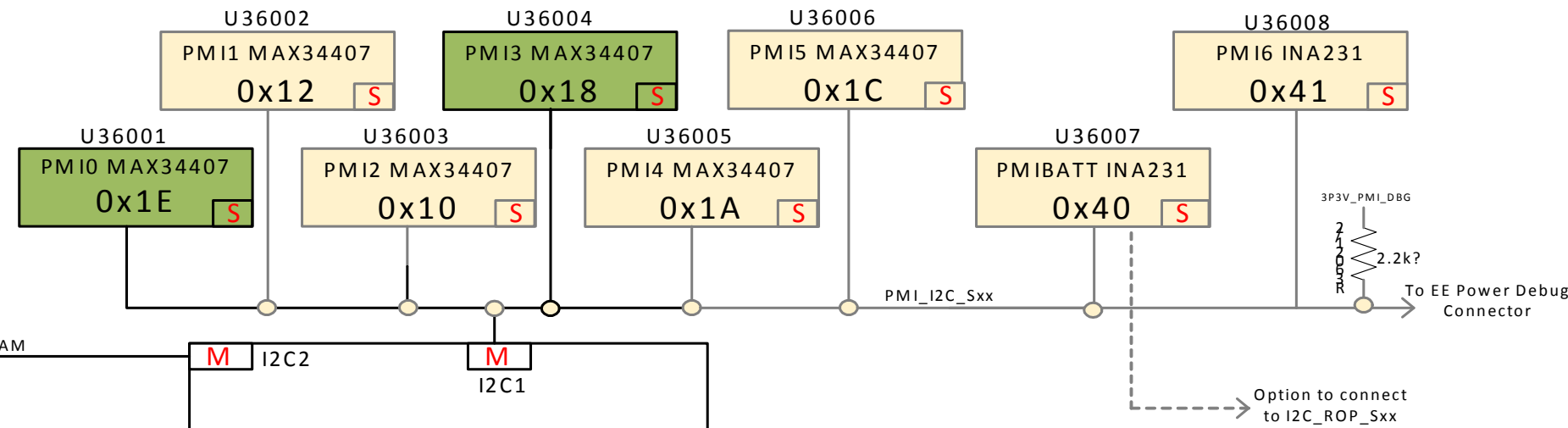


## Display

## Power Management



## DEBUG: Power Monitors



## Debug Connector

## EE Power Debug Connector

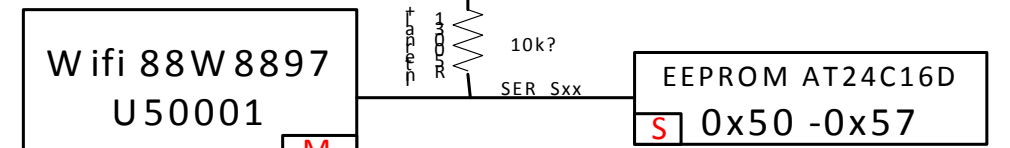
## Debug Muxes

## Removed in Retail

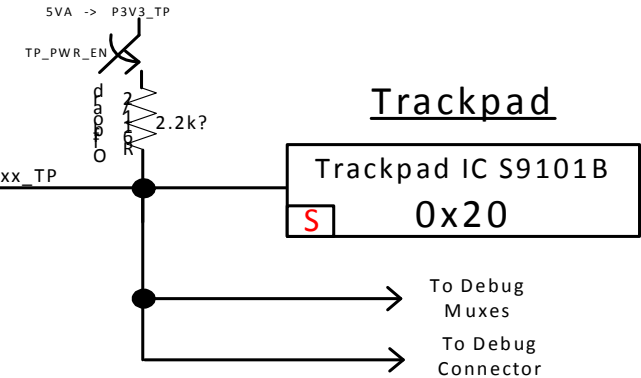
## DEBUG\_OSG in Retail

## DNP in Non-Retail/Retail

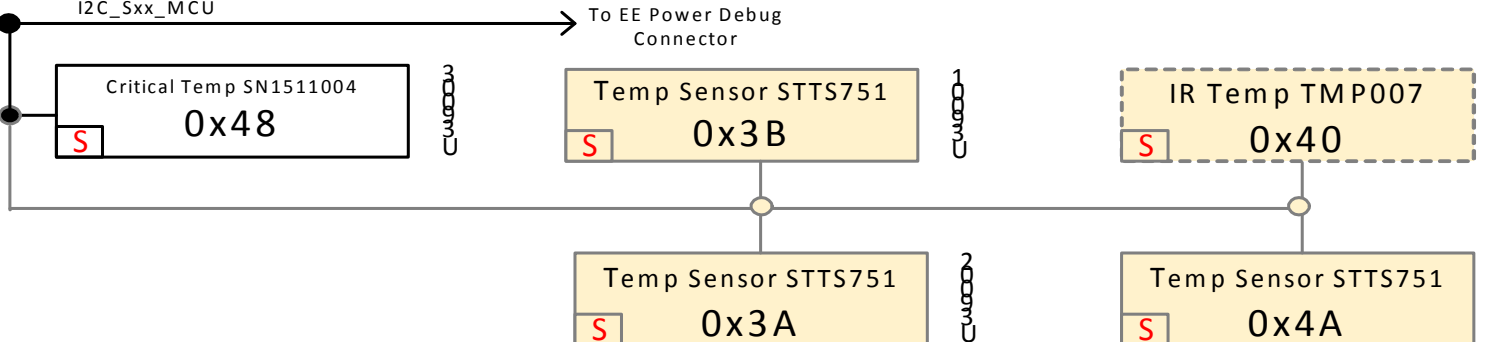
## Wifi/BT



## Trackpad

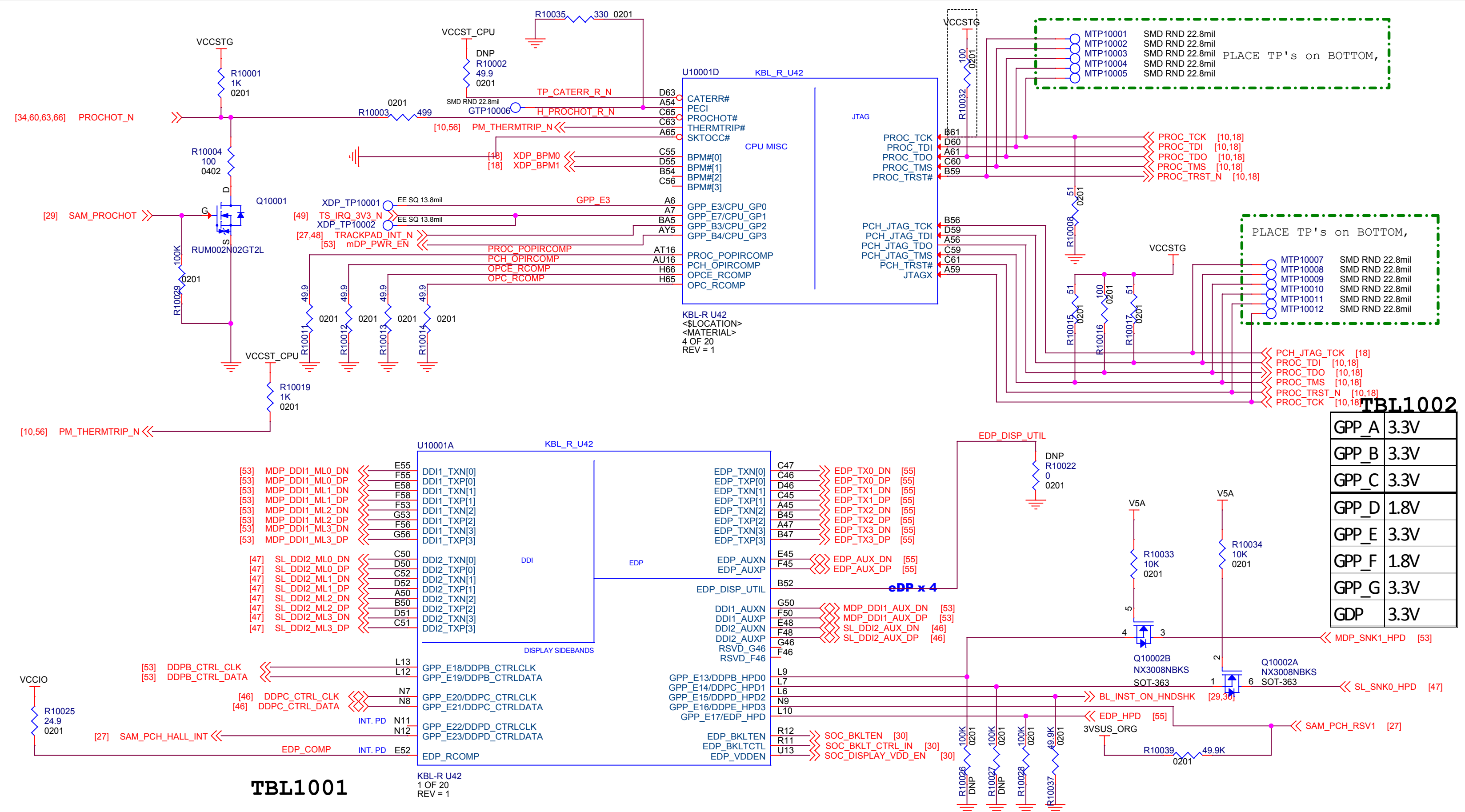


## Temp Sensors



DV17U7660s16s512x2Retail

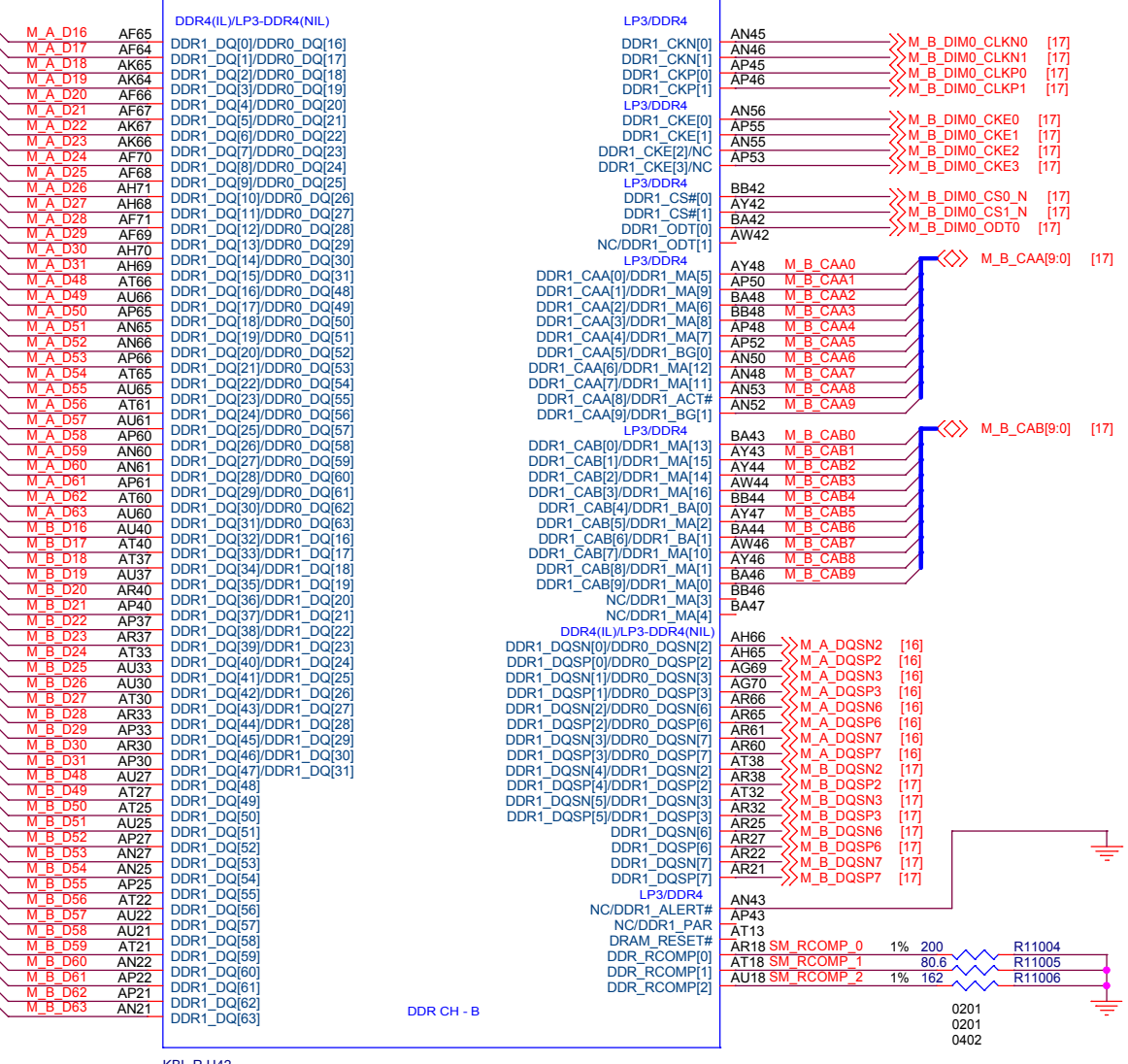
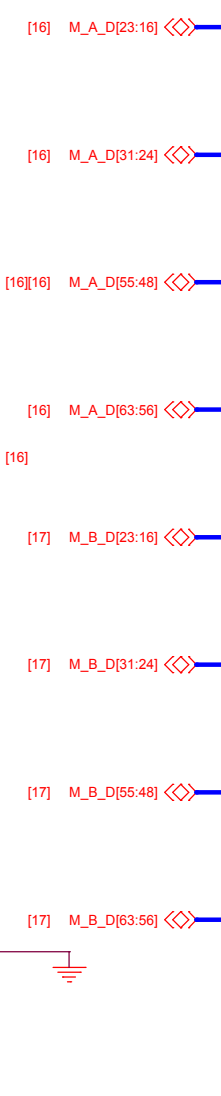
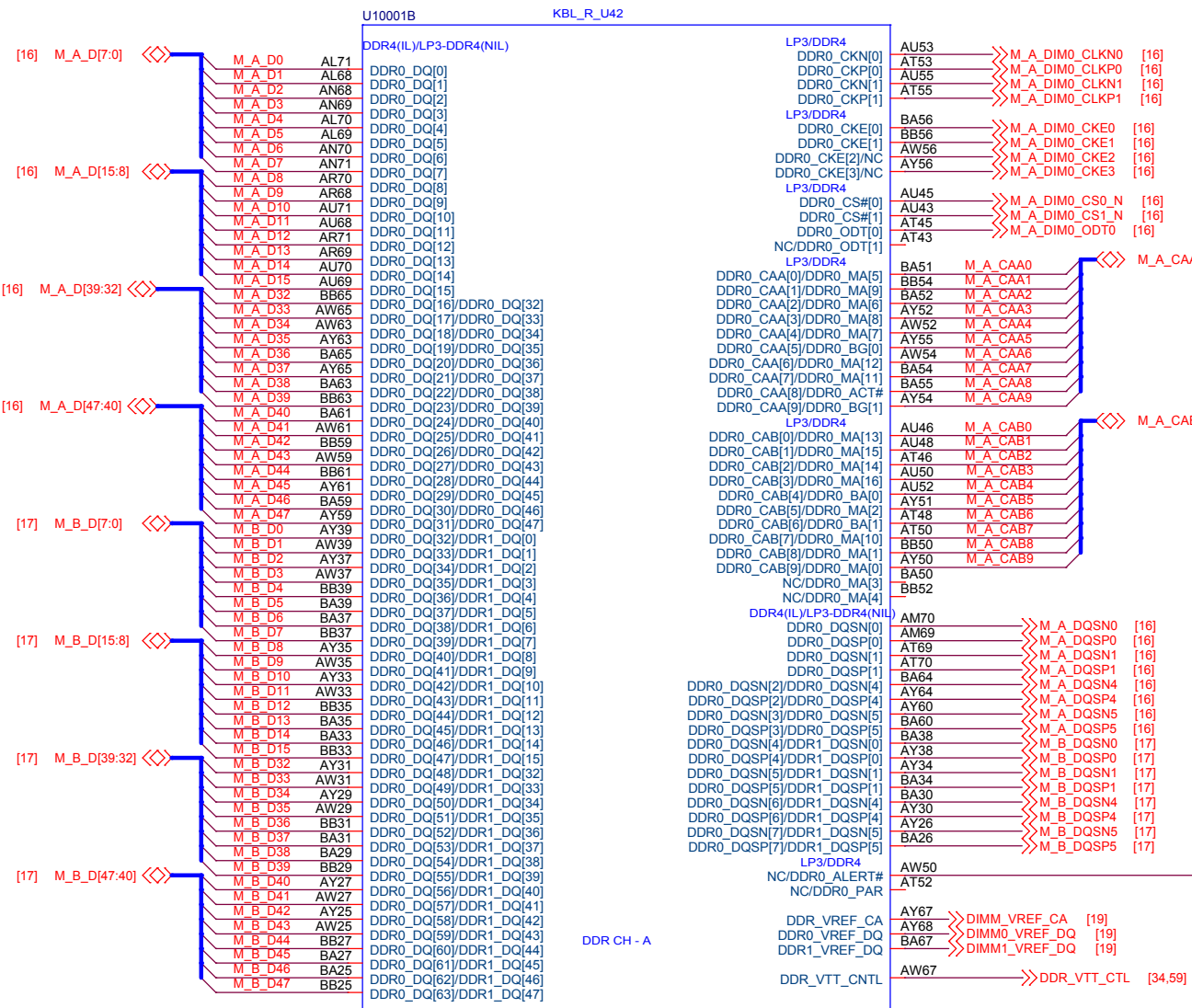
Title: 09. I2C MAP	
Microsoft Confidential	
Size A3	Project Name A
Date: Thursday, April 26, 2018	Rev 1.0.0.1
Sheet 9	of 79



BoardID	description	CPU	stuff(all)	No-Stuff
000	reserved		R23040, R23042, R23044	R23041, R23043, R23045, R28091, R28092, R28093
001	reserved		R23041, R23042, R23044, R28091	R23040, R23043, R23045, R28093, R28092
010	KBL U42 i5-8250U	M1086844-00	R23040, R23043, R23044, R28092	R23041, R23042, R23045, R28093, R28091
011	reserved		R23041, R23043, R23044, R28091, R28092	R23040, R23042, R23045, R28093
100	KBL U42 i5-8350U	M1029639-001	R23040, R23042, R23045, R28093	R23041, R23043, R23044, R28091, R28092
101	reserved		R23041, R23042, R23045, R28093, R28091	R23040, R23043, R23044, R28092
110	KBL U42 i7-8650U	M1020597-001	R23040, R23043, R23045, R28093, R28092	R23041, R23042, R23044, R28091
111	reserved		R23041, R23043, R23045, R28091, R28092, R28093	R23040, R23042, R23044

U SPECIFIC

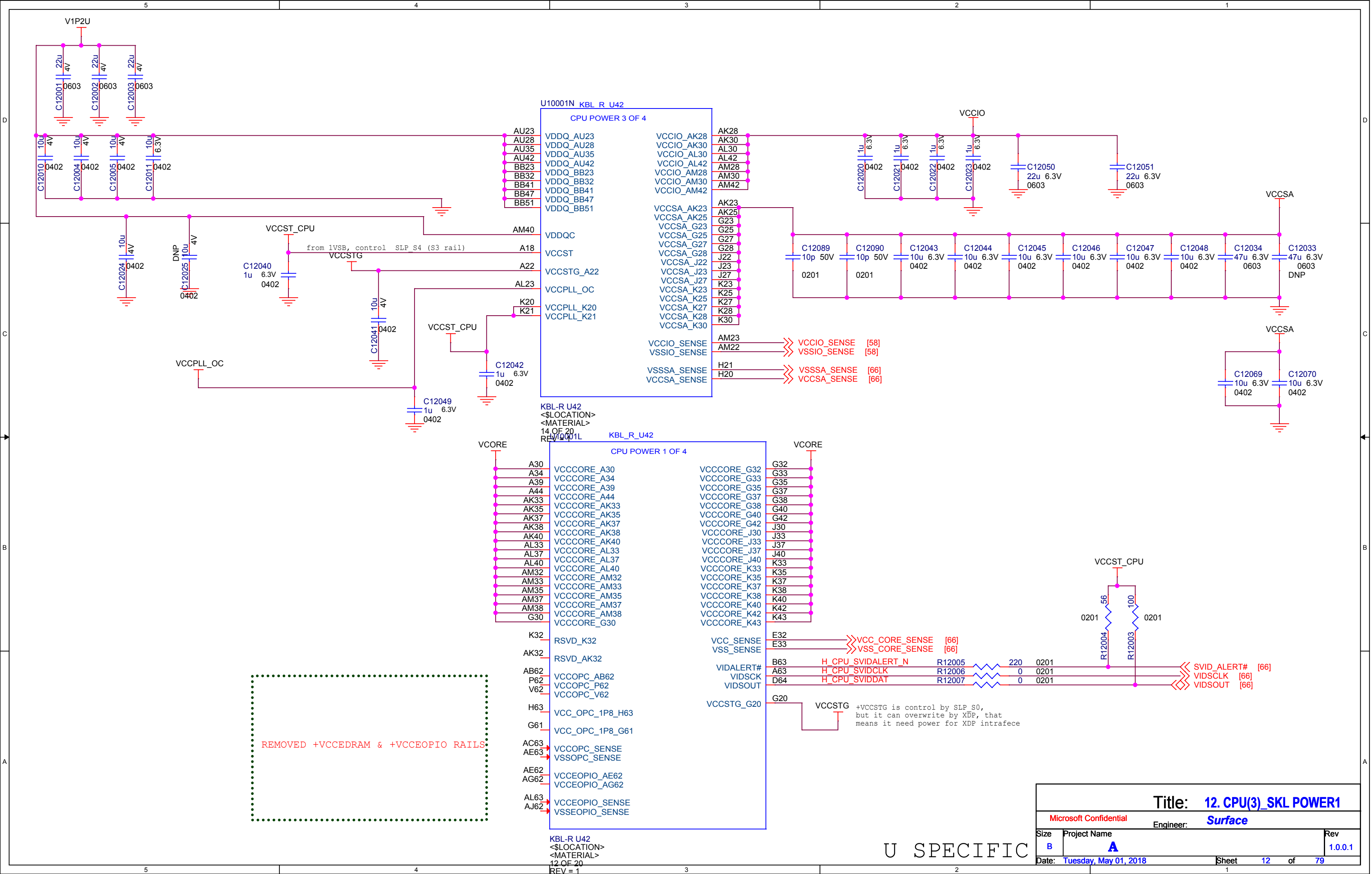
Title: 10. CPU(1)_MISC,JTAG,DDI,EDP		
Microsoft Confidential Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Friday, April 27, 2018	Sheet 10	of 79



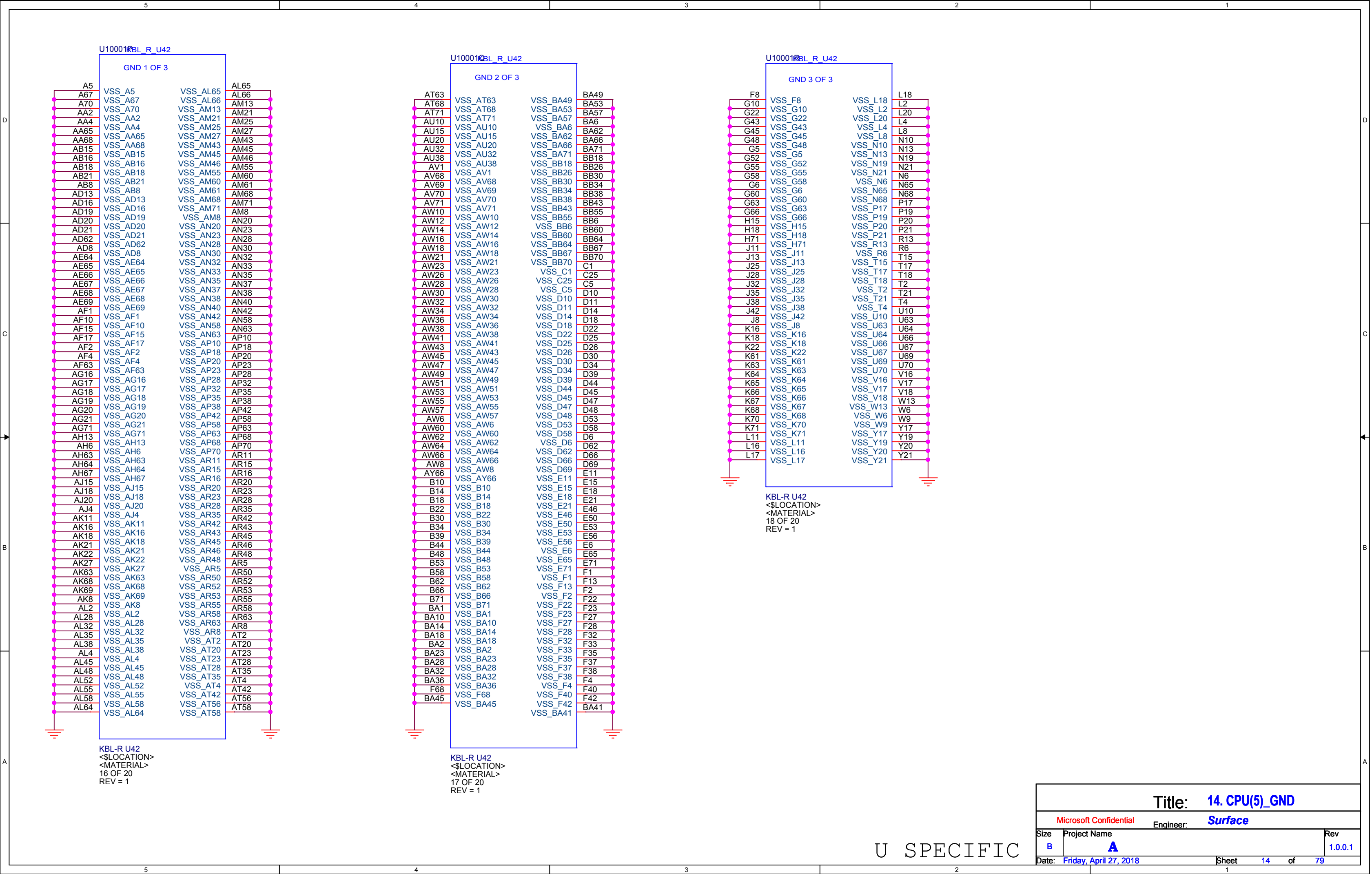
KBL-R U42  
<LOCATION>  
<MATERIAL>  
2 OF 20  
REV = 1

KBL-R U42  
<LOCATION>  
<MATERIAL>  
3 OF 20  
REV = 1







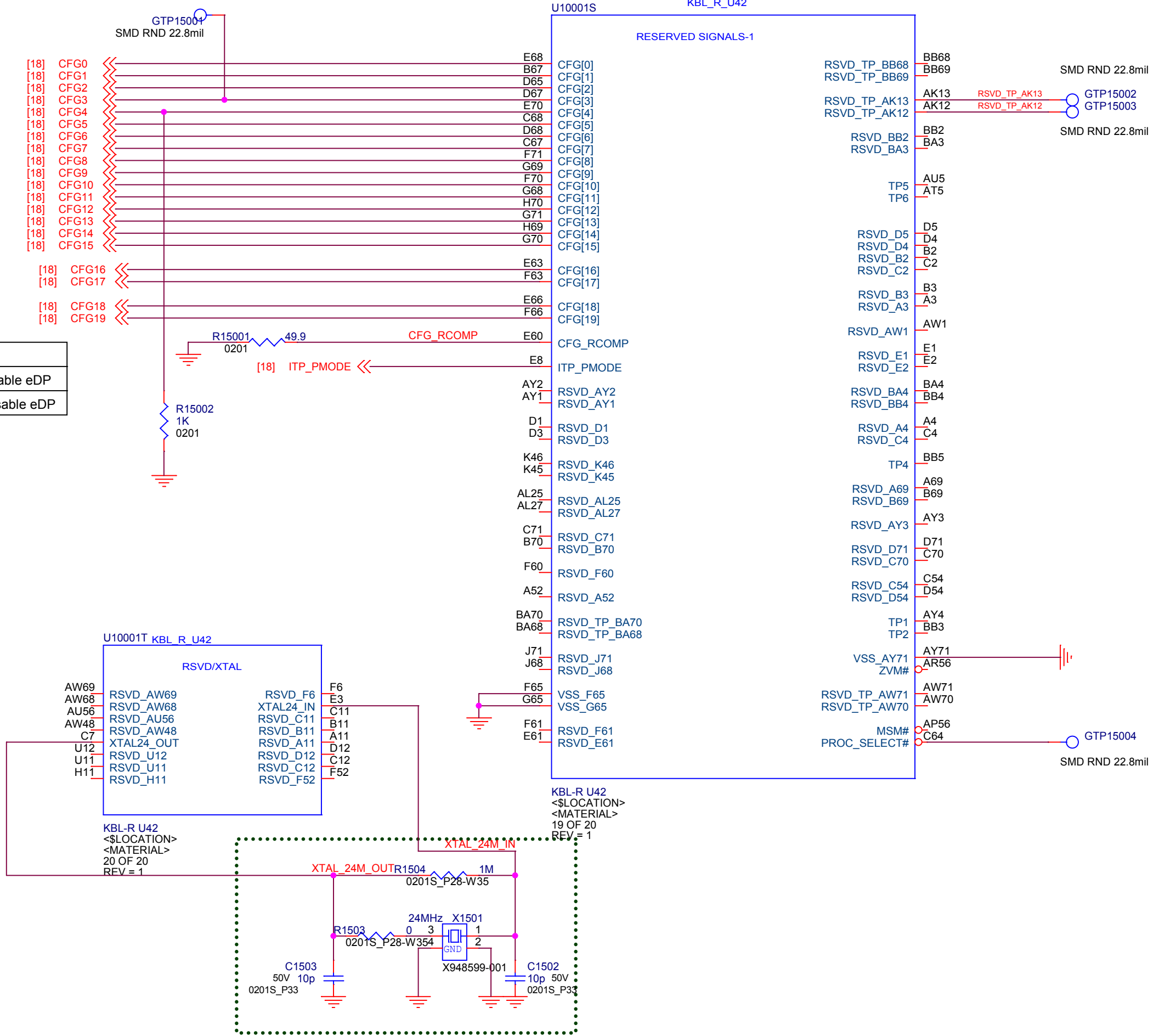


U SPECIFIC

Title: 14. CPU(5)_GND		
Microsoft Confidential		
Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Friday, April 27, 2018	Sheet 14 of 79	



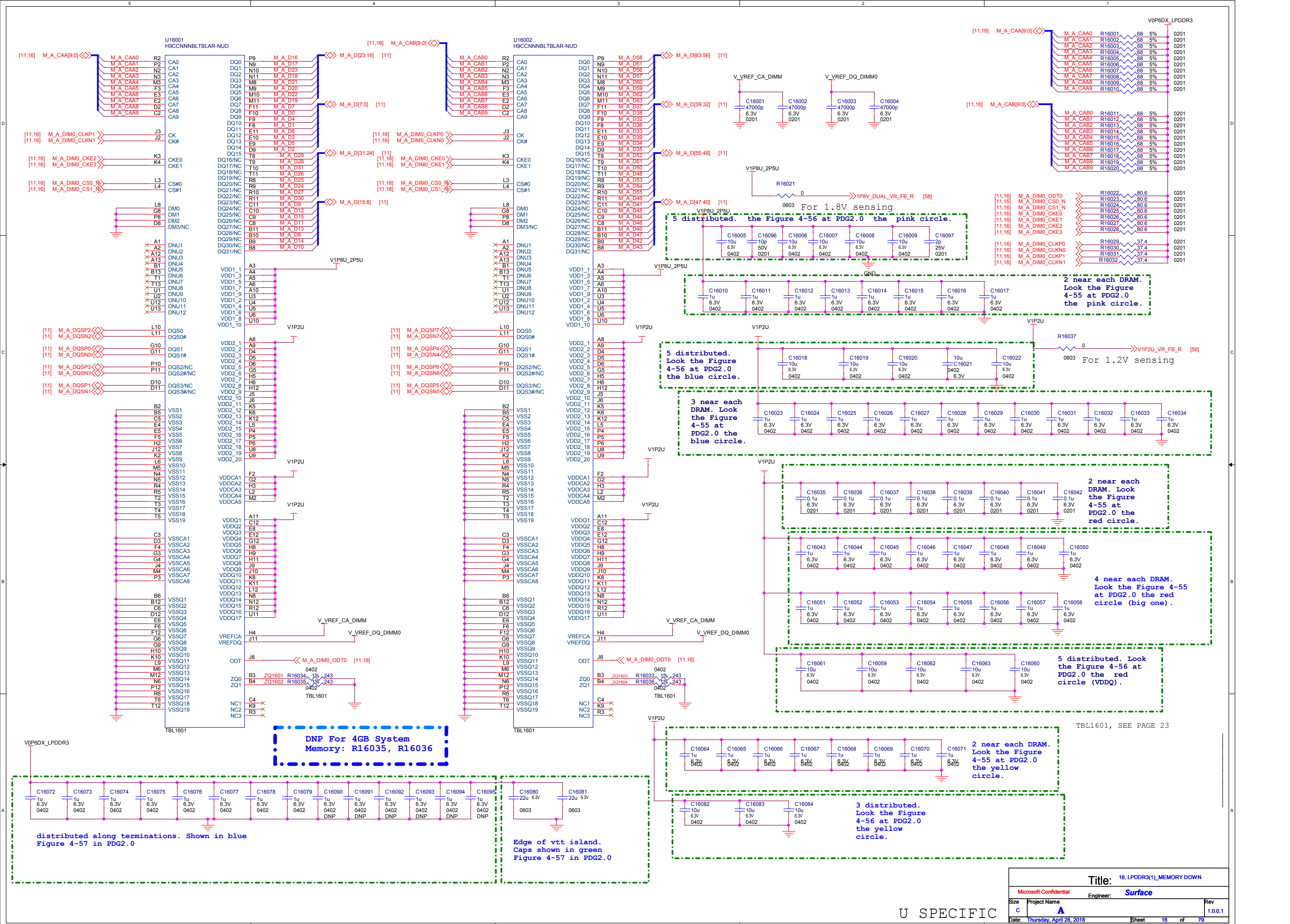
CFG4	
0 Default	enable eDP
1	Disable eDP



ZVM# and MSM# may need to control the VCCOFC and VCCBOPIO

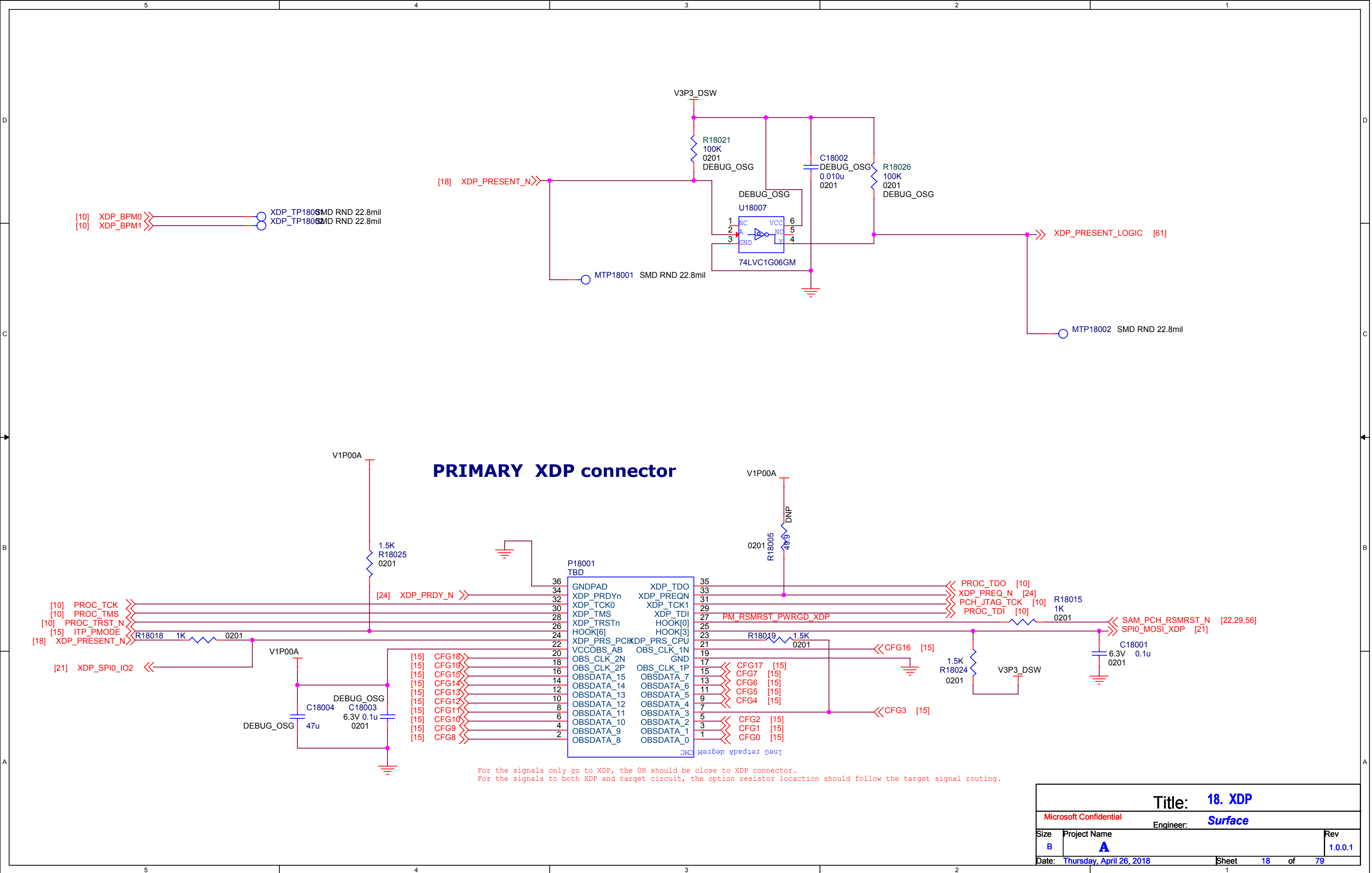
Title: 15. CPU(6)_CFG_RESERVED		
Microsoft Confidential		Engineer: Surface
Size B	Project Name A	Rev 1.0.0.1
Date: Friday, April 27, 2018	Sheet 15 of 79	

U SPECIFIC



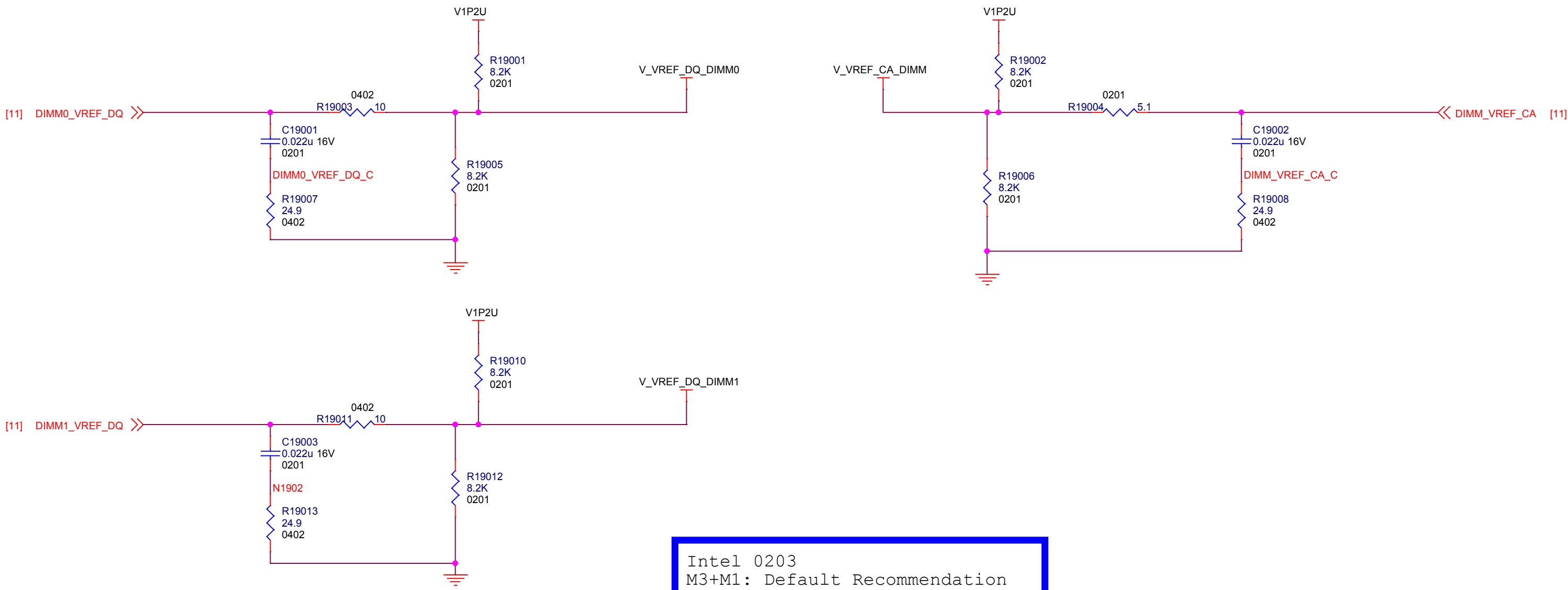




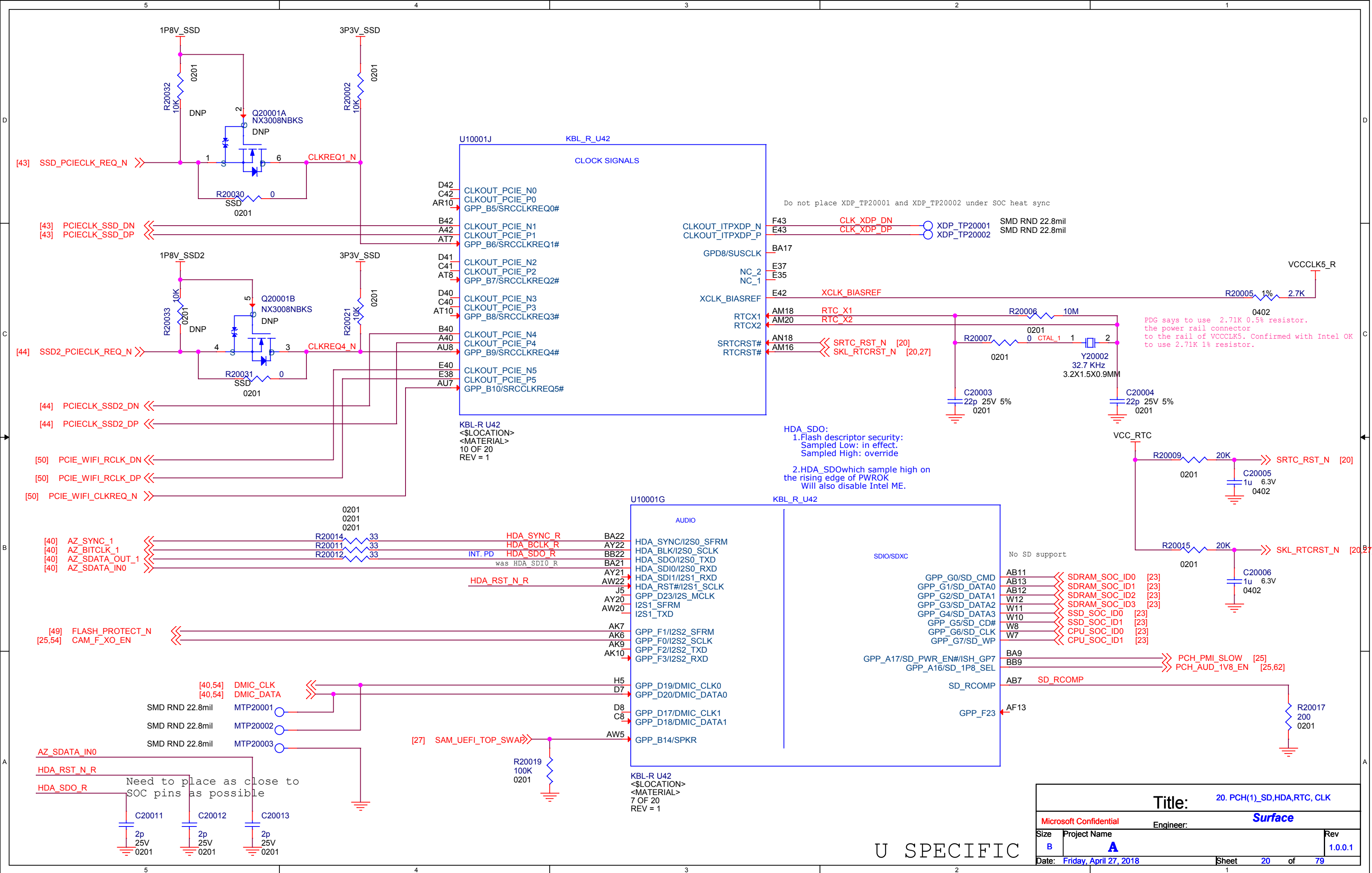


# LPDDR3 Vref

M3: CPU driven VREF path is stuffed by default.  
M1: VREF\_DQ driven by a Voltage Divider Network during Processor power-off

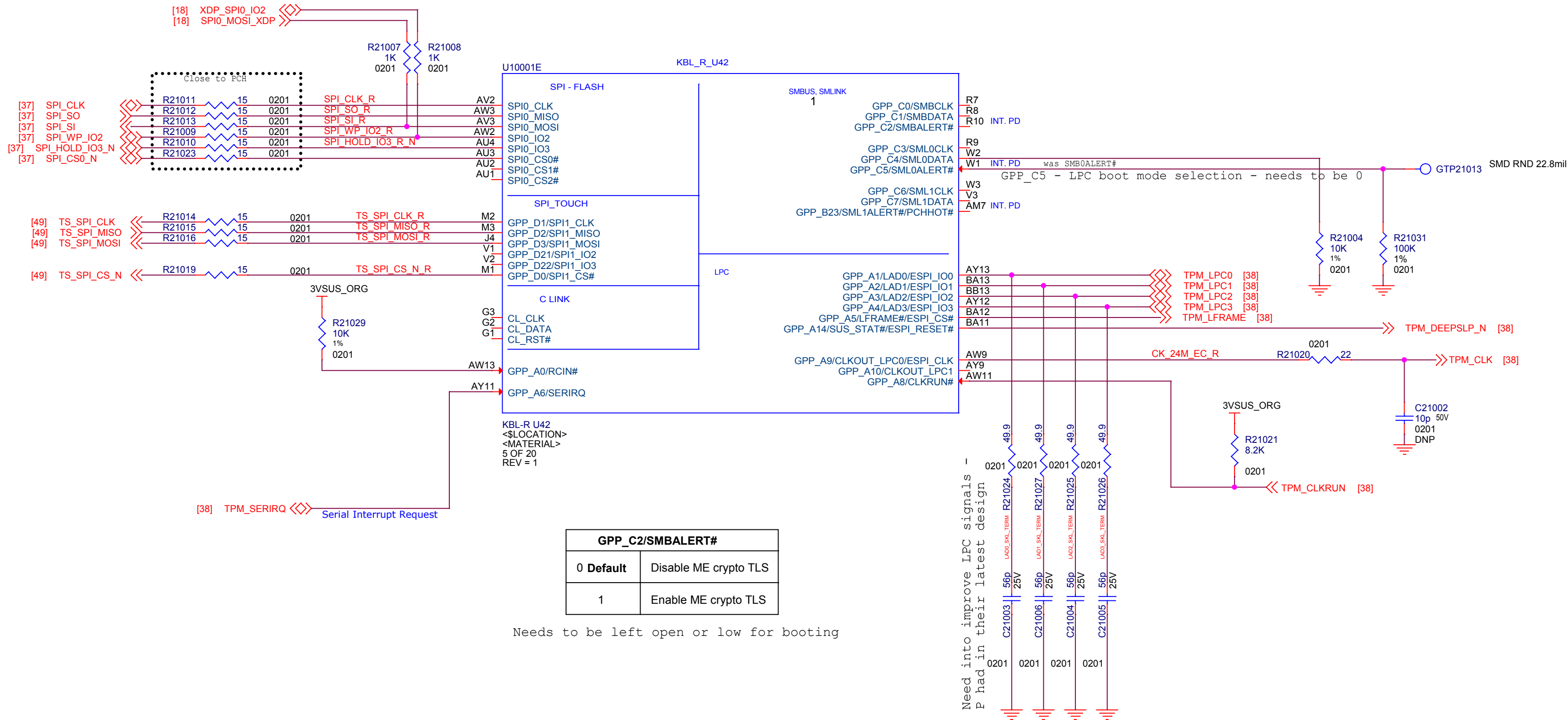


Title: 19. LPDDR3(3)_CA/DQ Voltage		
Microsoft Confidential		
Engineer: Surface		Rev
Size B	Project Name A	1.0.0.1
Date: Thursday, April 26, 2018	Sheet 19 of 79	





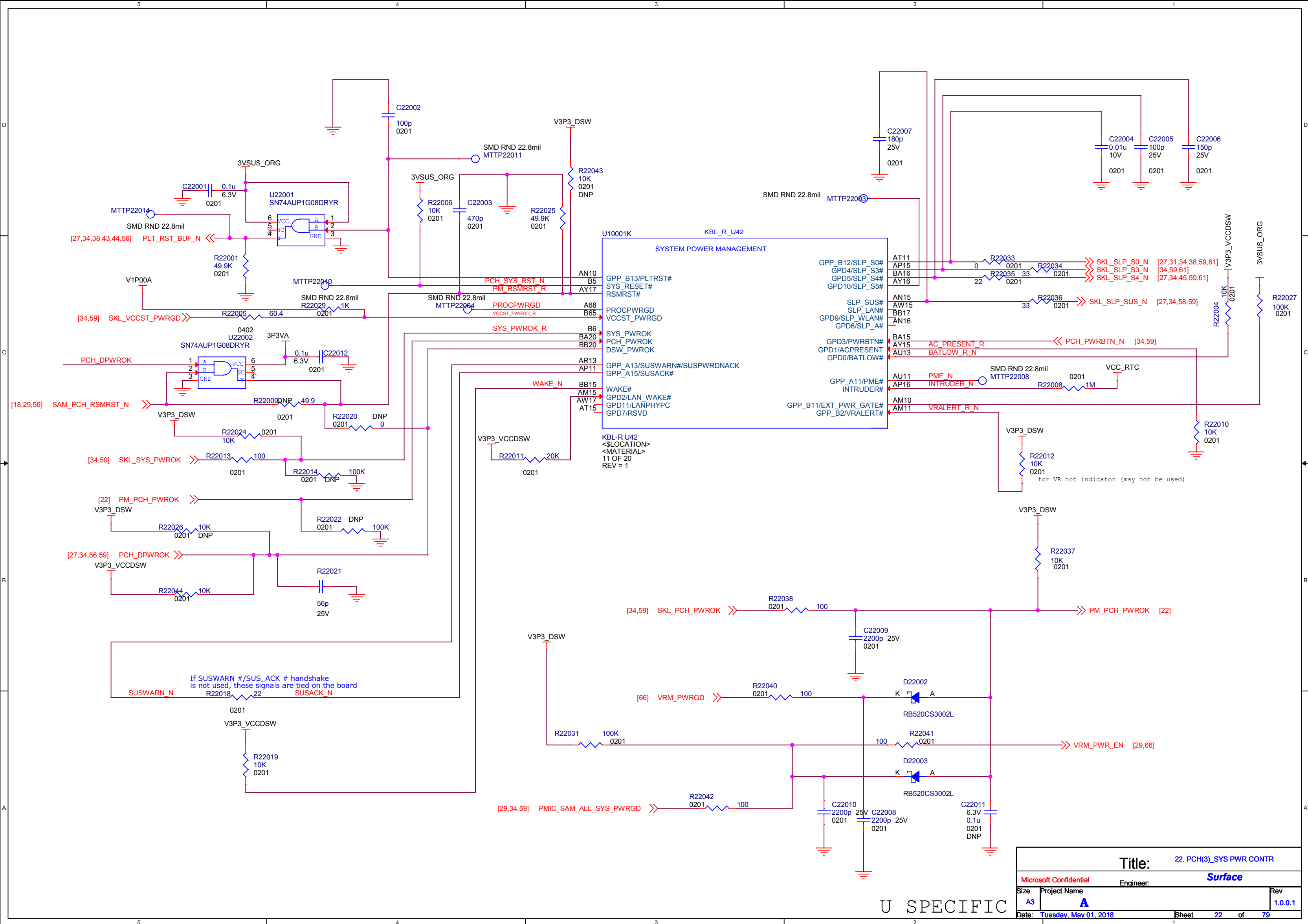
Connected to device.  
Default : Clock free run. (PD 10K).  
Reserver 10K PU for power saving purpose.



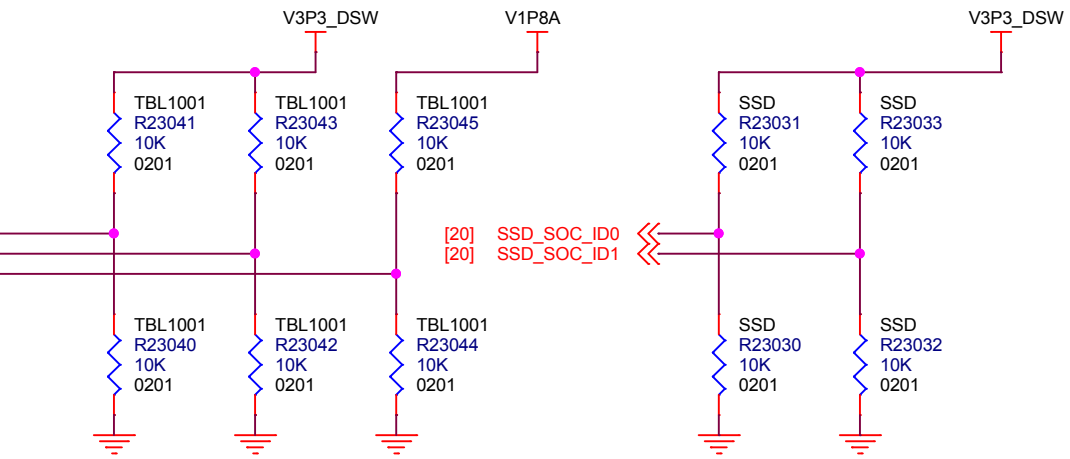
Need into improve LPC signals  
P had in their latest design

U SPECIFIC

Title: 21. PCH(2)_CLK,SMB,LPC, SPI		
Microsoft Confidential		Engineer: Surface
Size B	Project Name A	Rev 1.0.0.1
Date: Friday, April 27, 2018	Sheet 21	of 79



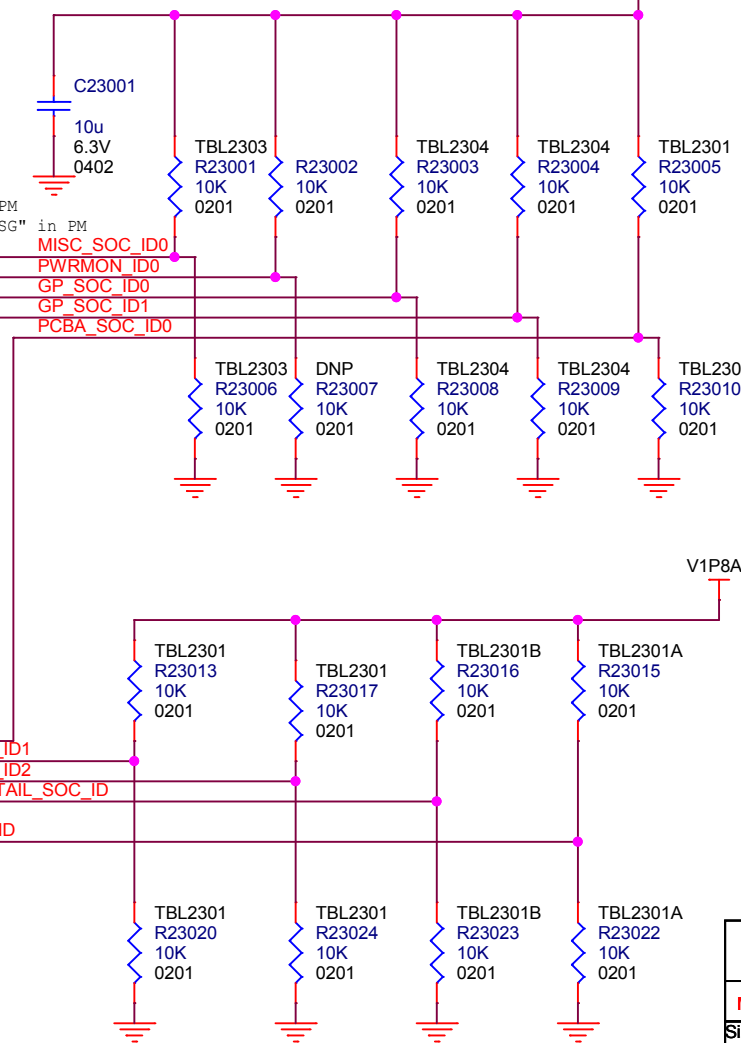
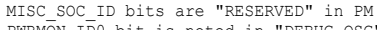
TBL2301	PCBA vendor and revision
R23010, R23020, R23024	Revision EV2P5
R23005, R23013, R23017, R28051, R28052, R28053	NO-STUFF FOR REVISION
R23005, R23020, R23024, R28051	Revision EV2P51
R23010, R23013, R23017, R28052, R28053	NO-STUFF FOR REVISION
R23010, R23013, R23024, R28052	Revision DV
R23005, R23020, R23017, R28051, R28053	NO-STUFF FOR REVISION
R23005, R23013, R23024, R28051, R28052	Revision DV1.01
R23010, R23020, R23017, R28053	NO-STUFF FOR REVISION
R23010, R23020, R23017, R28053	Revision DV1.1, DV1.2, FV
R23005, R23013, R23024, R28051, R28052	NO-STUFF FOR REVISION
R23005, R23020, R23017, R28051, R28053	Lacey EV1
R23010, R23013, R23024, R28052	NO-STUFF FOR REVISION
R23010, R23013, R23017, R28052, R28053	Reserved
R23005, R23020, R23024, R28051	NO-STUFF FOR REVISION
R23005, R23013, R23017, R28051, R28052, R28053	Reserved
R23010, R23020, R23024	NO-STUFF FOR REVISION



BoardID	SSD vendor	stuff	No-Stuff
00	Toshiba SSD	R23030, R23032	R23031, R23033, R28081, R28082
01	SAMSUNG SSD	R23031, R23032, R28081	R23030, R23033, R28082
10	INTEL PS SSD	R23030, R23033, R28082	R23031, R23032, R28081
11	Hynix SSD	R23031, R23033, R28081, R28082	R23030, R23032

BoardID	GreenPak Revision	stuff	No-Stuff
00	Initial release, Мххххххх-001	R23008, R23009	R23003, R23004, R28061, R28062
01	1st new revision	R23003, R23009, R28061	R23008, R23004, R28062
10	2nd new revision	R23008, R23004, R28062	R23003, R23009, R28061
11	3rd new revision	R23003, R23004, R28061, R28062	R23008, R23009

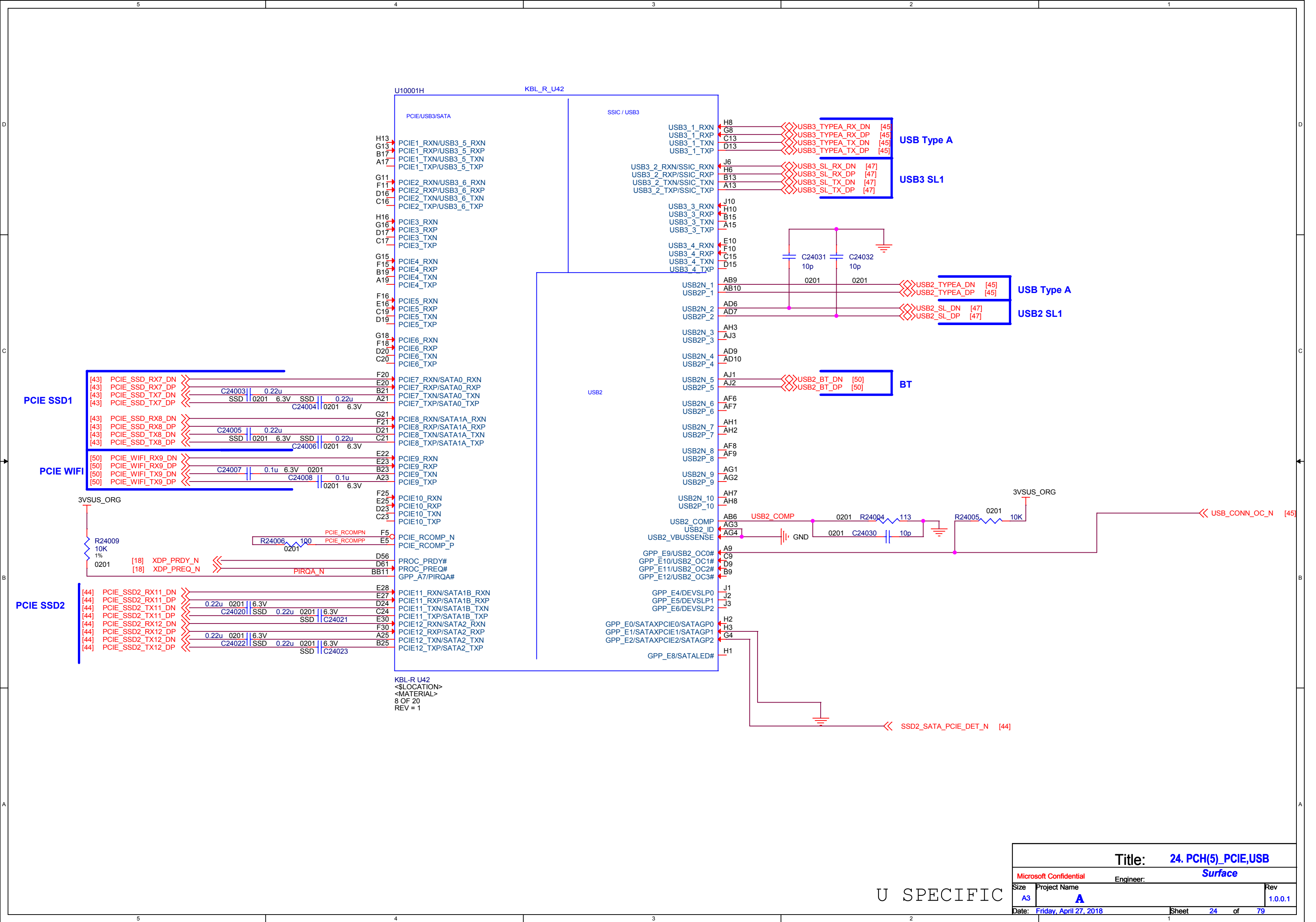
BoardID	s dram vendor and revision	Size	stuff	No-Stuff
0000	Hynix: H9CCNNN8JTBLAR-NUD, 8Gb LPDDR3	4GB	R23050, R23052, R23054, R2305	R23051, R23053, R23055, R23057
0001	Samsung: K4E8E324EB-EGCF000, 8Gb LPDDR3	4GB	R23051, R23052, R23054, R2305	R23050, R23053, R23055, R23057
0010	Hynix: H9CCNNN8GTALAR-NUD, 8Gb LPDDR3	4GB	R23050, R23053, R23054, R2305	R23051, R23052, R23055, R23057
0011	Reserved	4GB	R23051, R23053, R23054, R2305	R23050, R23052, R23055, R23057
0100	Hynix: H9CCNNNBLTBLAR-NUD, 16Gb LPDDR3	8GB	R23050, R23052, R23055, R2305	R23051, R23053, R23054, R23057
0101	Samsung: K4E6E304EB-EGCF000, 16Gb LPDDR3	8GB	R23051, R23052, R23055, R2305	R23050, R23053, R23054, R23057
0110	Hynix: H9CCNNNBJTALAR-NUD, 16Gb LPDDR3	8GB	R23050, R23053, R23055, R2305	R23051, R23052, R23054, R23057
0111	Reserved	8GB	R23051, R23053, R23055, R2305	R23050, R23052, R23054, R23057
1000	Hynix: H9CCNNNCLTMLBR-NUD, 32Gb LPDDR3	16GB	R23050, R23052, R23054, R2305	R23051, R23053, R23055, R23056
1001	Samsung: K4EBE304EB-EGCF000, 32Gb LPDDR3	16GB	R23051, R23052, R23054, R2305	R23050, R23053, R23055, R23056
1010	Hynix: H9CCNNNCLGALAR-NUD, 32Gb LPDDR3	16GB	R23050, R23053, R23054, R2305	R23051, R23052, R23055, R23056
1011	Reserved	16GB	R23051, R23053, R23054, R2305	R23050, R23052, R23055, R23056
1100	Reserved	Reserved	R23050, R23052, R23055, R2305	R23051, R23053, R23054, R23056
1101	Reserved	Reserved	R23051, R23052, R23055, R2305	R23050, R23053, R23054, R23056
1110	Reserved	Reserved	R23050, R23053, R23055, R2305	R23051, R23052, R23054, R23056
1111	Reserved	Reserved	R23051, R23053, R23055, R2305	R23050, R23052, R23054, R23056



POWER MONITORS	
R23007	POWER MONITORS, ELSE NO-STUFF
R23002	NO POWER MONITORS, ELSE NO-STUFF
DV HAS NO POWER MONITORS	

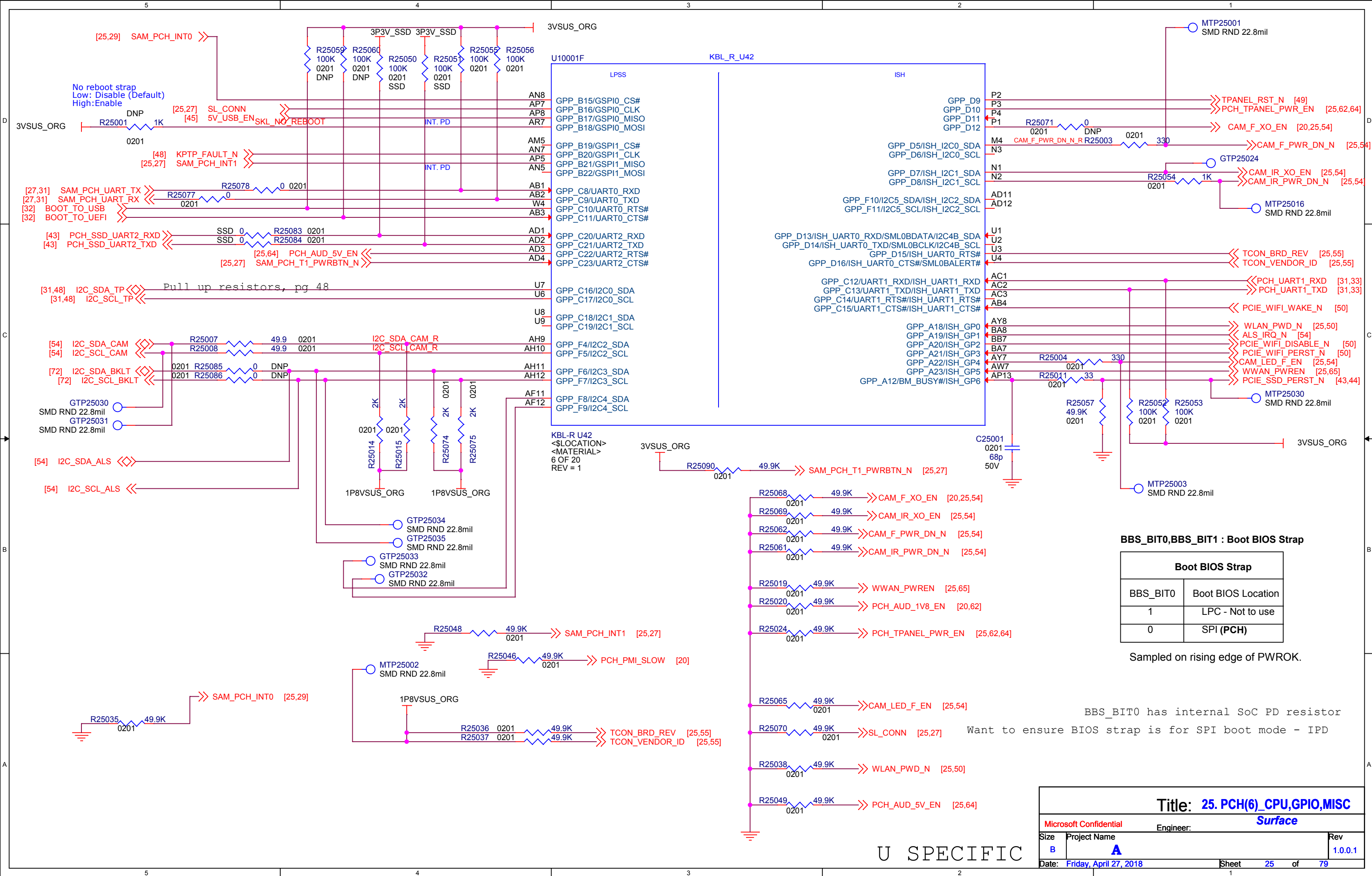
Title: 23. PCH(4)_CCI, HWID			
Microsoft Confidential		Engineer: Surface	
Size A3	Project Name A		Rev 1.0.0.1
Date: Friday, April 27, 2018	Sheet	23	of 79

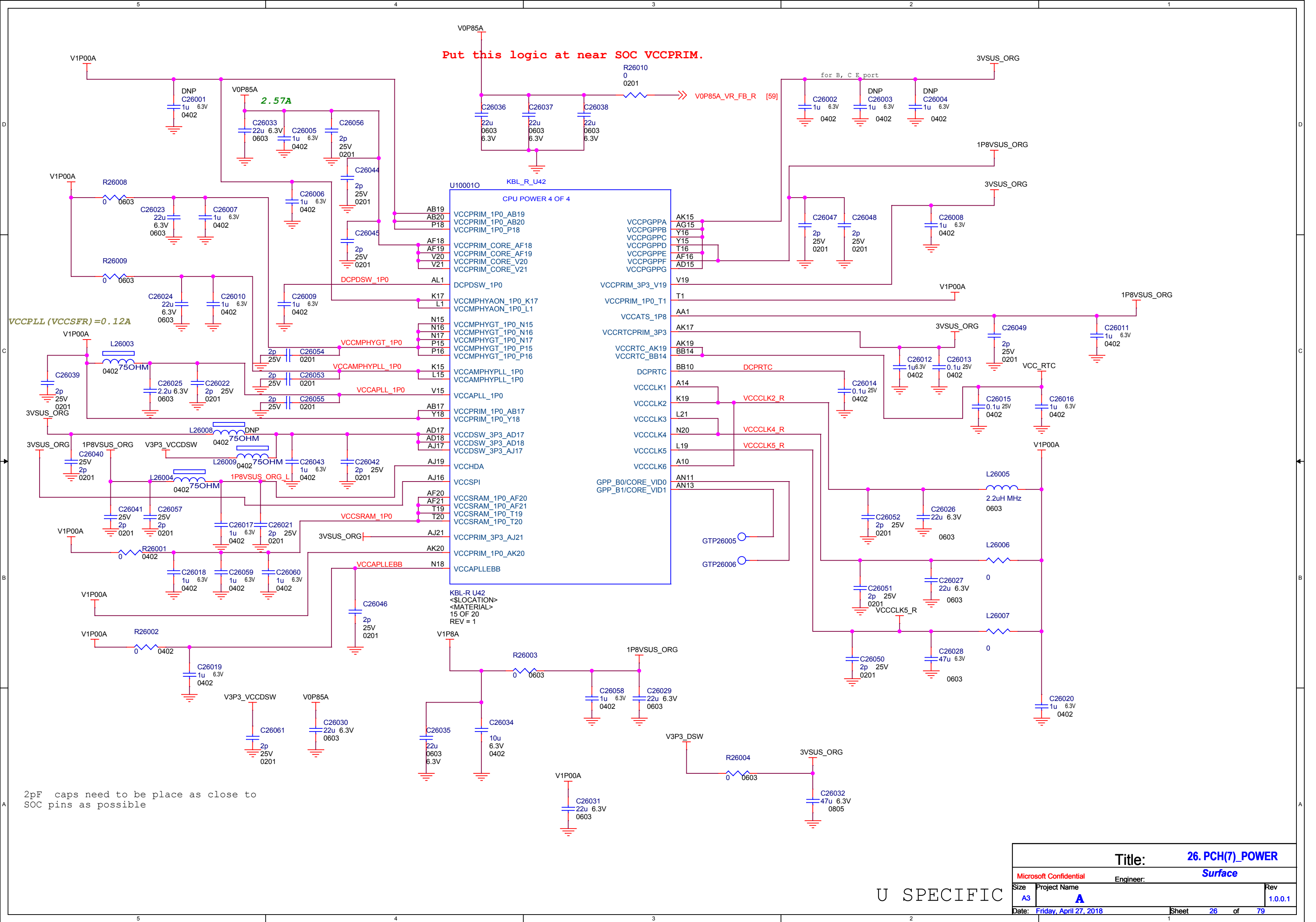




U SPECIFIC

Title: 24. PCH(5)_PCIE,USB		
Microsoft Confidential		
Engineer: Surface		
Size: A3	Project Name: A	Rev: 1.0.0.1
Date: Friday, April 27, 2018	Sheet: 24	of 79





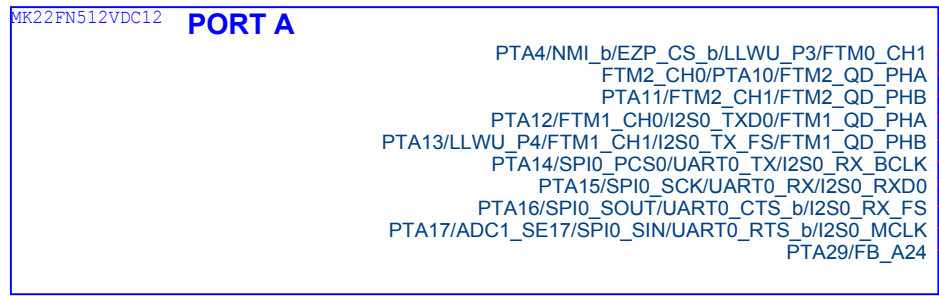
2pF caps need to be place as close to SOC pins as possible

Title: 26. PCH(7)_POWER	
Microsoft Confidential	
Size A3	Project Name A
Date: Friday, April 27, 2018	Rev 1.0.0.1
Sheet 26 of 79	

U SPECIFIC

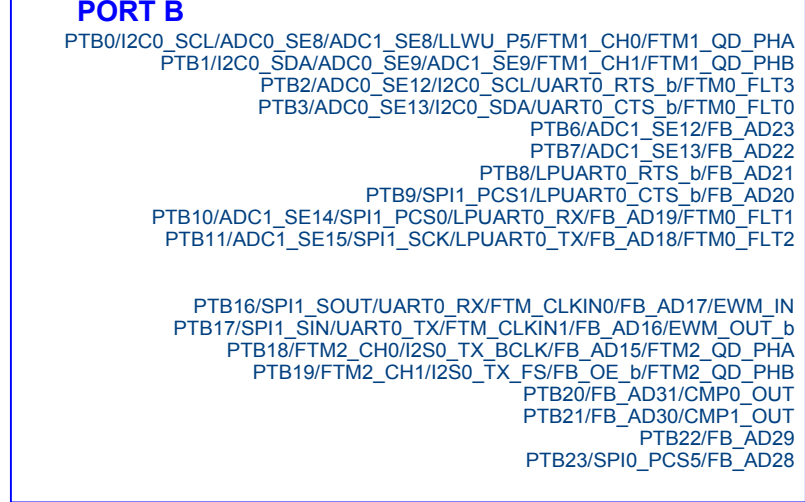


U27001A



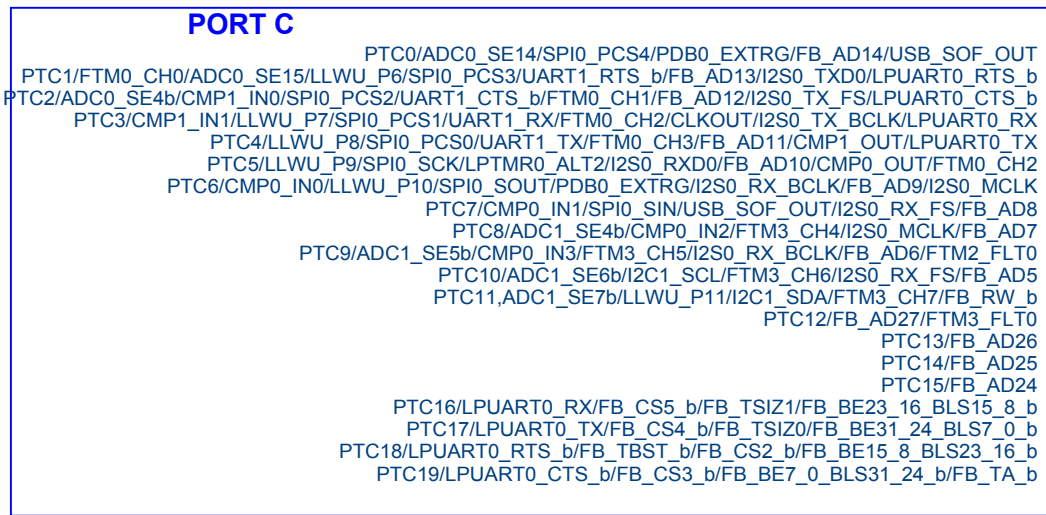
MK22FN512VDC12

U27001B



MK22FN512VDC12

U27001C



MK22FN512VDC12

MTP27001

Use last, NMI

>>>CPUFAN\_PWM [39]  
>>>SAM\_PANEL\_LOGO\_EN [30]  
>>>SAM\_SL\_5V\_PG [63]  
<<MASTER\_THERMTRIP\_N [56]  
>>>DEBUG\_LED0 [29]  
>>>SAM\_PCH\_UART\_TX [25,31]  
>>>SAM\_PCH\_UART\_RX [25,31]  
>>>SKL\_SLP\_S4\_N [22,34,45,59,61]  
>>>SAM\_PCH\_HALL\_INT [10]  
>>>SAM\_KBTP\_PWR [48]

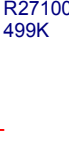
MTP27003  
MTTP27013

MTP27002  
MTTP27012

DEBUG\_LED1 >>>CPUFAN\_TACH [39]

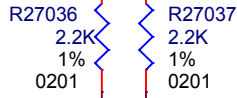
<<SKL\_SLP\_S0\_N [22,31,34,38,59,61]  
<<PCH\_DPWR0K [22,34,56,59]  
>>>SAM\_SL\_5V\_EN [63,69]  
>>>3P3V\_SSD\_EN\_R [29]

<<TRACKPAD\_INT\_N [10,48]  
>>>SAM\_GP\_DEEPSLP [56]  
>>>SL\_CONN [25]



>>>SAM\_TEST\_B10 [34]  
>>>SAM\_SSD\_FLUSH [43]  
<<SKL\_SLP\_SUS\_N [22,34,58,59]  
>>>BATGONE [63,70]  
>>>SAM\_DISPLAY\_BKLT\_EN [30]  
>>>SAM\_PCH\_T1\_PWRBTN\_N [25]  
>>>SAM\_UEFI\_TOP\_SWAP [20]  
>>>SAM\_PCH\_RSV1 [10]

3P3VA\_SW



R27046  
DEBUG\_SL  
2K 0402

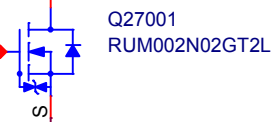
R27047  
DEBUG\_SL  
2K 0402

>>>PMIC\_EN\_R [29]  
>>>KIP\_IO [29,31,48]  
>>>PLT\_RST\_BUF\_N [22,34,38,43,44,56]  
>>>SL\_PG [56,69]  
>>>DEBUG\_MUX\_S3 [31]  
>>>GP\_SAM\_COLD\_BOOT [56]  
>>>RTCRST\_CTRL\_R [29]  
>>>SAM\_PCH\_RSMRST\_N\_R [29]  
>>>VCCRTC\_RST [56]  
>>>DEBUG\_MUX\_S2 [31]  
>>>I2C\_ROP\_SCL [31,63,70]  
>>>I2C\_ROP\_SDA [31,63,70]

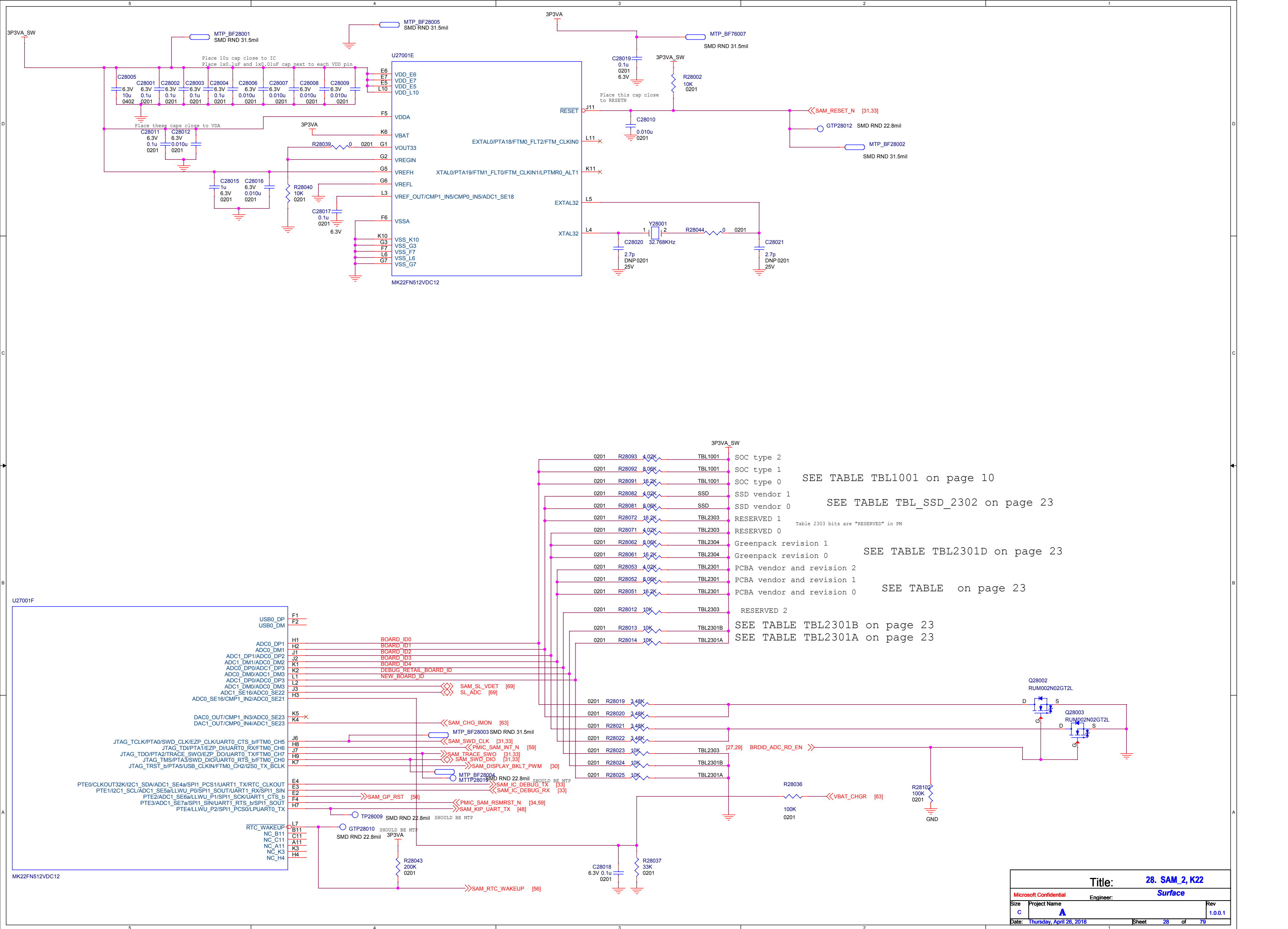
>>>SB\_PWRBTN\_SR [29]  
>>>SAM\_PCH\_INT1 [25]  
>>>SL\_UART\_SEL\_N [69]  
>>>BRDID\_ADC\_RD\_EN [28,29]  
>>>SAM\_THERM1 [39]  
>>>SL\_ADC\_RD\_EN [69]  
>>>SL\_3P3V\_DIS [46]  
<<SSD\_FLUSH\_DONE [43,56]

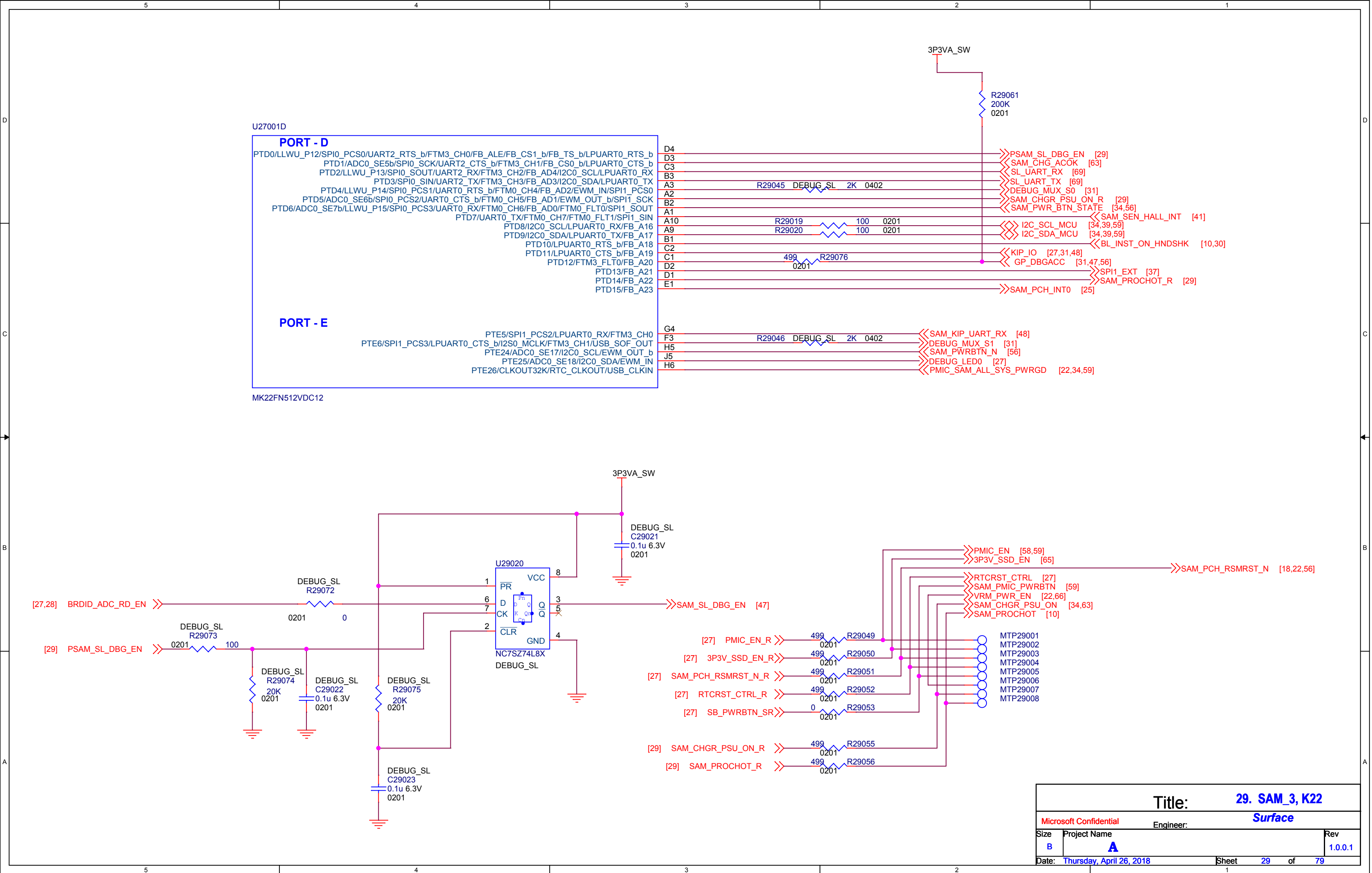
PU Resistors are on PCH side

>>>SKL\_RTCRST\_N [20]



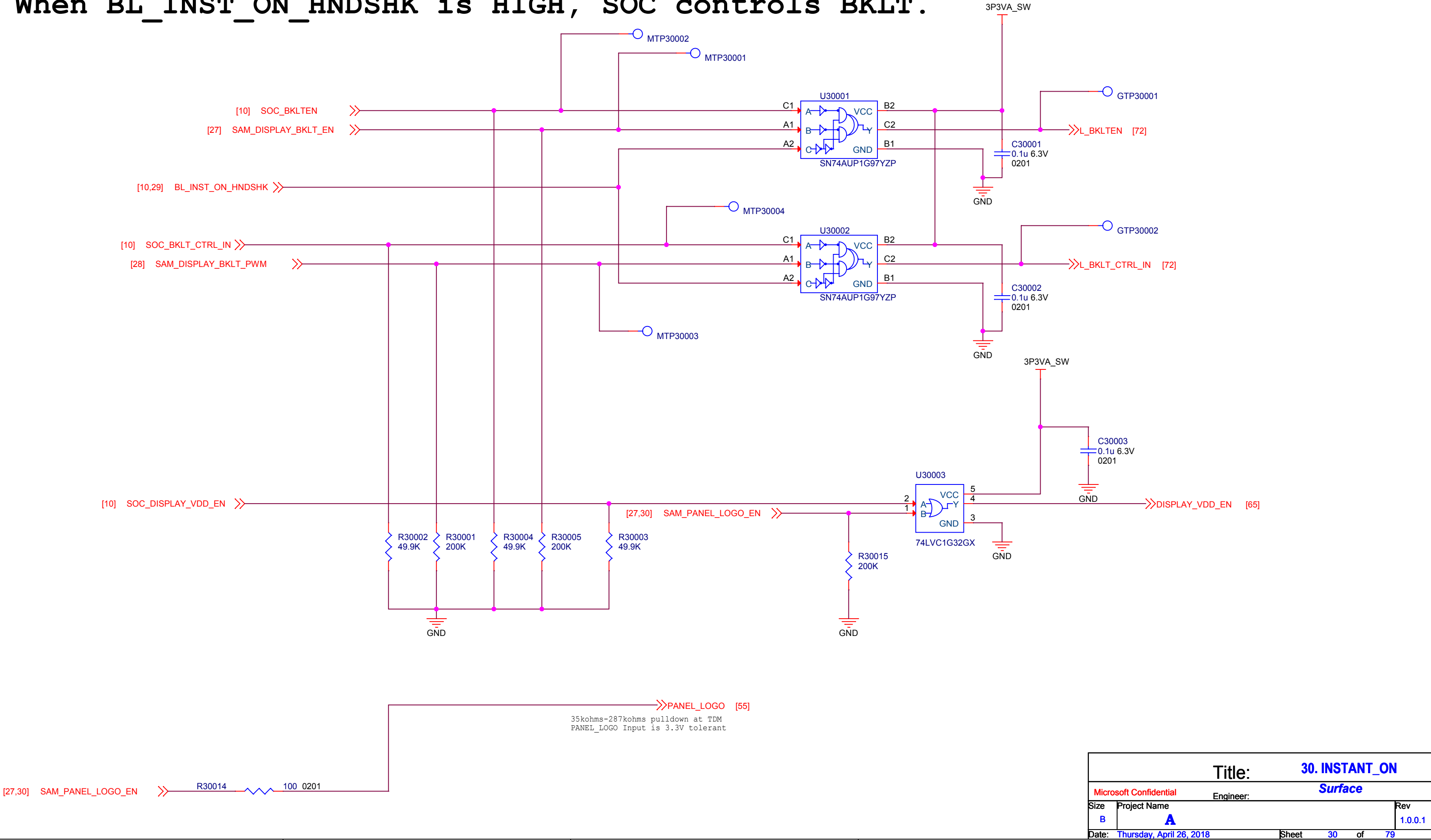
Title: 27. SAM_1, K22		
Microsoft Confidential Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 27 of 79	



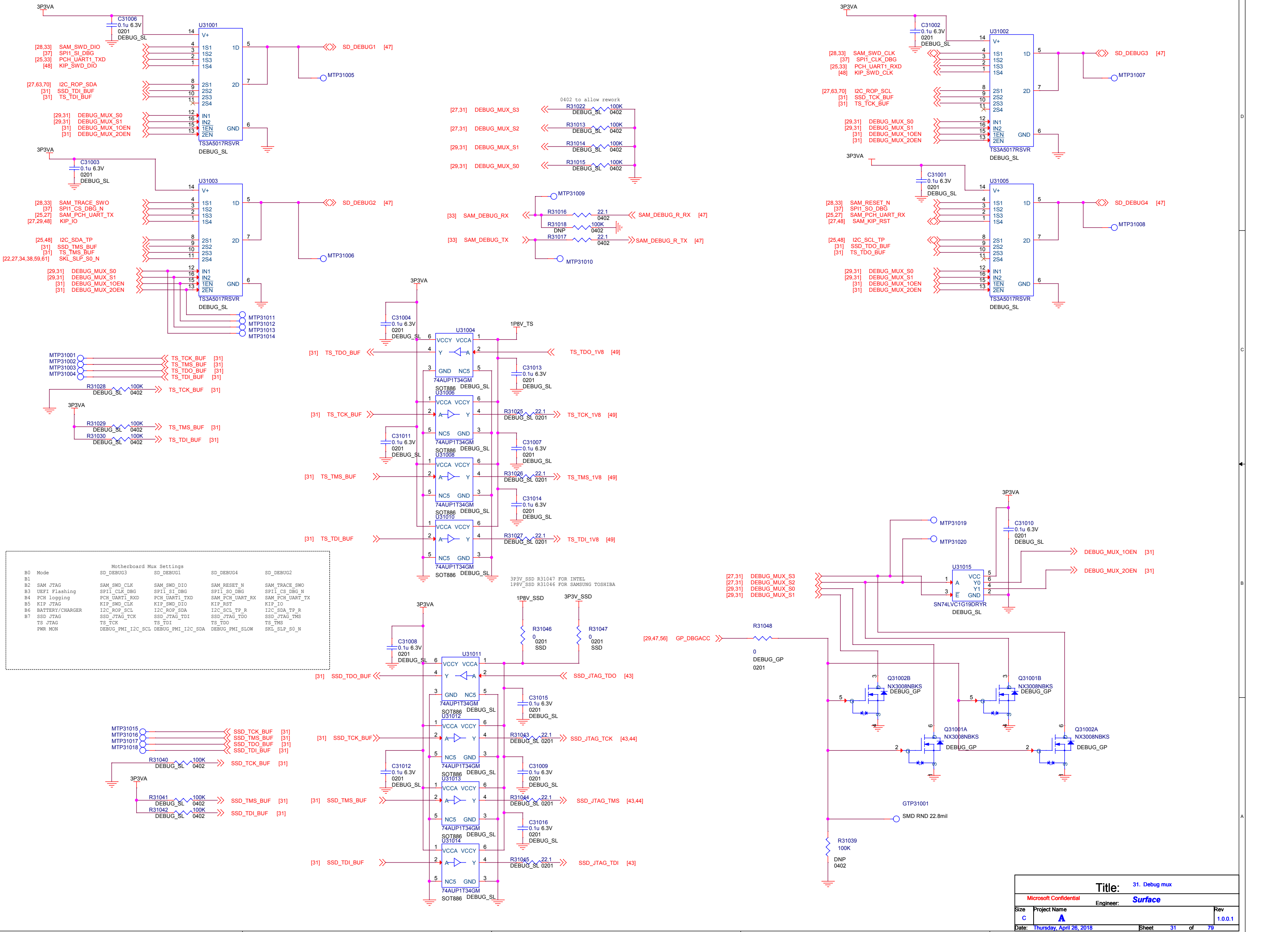




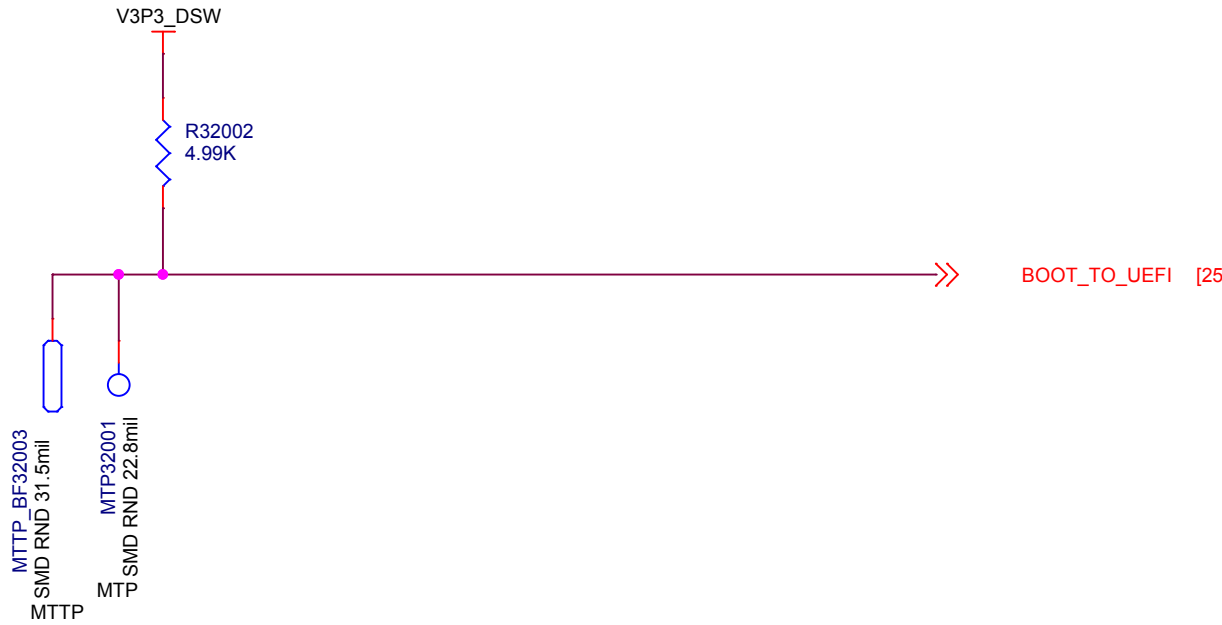
When BL\_INST\_ON\_HNDSHK is LOW, SAM controls BKLT.  
When BL\_INST\_ON\_HNDSHK is HIGH, SOC controls BKLT.



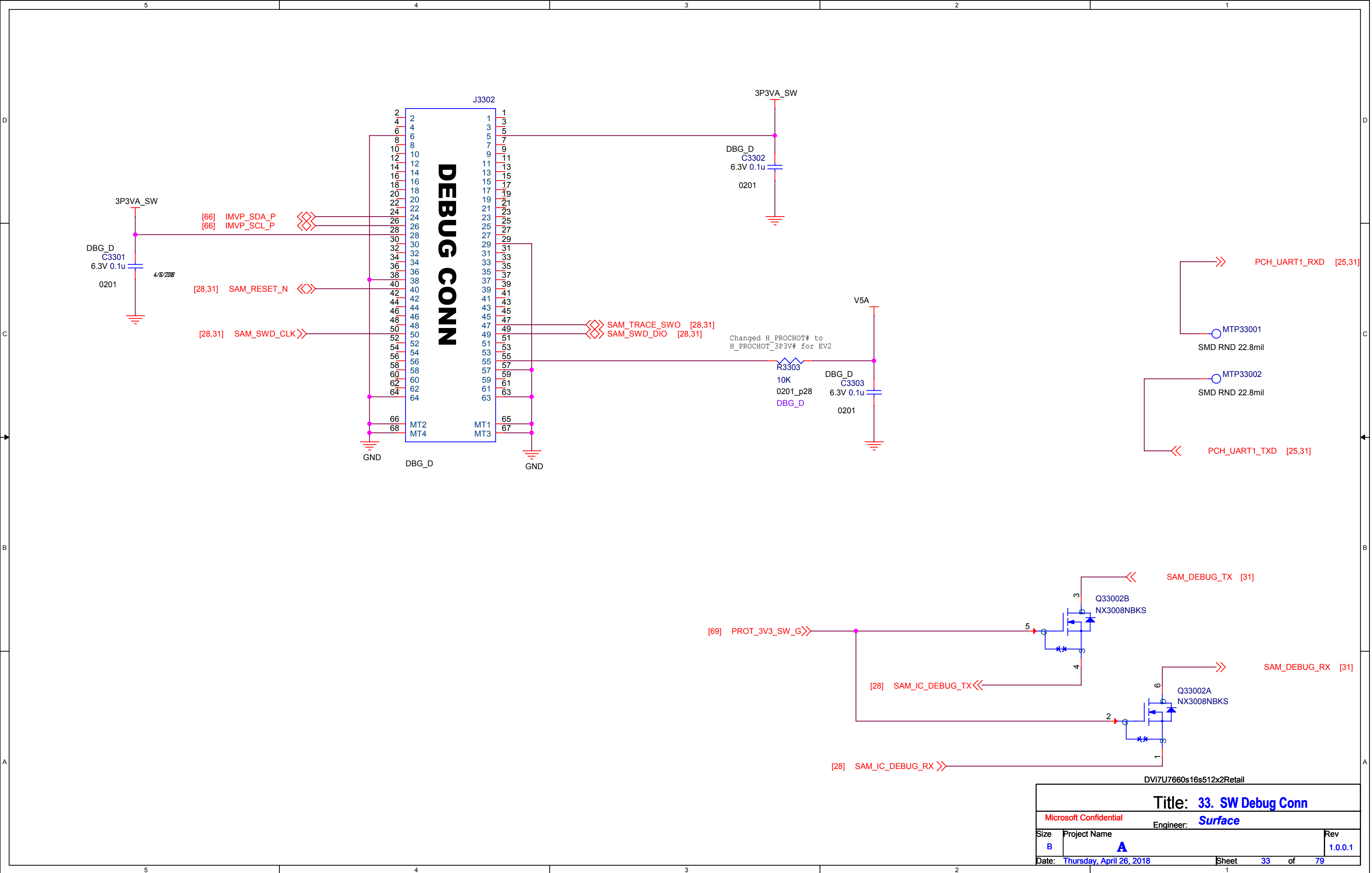
Title: 30. INSTANT_ON		
Microsoft Confidential		Engineer: Surface
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 30 of 79	



BOOT\_TO\_USB



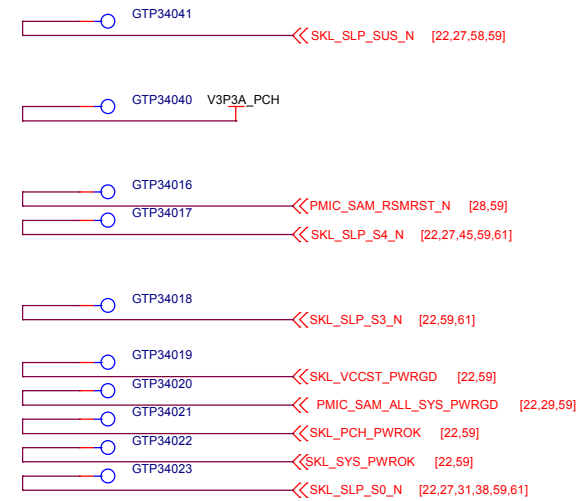
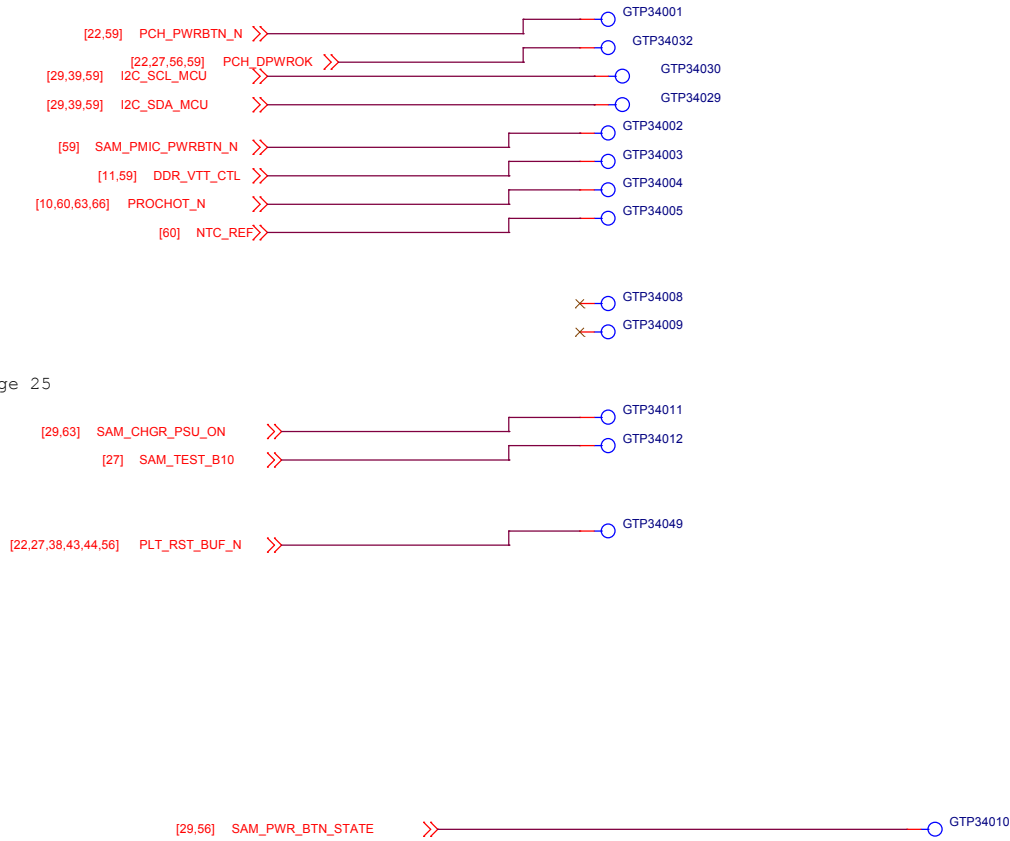
Title: 32. Debug Buttons		
Microsoft Confidential		Engineer: Surface
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 32 of 79	1



Title: 33. SW Debug Conn		
Microsoft Confidential		
Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 33 of 79	



I2C testpoints are shown on page 25



5					4					3					2					1				
D																								
C																								
B																								
A																								

</

Title: 35. EMPTY		
Microsoft Confidential Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 35 of 79	

MTP36003  
SMD RND 22.8mil

No Power Monitors in this SKU

MTP36001  
SMD RND 22.8mil

MTP36002  
SMD RND 22.8mil

Resistor Address for MAX3440

20.5K	=>	0x3C/0x3D
11.0K	=>	0x38/0x39
5.90K	=>	0x34/0x35
3.16K	=>	0x30/0x31
1.74K	=>	0x2C/0x2D
931K	=>	2x28/2x29
499	=>	2x24/2x25
GND	=>	2x20/2x21

Title: 36. Power Monitor			
Microsoft Confidential		Engineer: Surface	
Size	Project Name	Rev	
Cuspm	A	1.0.0.1	
Date: Thursday, April 26, 2018		Sheet	36 of 79

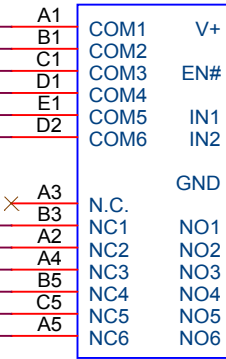
UEFI SPI ROM

(128Mb=16MB @104MHz)  
Needs to >= 66MHz

U37001  
W25Q128JVPIQ



DEBUG\_SL  
U37002  
TS3A27518EZQSR



SPI\_CLK = 20/33/50Mhz

[21] SPI\_CLK  
[21] SPI\_SI  
[21] SPI\_SO  
[21] SPI\_WP\_IO2  
[21] SPI\_HOLD\_IO3\_N  
[21] SPI\_CS0\_N

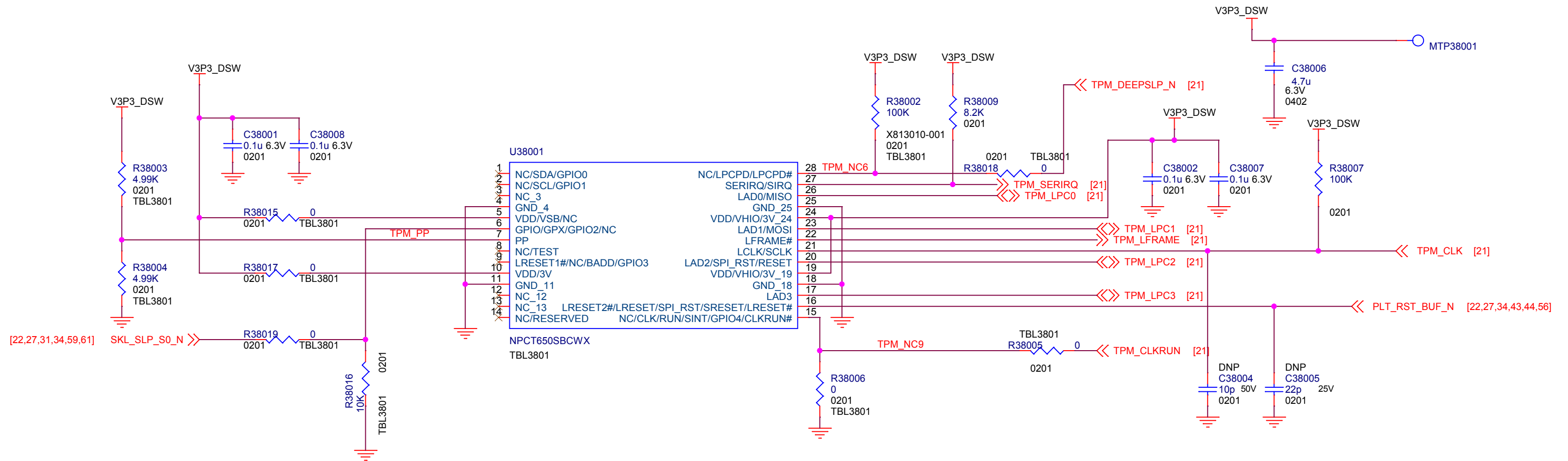
SPI\_CLK R37006 0 NDEB SL 0201  
SPI\_SI R37007 0 NDEB SL 0201  
SPI\_SO R37008 0 NDEB SL 0201  
SPI\_WP\_N R37009 0 NDEB SL 0201  
SPI\_HOLD\_N R37010 0 NDEB SL 0201  
SPI\_CS0\_N R37011 0 NDEB SL 0201

IN1/IN2 = L => COM to NC  
IN1/IN2 = H => NC to COM

Title: 37. SPI ROM UEFI		
Microsoft Confidential		
Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Tuesday, May 01, 2018	Sheet 37 of 79	

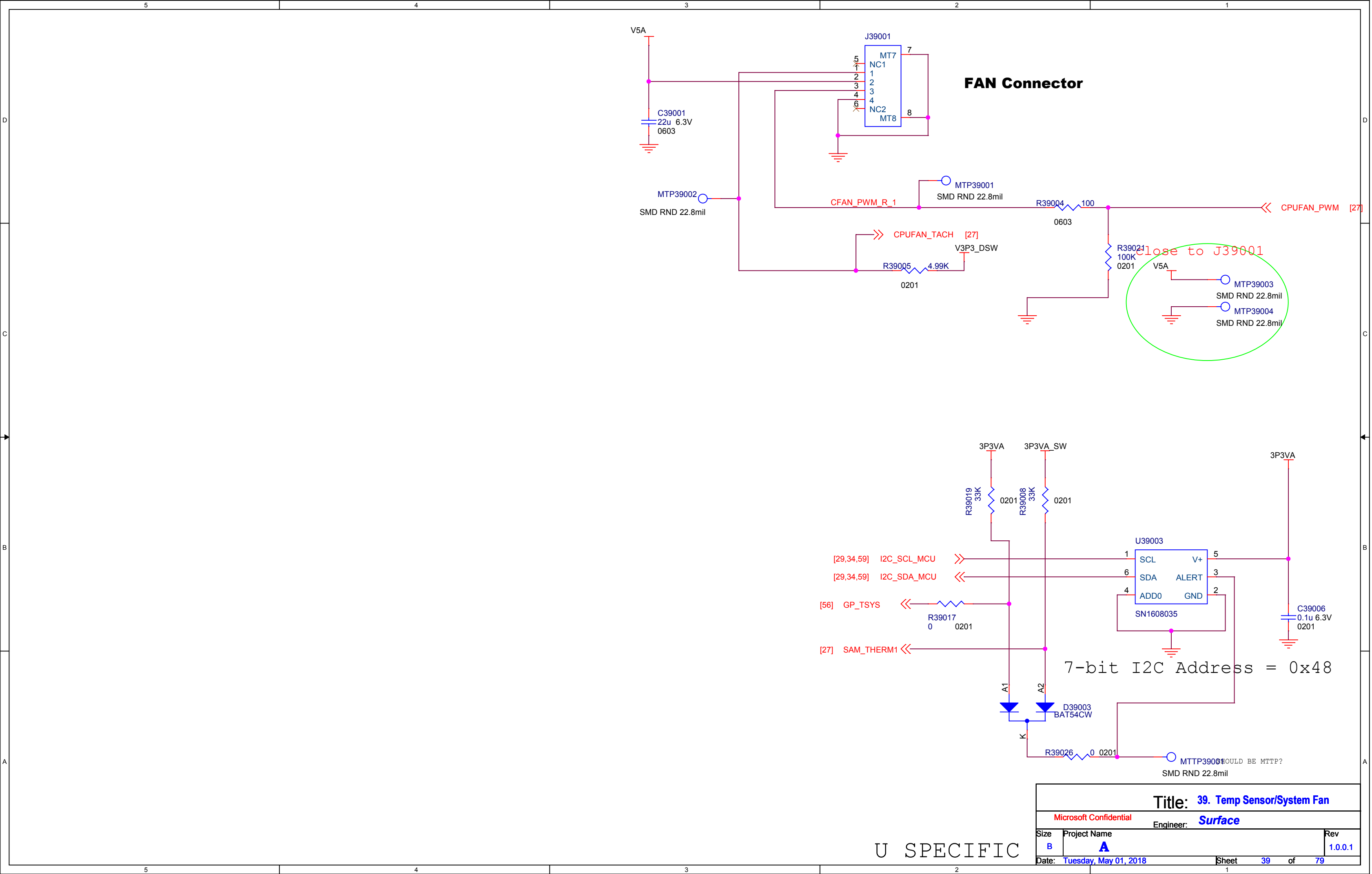


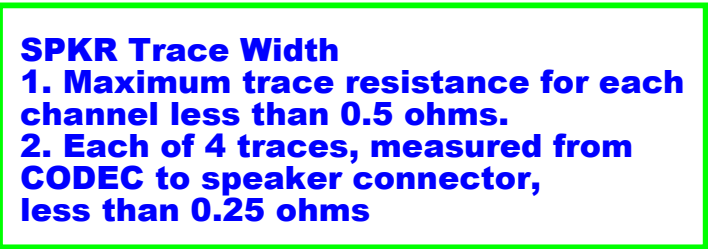
# Trusted Platform Module



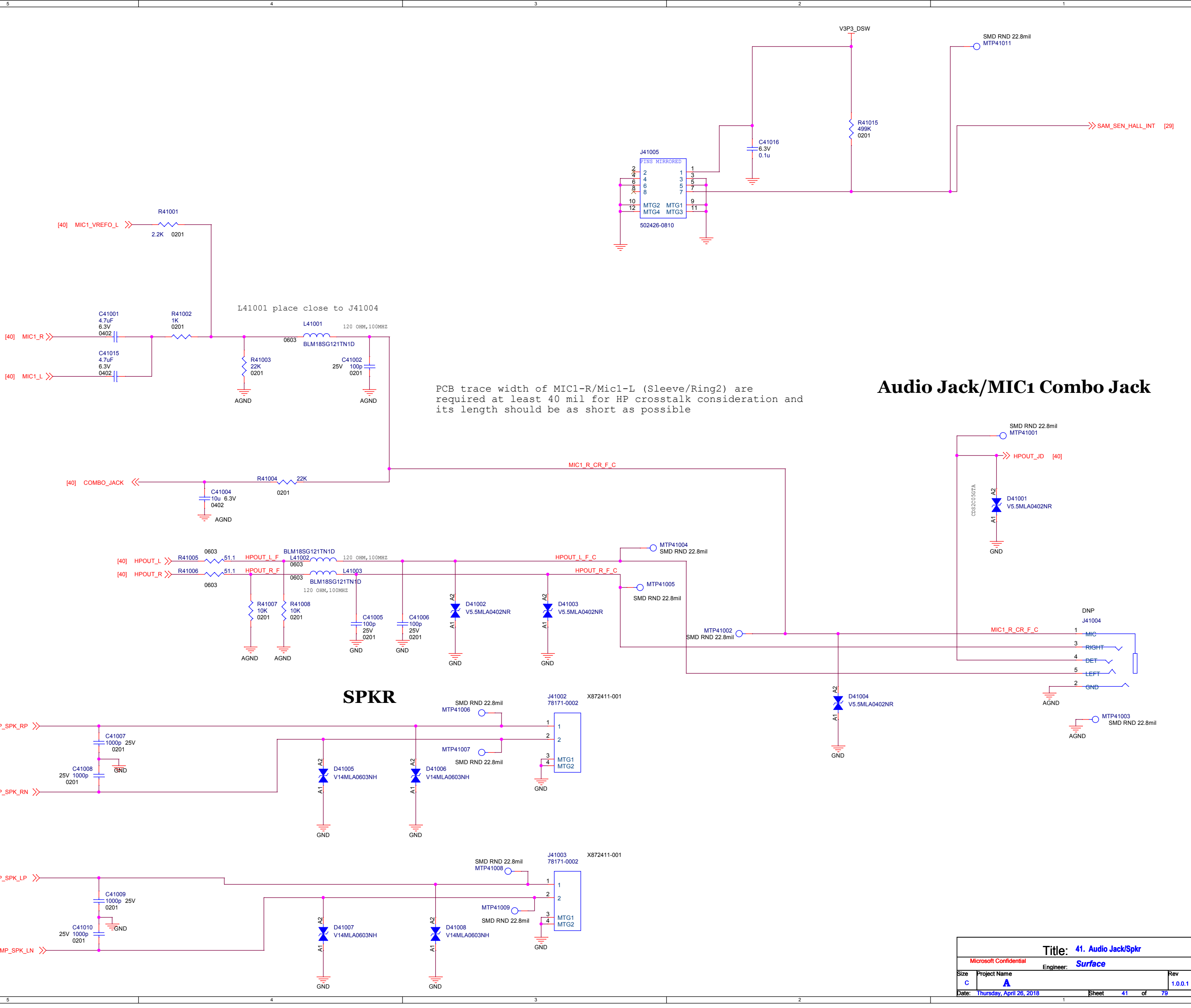
TBL3801		
Lancelot RefDes	Nuvuton	NationZ
U38001	M1006791-002	X930840-002
R38002	NO STUFF	X813010-001
R38003	NO STUFF	NO STUFF
R38004	X813007-001	NO STUFF
R38005	X811786-001	NO STUFF
R38006	NO STUFF	X811786-001
R38015	X811786-001	NO STUFF
R38016	NO STUFF	NO STUFF
R38017	X811786-001	X811786-001
R38018	X811786-001	NO STUFF
R38019	X811786-001	NO STUFF

Title: <b>38. TPM</b>		
Microsoft Confidential		Engineer: <b>Surface</b>
Size <b>B</b>	Project Name <b>A</b>	Rev <b>1.0.0.1</b>
Date: <b>Thursday, April 26, 2018</b>	Sheet <b>38</b> of <b>79</b>	





Title: 40. REALTEK ALC3269 CODEC		
Microsoft Confidential		
Engineer: Surface		Rev
Size A3	Project Name A	1.0.0.1
Date: Thursday, April 26, 2018	Sheet 40	of 79



Audio Jack/MIC1 Combo Jack

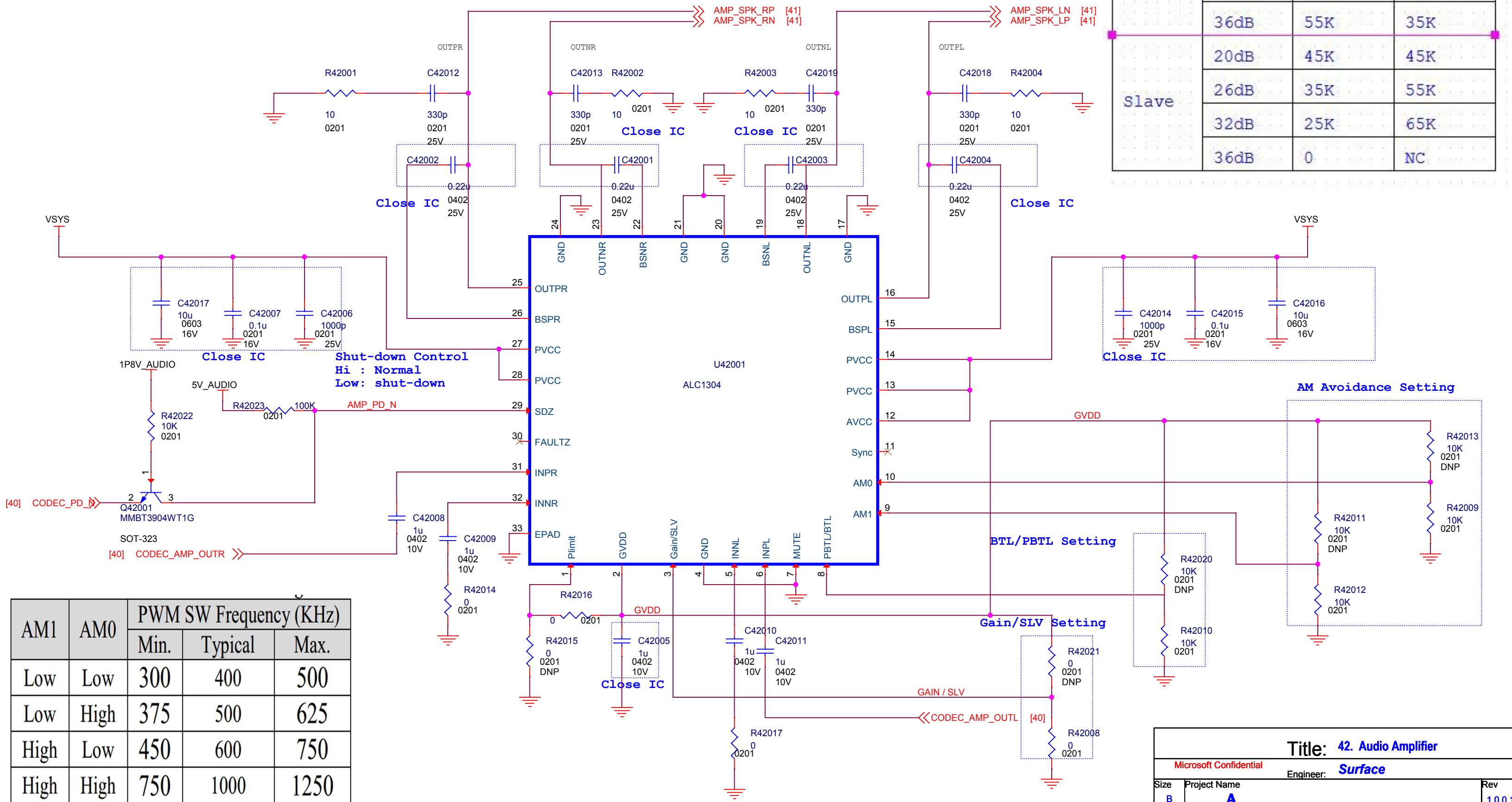
SPKR



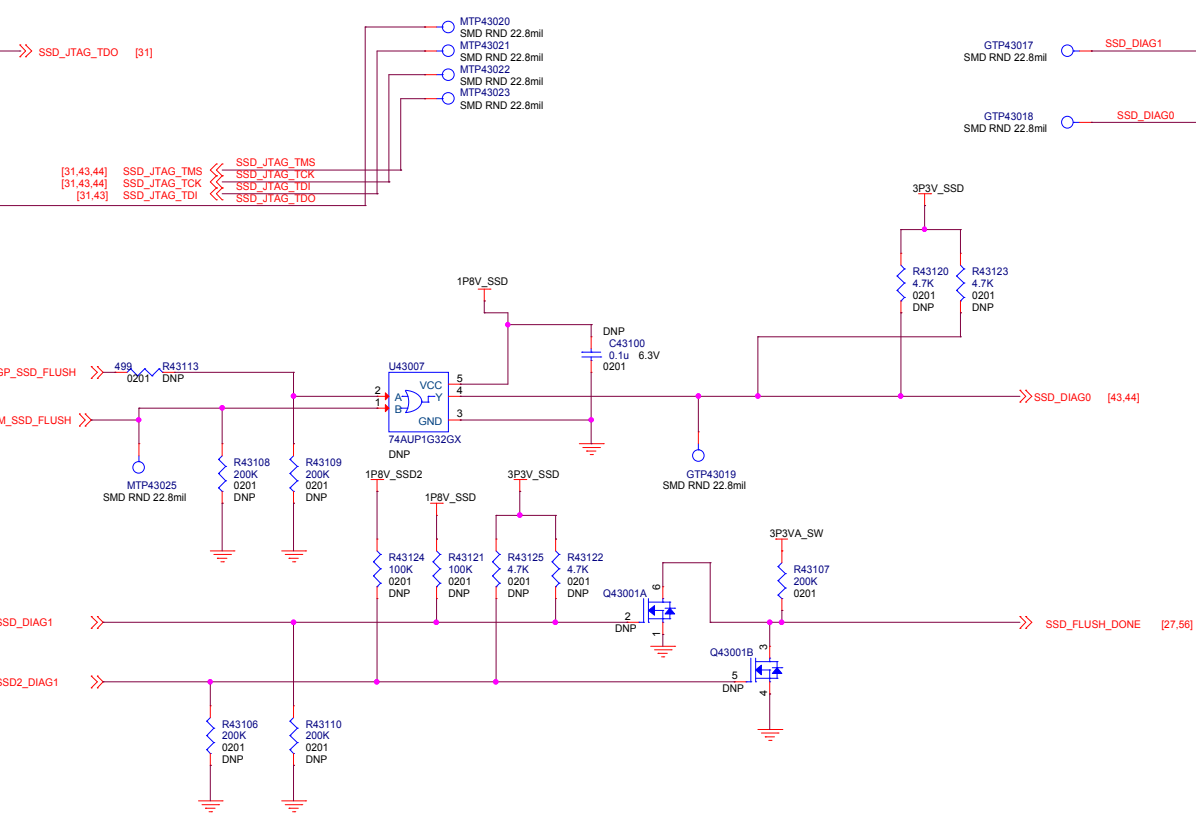
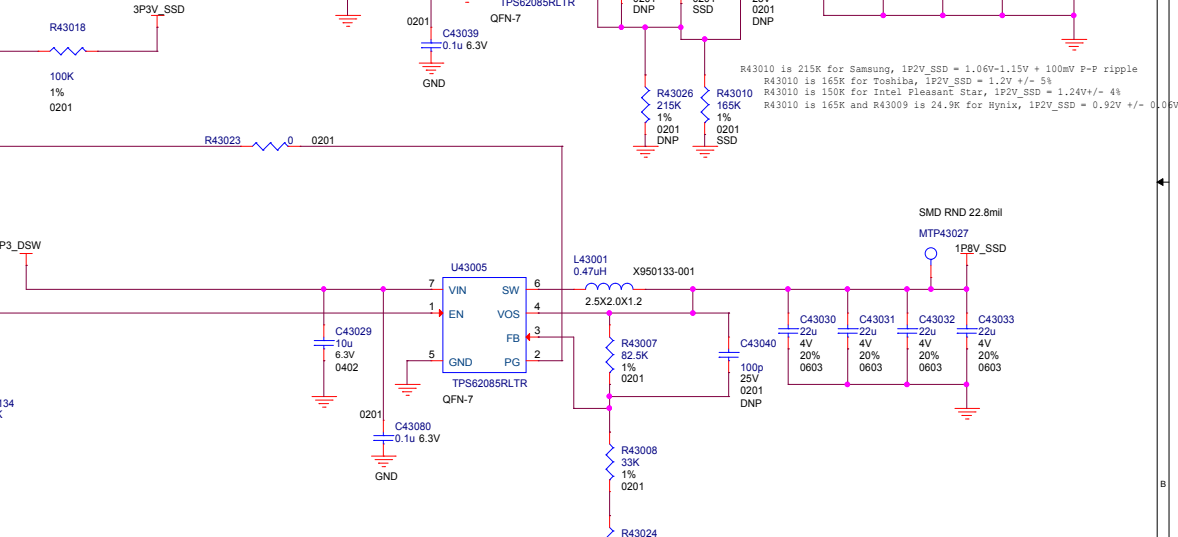
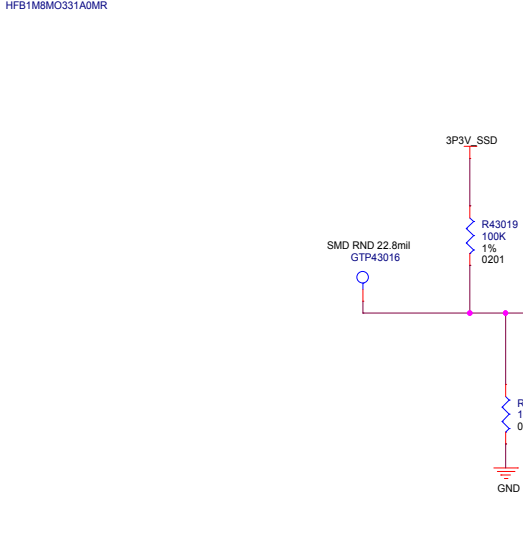
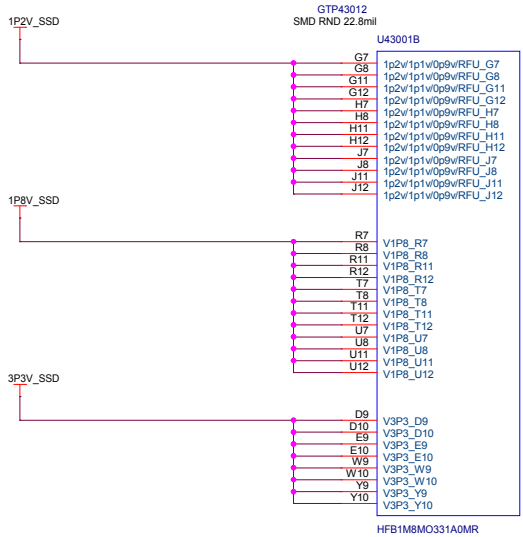
# Stereo Input (S.E.) Stereo Output-BTL

**SPKR Trace Width**  
**1. Maximum trace resistance for each channel less than 0.5 ohms.**  
**2. Each of 4 traces, measured from CODEC to speaker connector, less than 0.25 ohms**

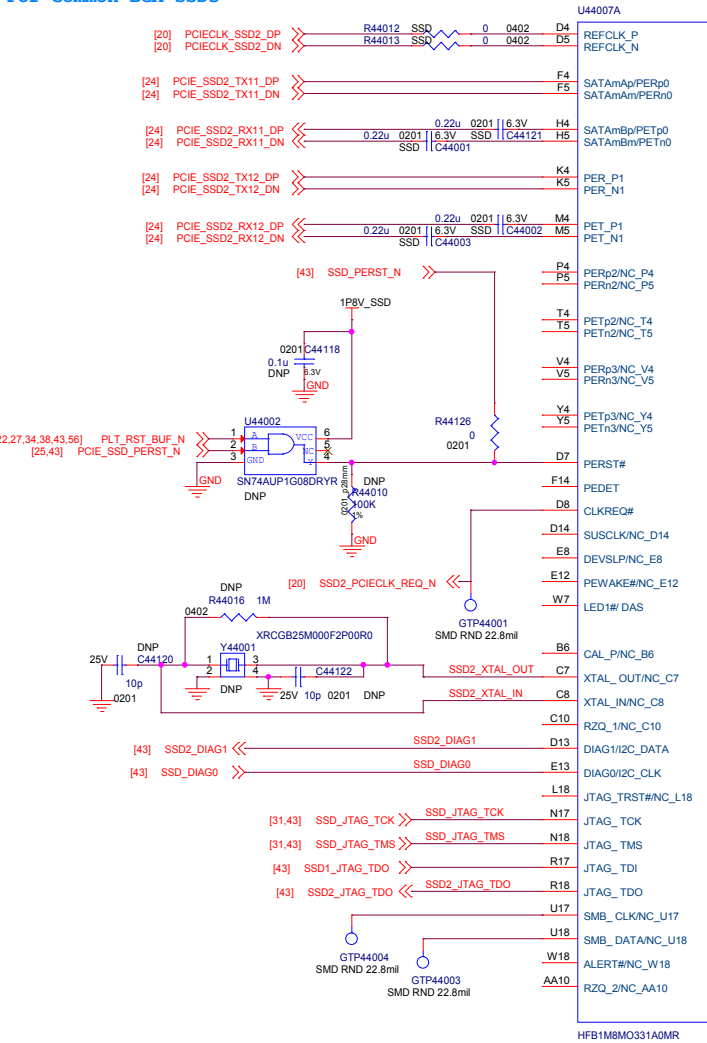
Mode	Gain	RX (ohm)	RY (ohm)
Master	20dB	NC	0
	26dB	75K	15K
	32dB	65K	25K
	36dB	55K	35K
Slave	20dB	45K	45K
	26dB	35K	55K
	32dB	25K	65K
	36dB	0	NC



AM1	AM0	PWM SW Frequency (KHz)		
		Min.	Typical	Max.
Low	Low	300	400	500
Low	High	375	500	625
High	Low	450	600	750
High	High	750	1000	1250

[illegible]

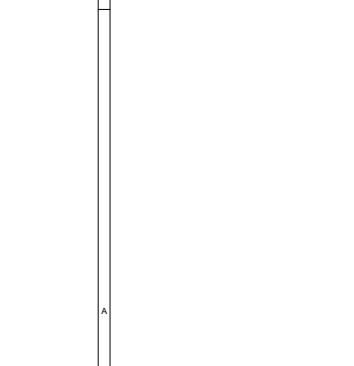
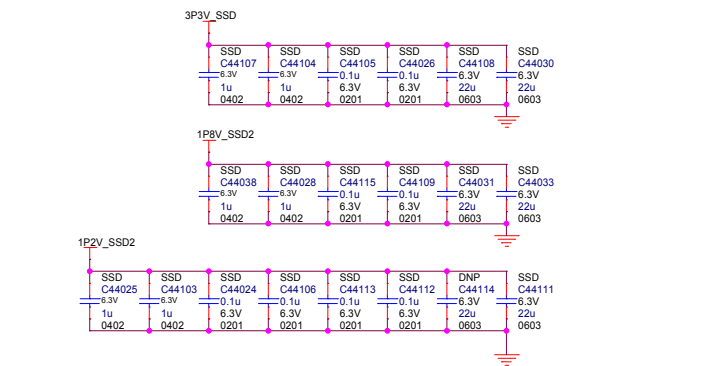
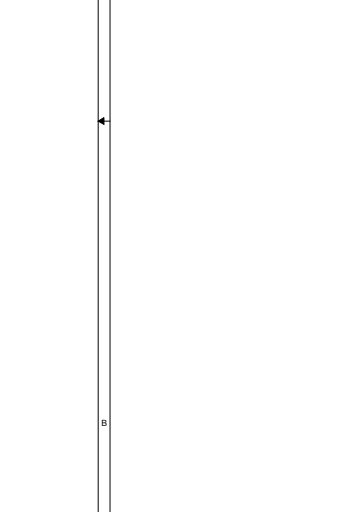
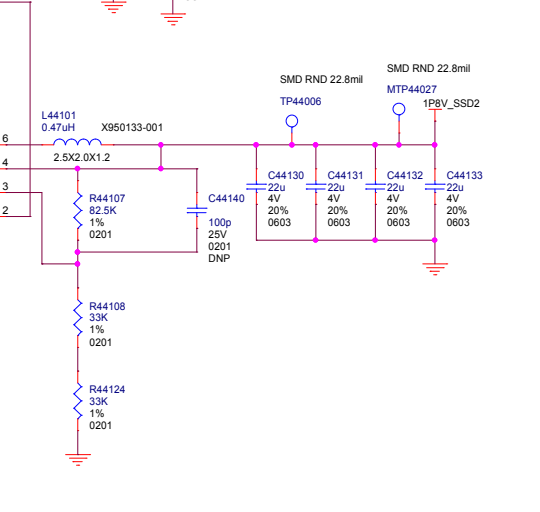
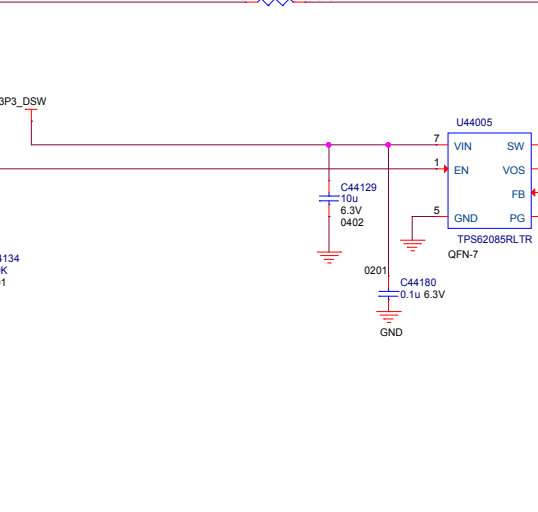
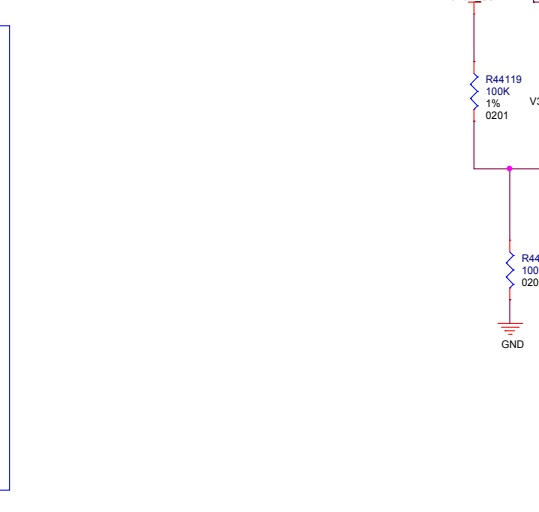
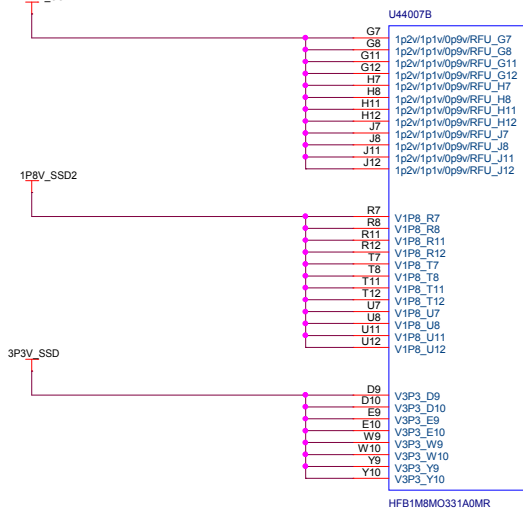
For common BGA SSDs

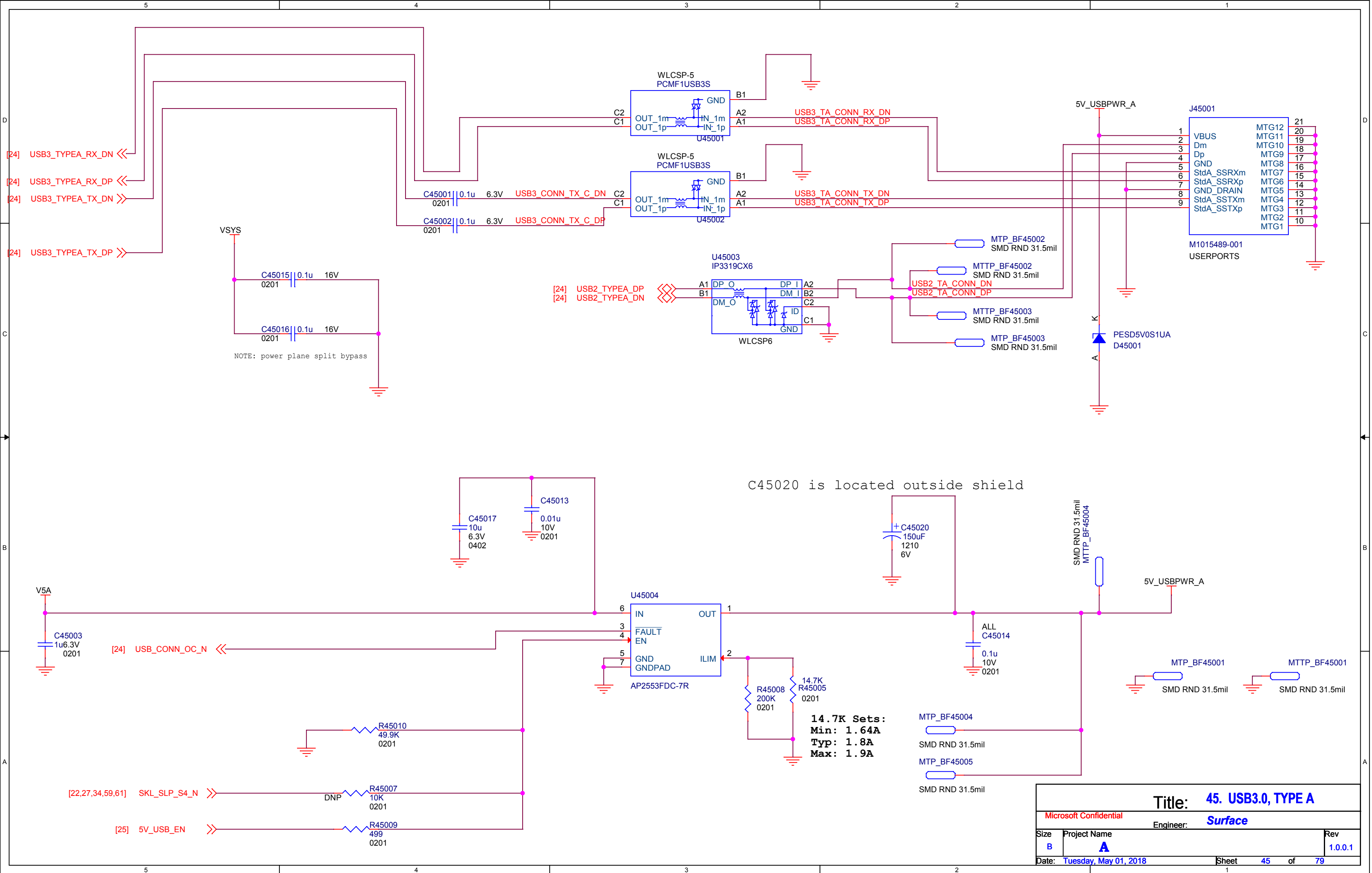


PCIe[12:1] TXN/P : Gen1 and Gen2 = 75 to 200 nF; where 100 nF is nominal value, Gen3 = 176 to 265 nF; where 220 nF is nominal value  
 PCIe[12:1] RXN/P : Gen1 and Gen2 = 75 to 200 nF; where 100 nF is nominal value, Gen3 = 176 to 265 nF; where 220 nF is nominal value

Difference between USB3 and PCIe: 1. No Choke, 2. Add cap on PER (p832 at DG v1.2)  
 RXN/RXP cap value must be different between Gen2 and Gen3  
 TX (from SOC) caps are at SOC side

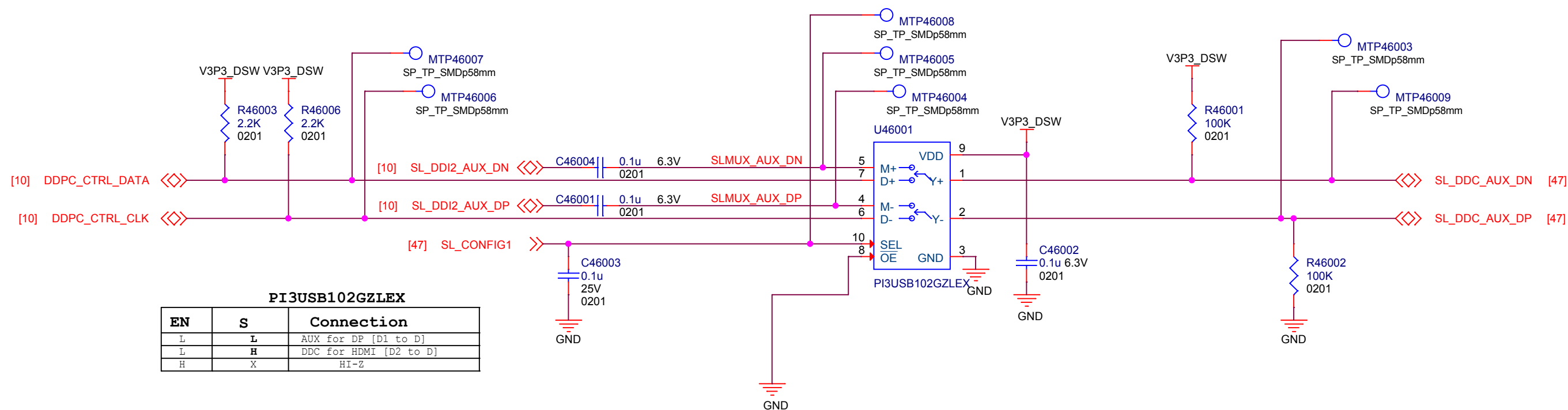
Always ON logic, as like Intel RVP5.



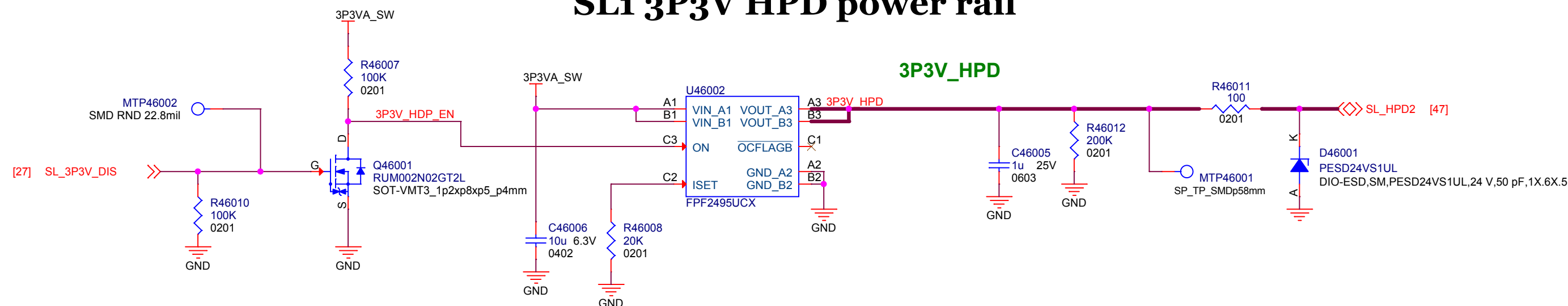




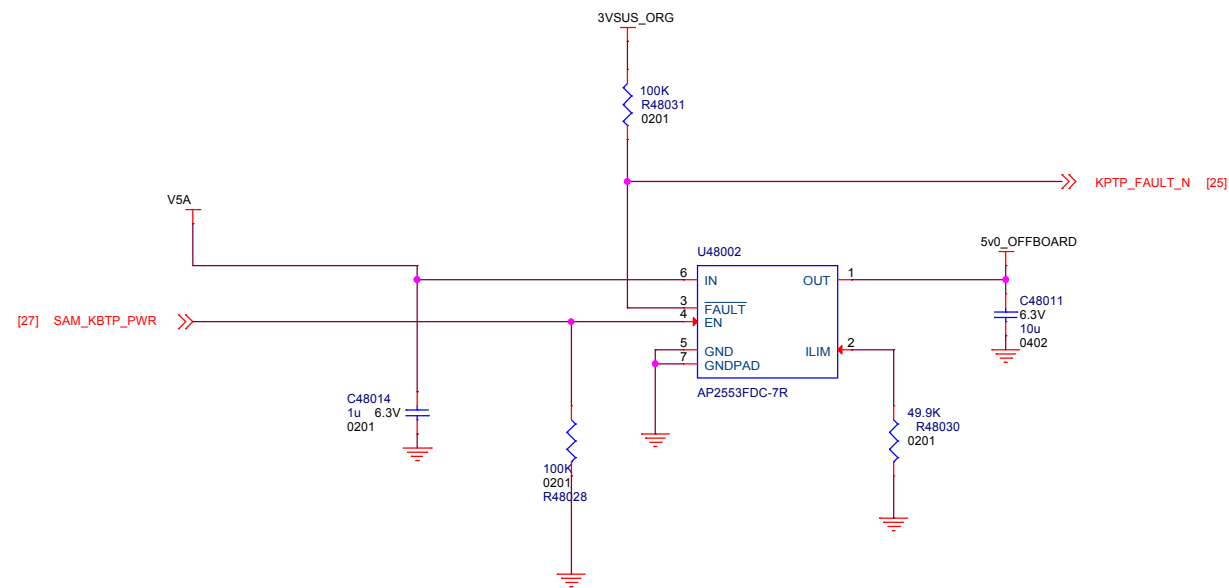
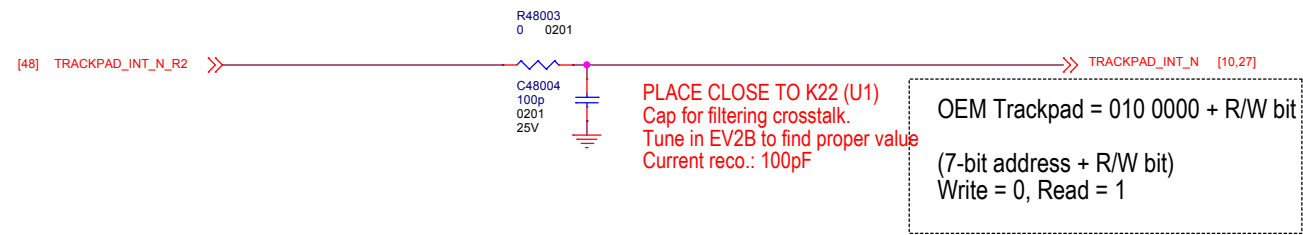
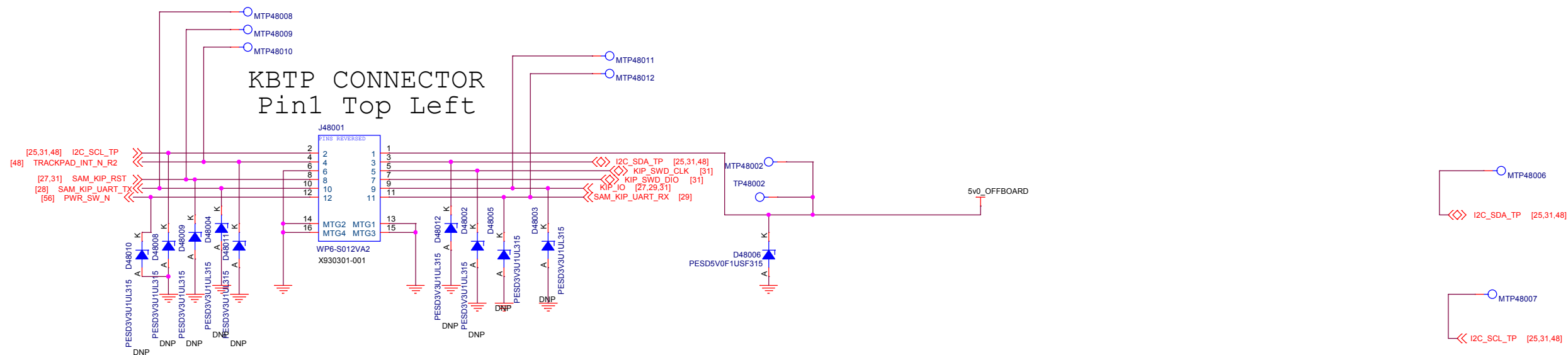
# SL1 DP mux to HDMI/DVI Dongle control

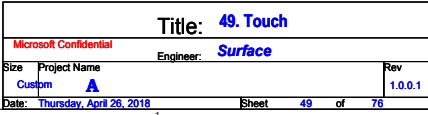


# SL1 3P3V HPD power rail

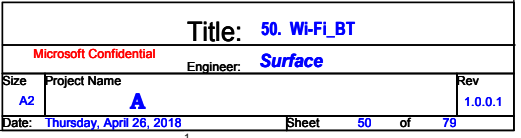








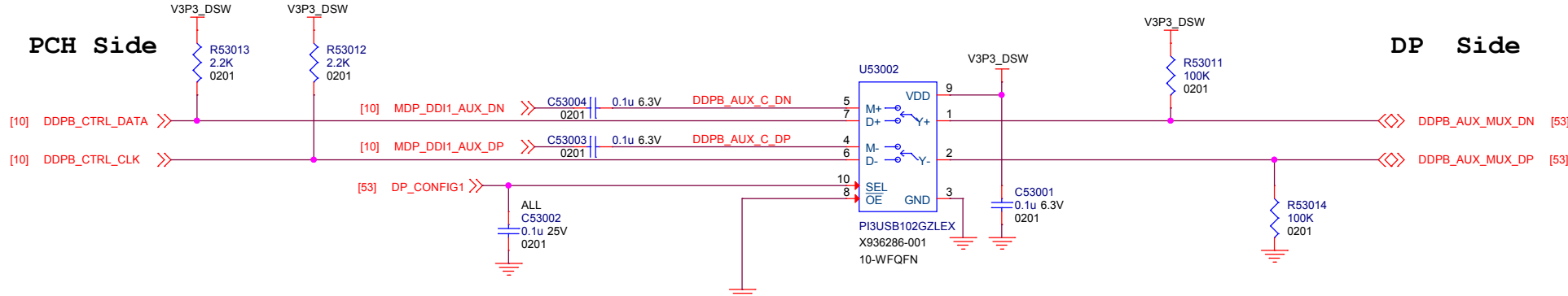




Title: 51. Empty					
Microsoft Confidential Engineer: Surface					
Size B	Project Name A				Rev 1.0.0.1
Date:	Thursday, April 26, 2018			Sheet	51 of 79

Title: 52. Empty		
Microsoft Confidential	Engineer: Surface	
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 52 of 79	

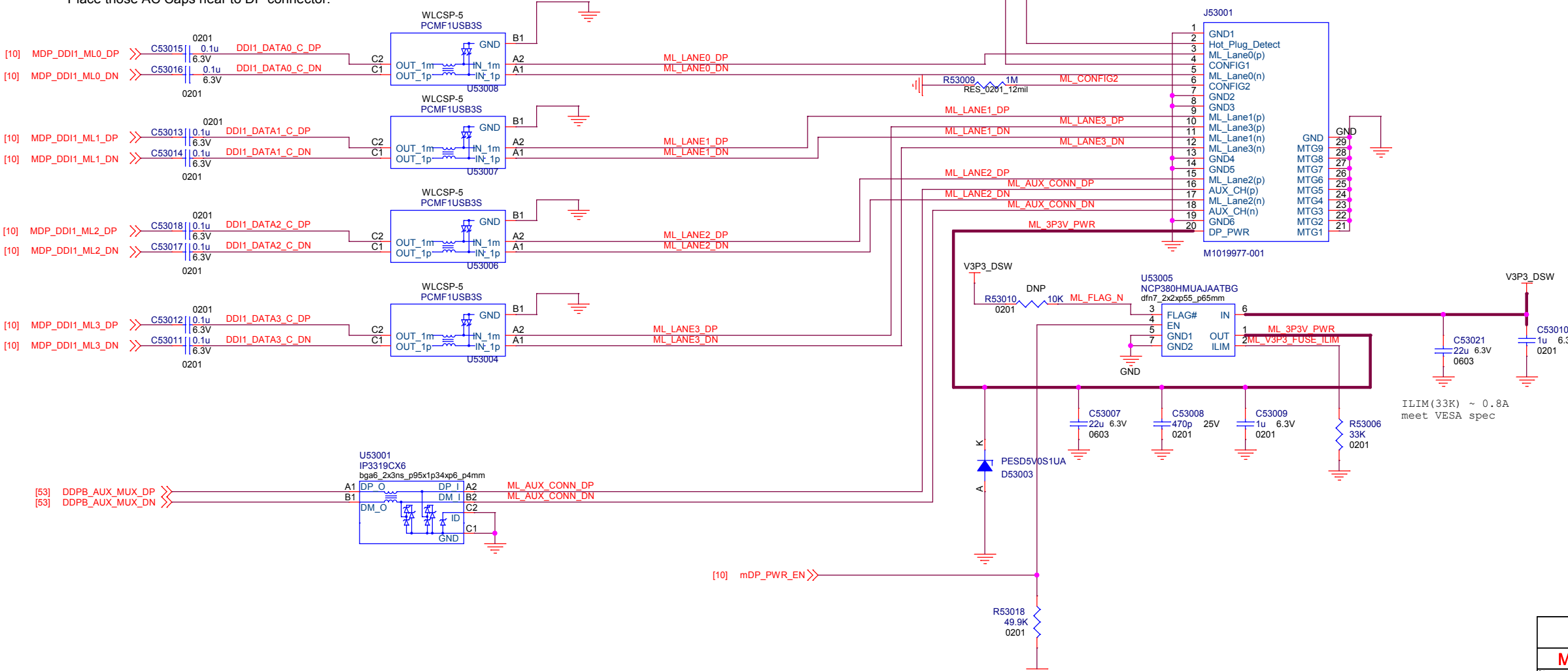
## mDP mux to HDMI/DVI Dongle control



**NOTE:**  
Place ESD Diodes close to DP connectors



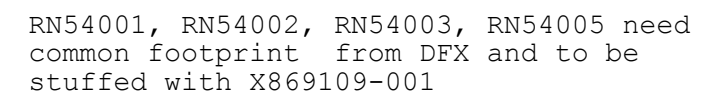
**NOTE:**  
Place those AC Caps near to DP connector



Title: mDP	
Engineer: Surface	
Size	Project Name
C	A
	Rev
	2.89.6

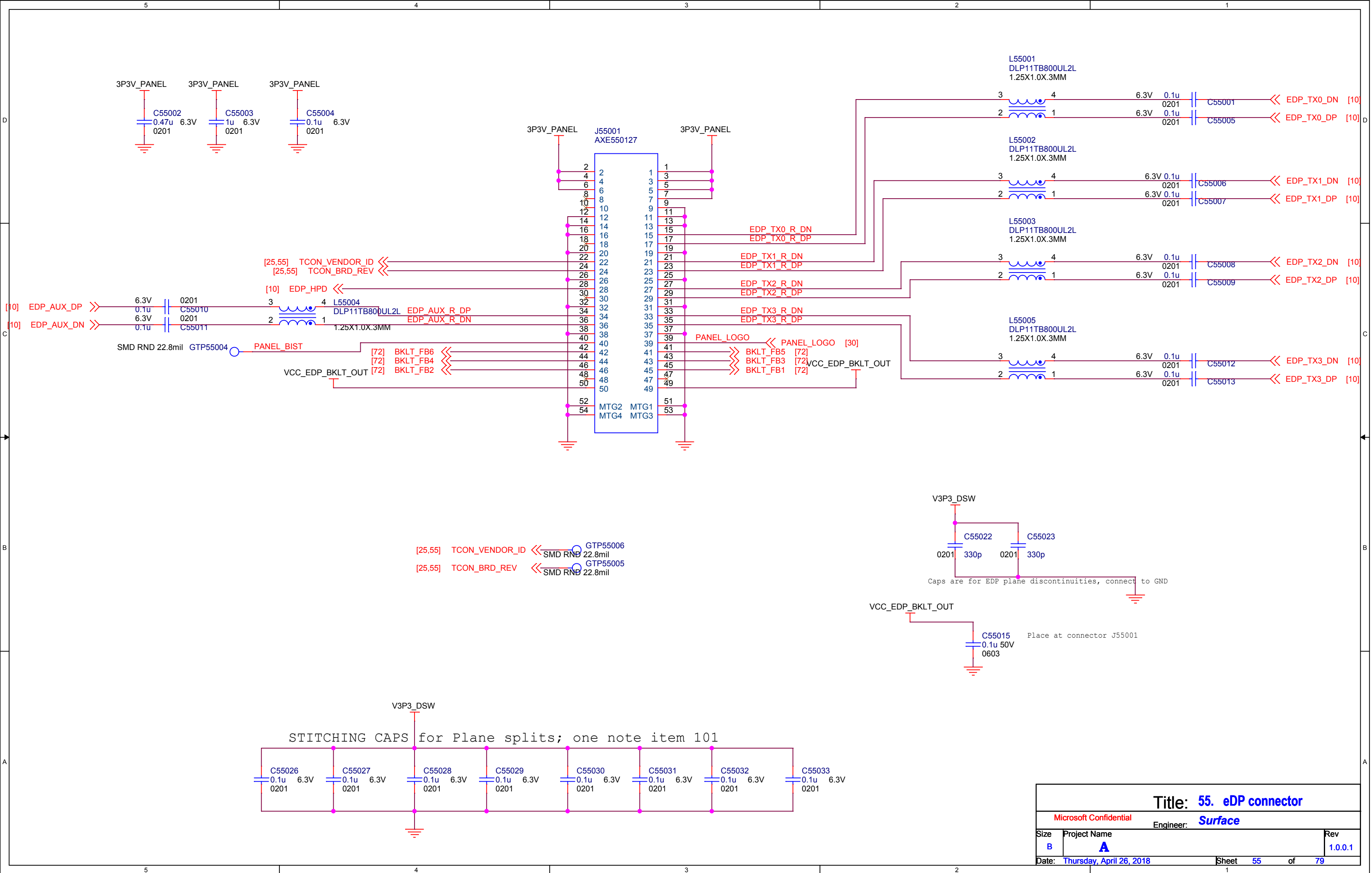


To IR LED on  
FPC through  
J54001



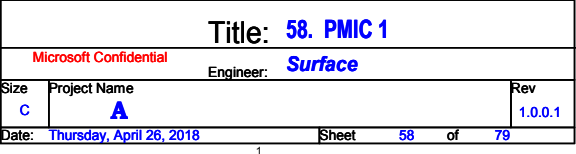
ALS 7-bit I2C Address = 0x44  
 RGB Cam 7-bit I2C Address = 0x36  
 RGB EEPROM 7-bit I2C Address = TBD  
 IR Cam 7-bit I2C Address = 0x60

<b>Title:</b> 54. Camera/Sensor Conn					
<b>Microsoft Confidential</b>			<b>Engineer:</b> Surface		
<b>Size</b> <b>B</b>	<b>Project Name</b> <b>A</b>				<b>Rev</b> 1.0.0.1
<b>Date:</b>	Thursday, April 26, 2018		<b>Sheet</b>	54	of 79

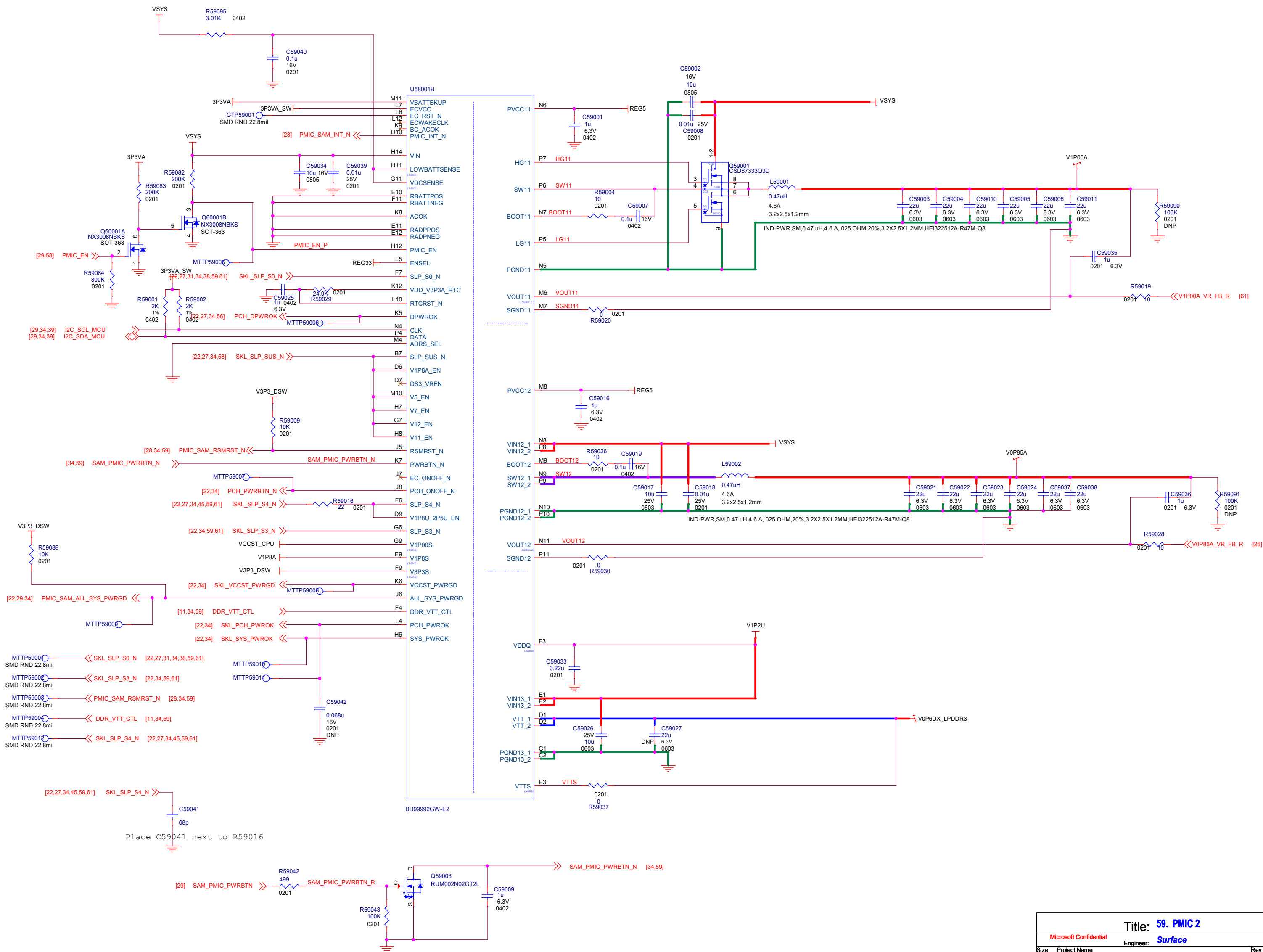


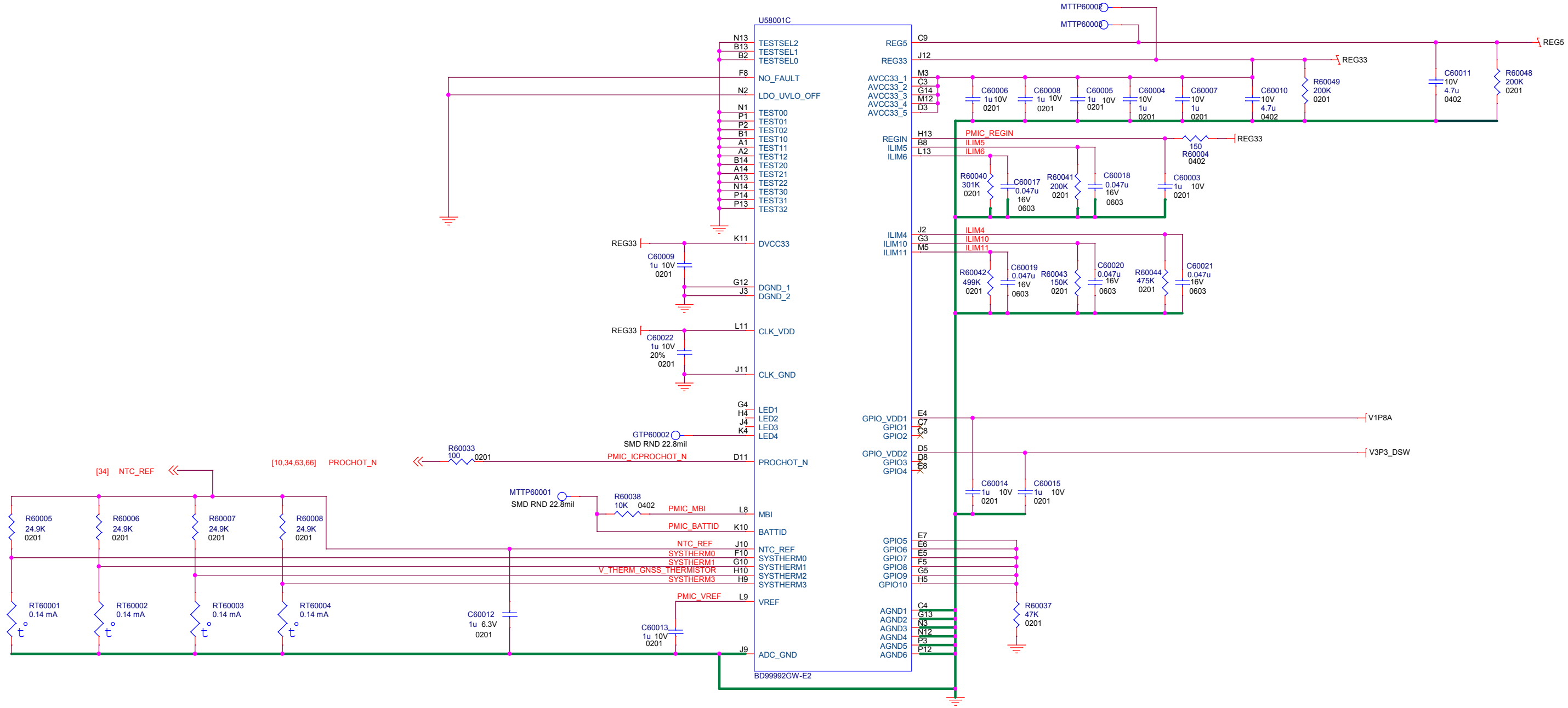


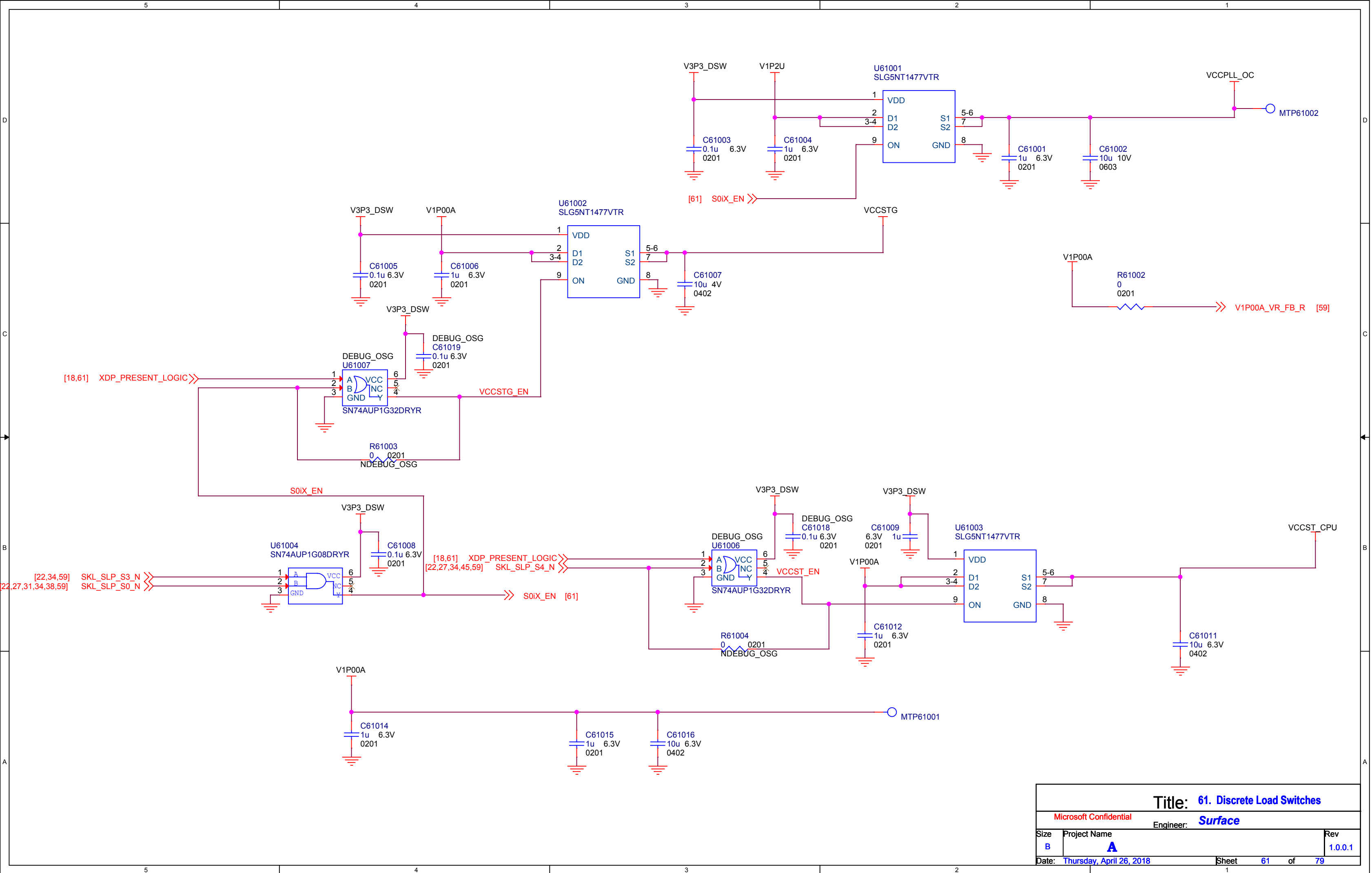


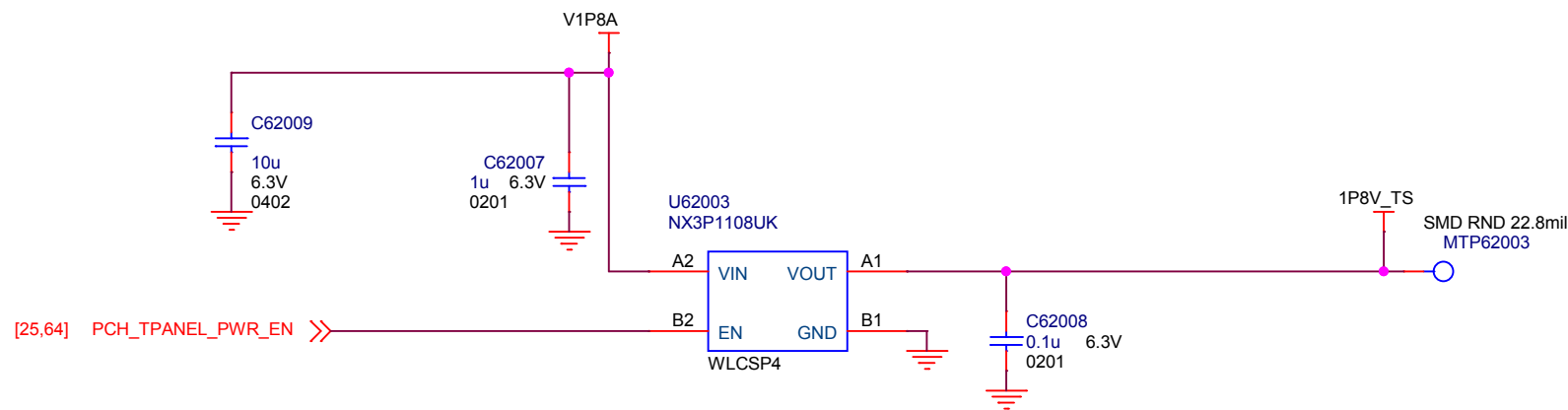
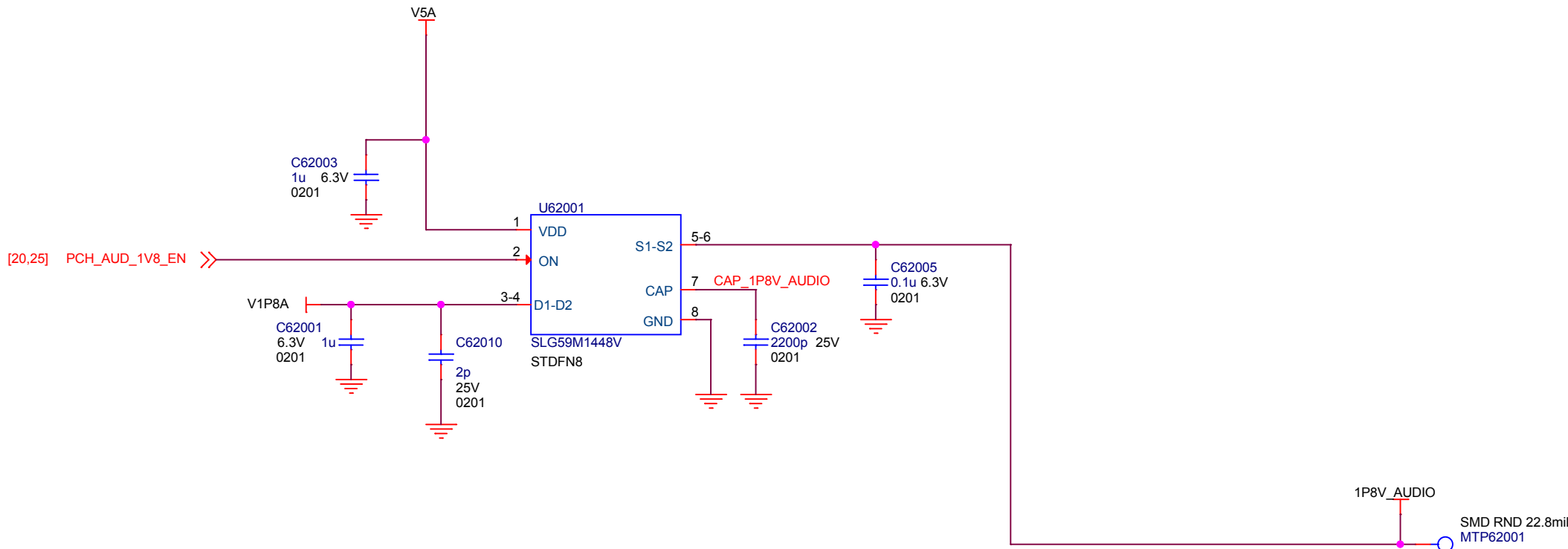


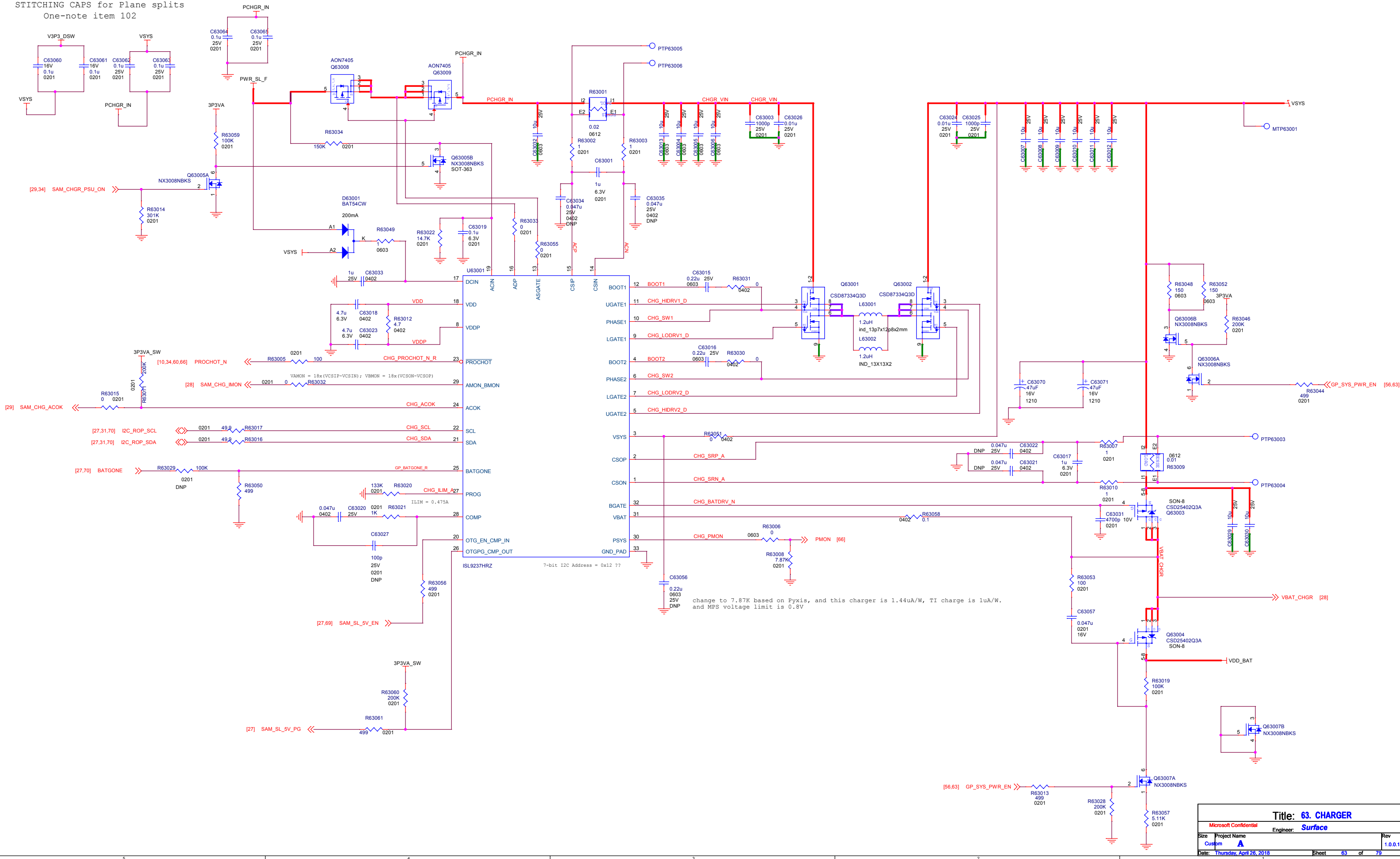




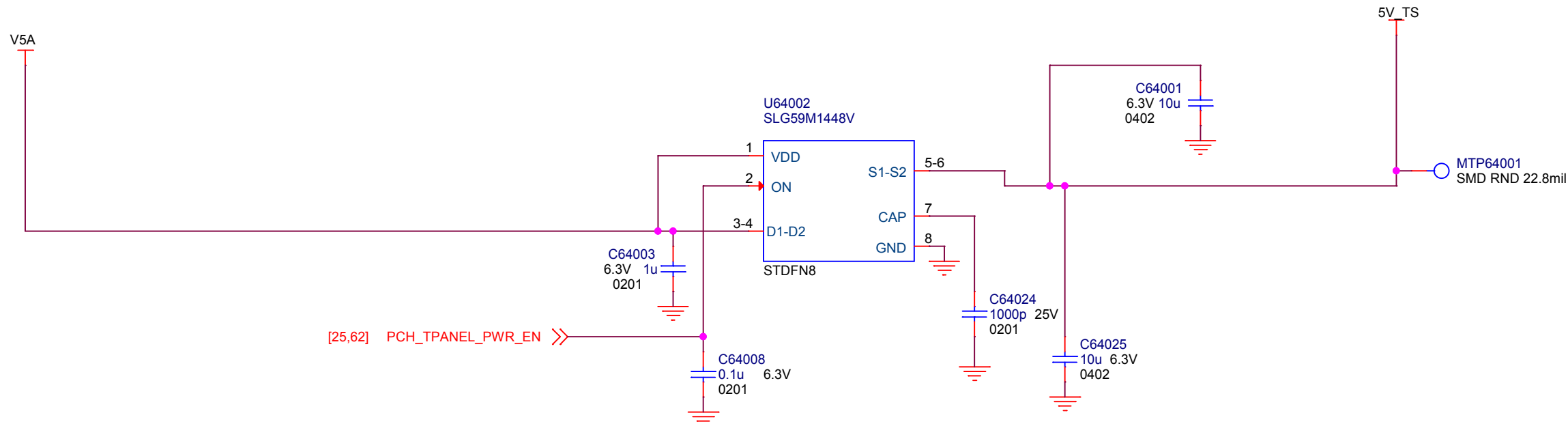




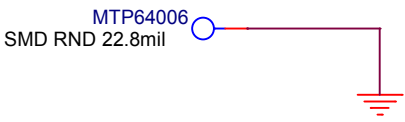
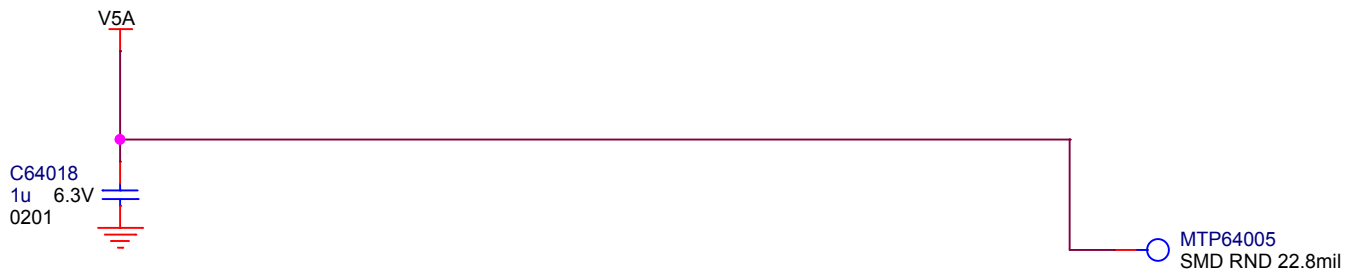
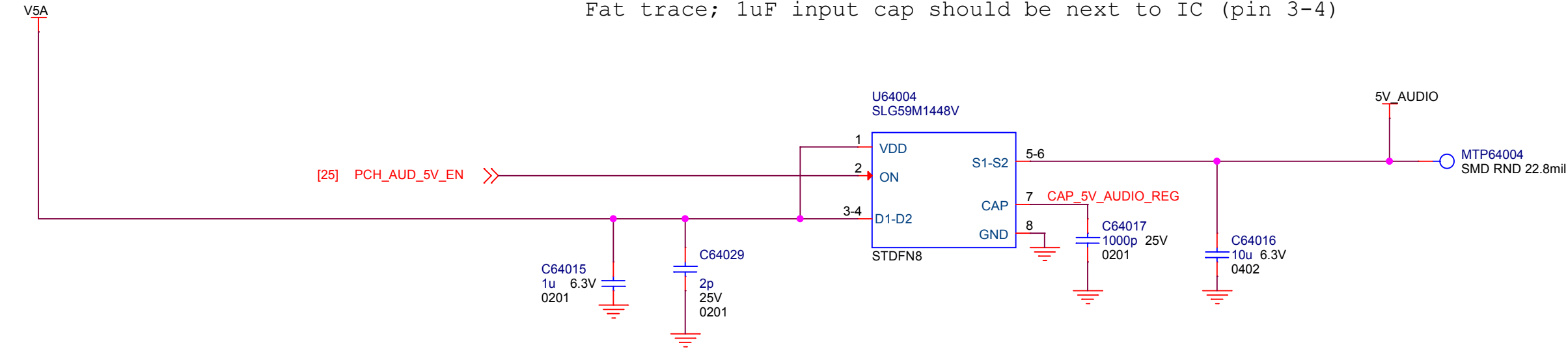






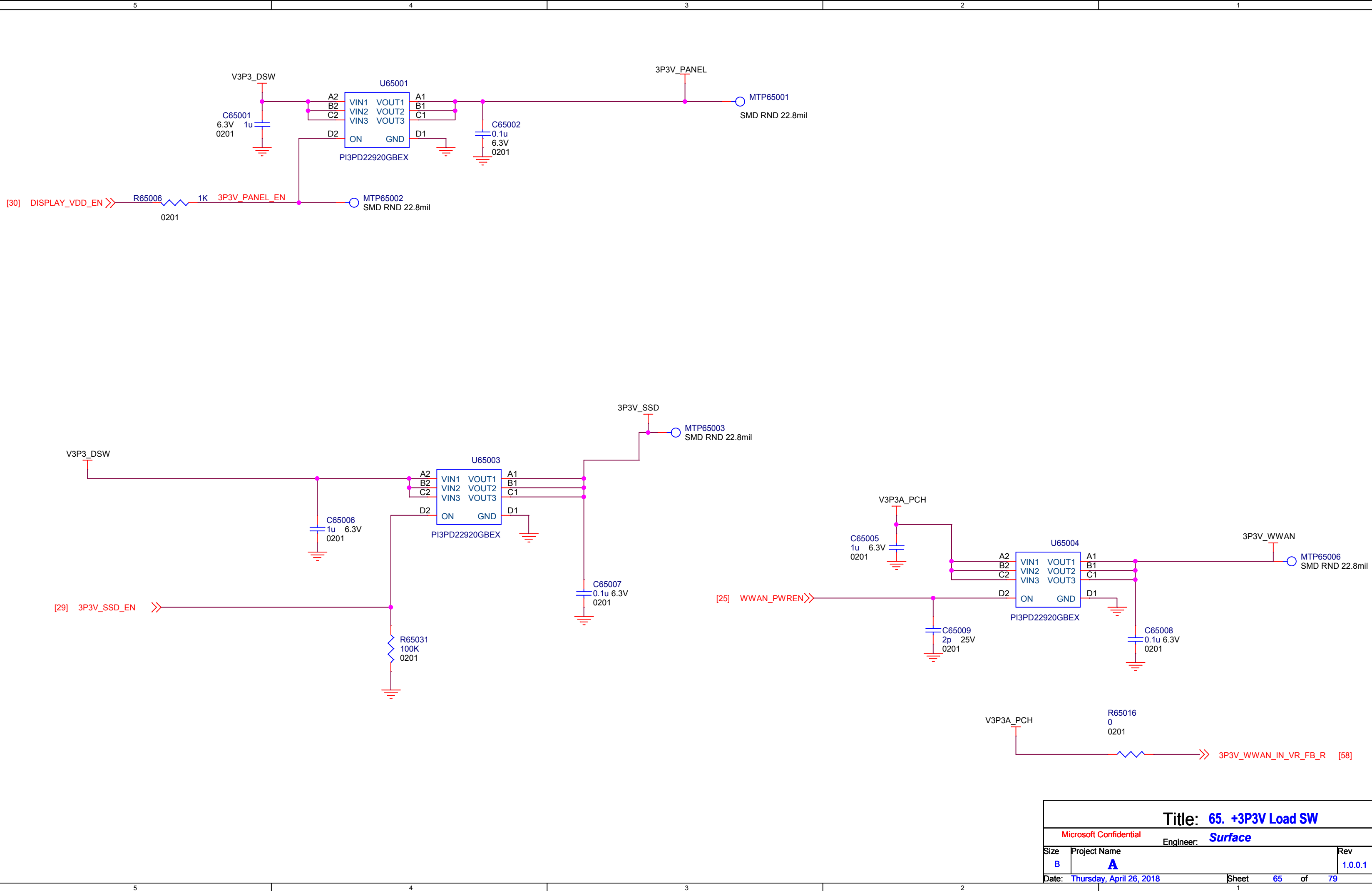


Note: connect pins 1, 3, 4 together at the chip  
Fat trace; 1uF input cap should be next to IC (pin 3-4)

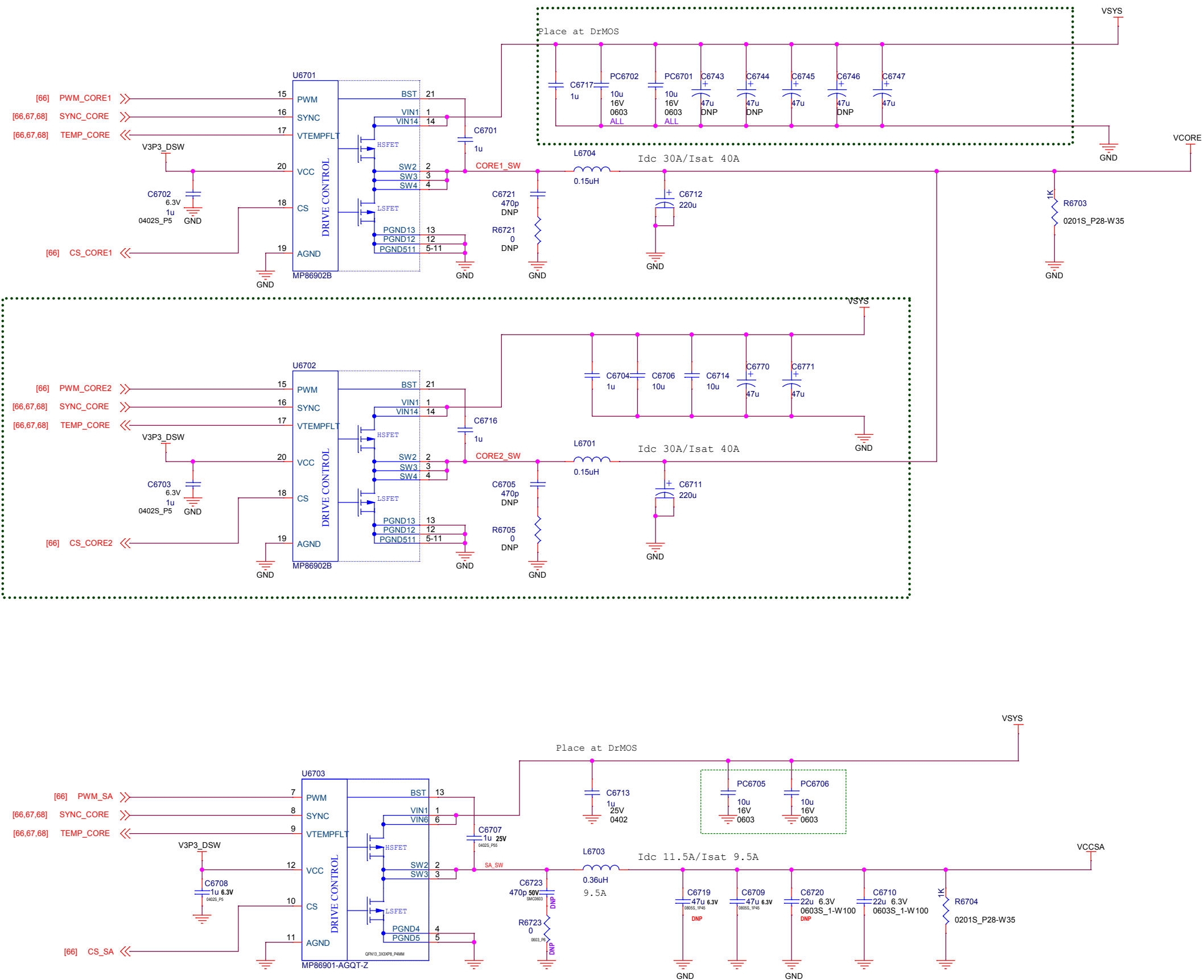


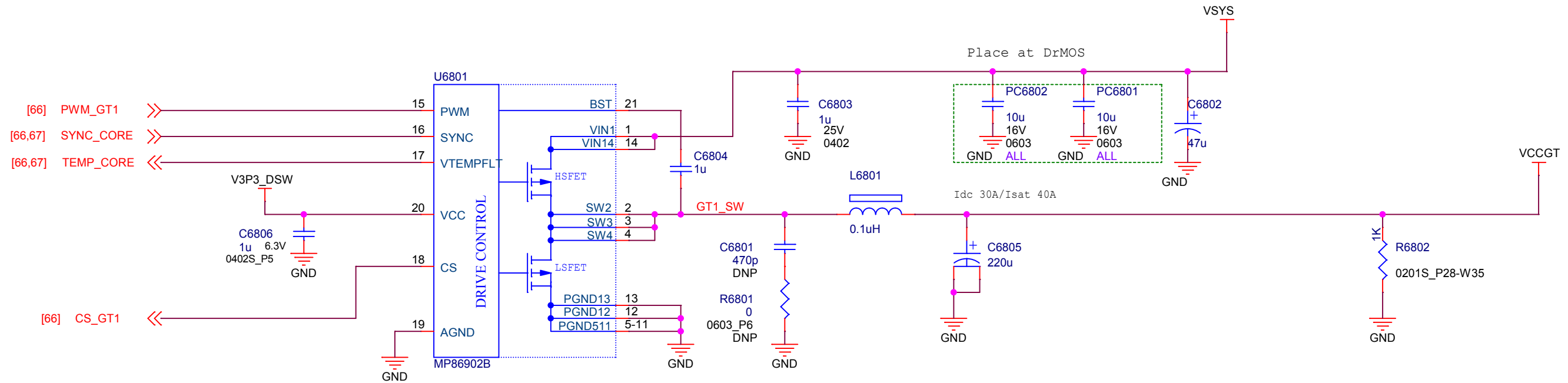
U SPECIFIC

Title: 64. +5V Load SW		
Microsoft Confidential		
Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 64 of 79	







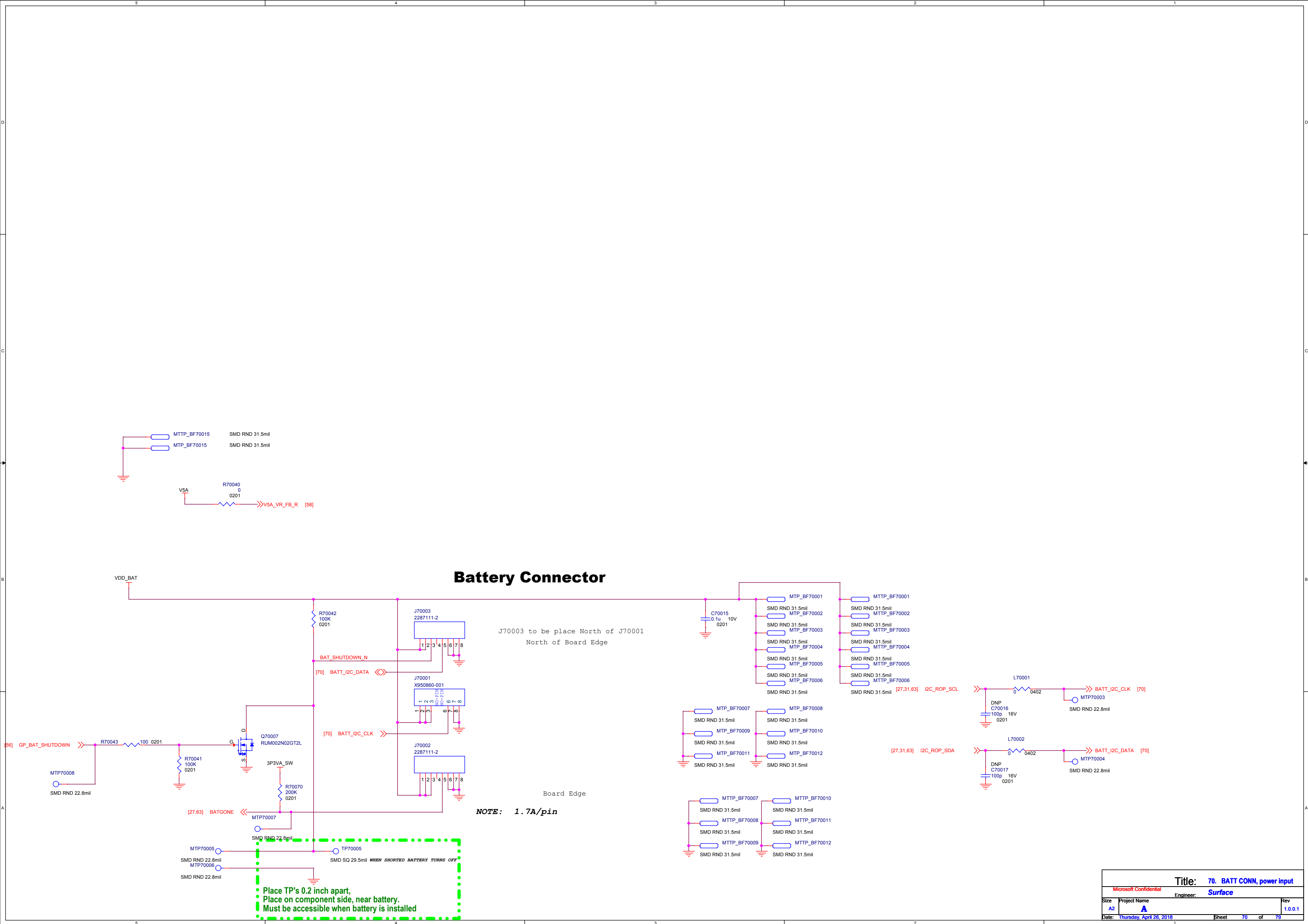


U SPECIFIC

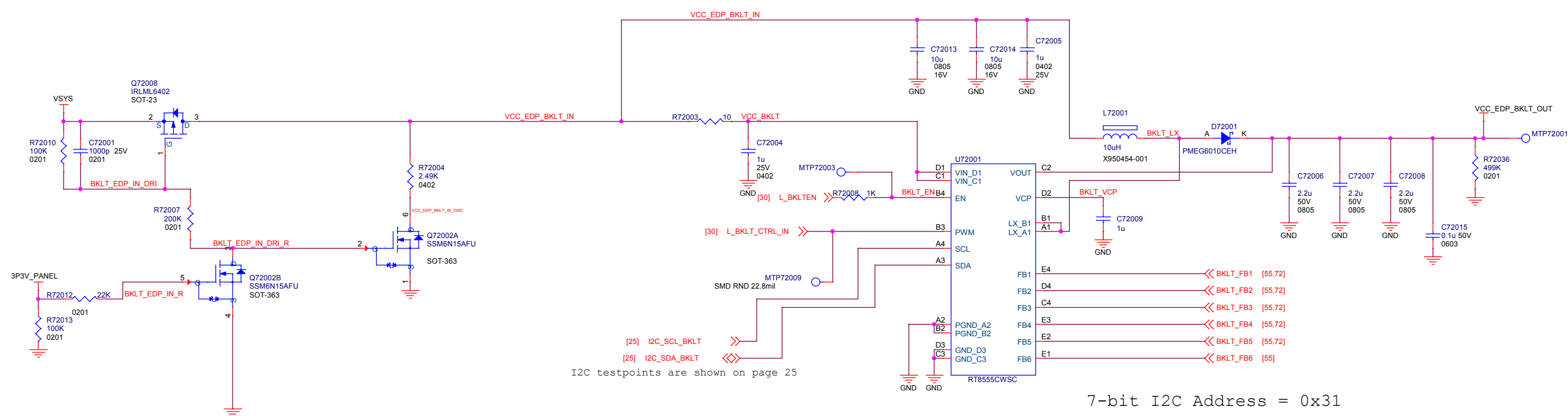
Title: 68. VCCGT		
Microsoft Confidential		
Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 68 of 79	







5					4					3					2					1																																																																																				
D																																																																																																								
C																																																																																																								
B																																																																																																								
A																																																																																																								
															<table><tr><td colspan="15">Title: 71. Empty</td></tr><tr><td colspan="15">Microsoft Confidential Engineer: Surface</td></tr><tr><td>Size</td><td colspan="13">Project Name</td><td colspan="1">Rev</td></tr><tr><td>B</td><td colspan="13">A</td><td colspan="1">1.0.0.1</td></tr><tr><td colspan="5">Date: Thursday, April 26, 2018</td><td colspan="5"></td><td colspan="5">Sheet 71 of 79</td><td colspan="5"></td></tr></table>										Title: 71. Empty															Microsoft Confidential Engineer: Surface															Size	Project Name													Rev	B	A													1.0.0.1	Date: Thursday, April 26, 2018										Sheet 71 of 79									
Title: 71. Empty																																																																																																								
Microsoft Confidential Engineer: Surface																																																																																																								
Size	Project Name													Rev																																																																																										
B	A													1.0.0.1																																																																																										
Date: Thursday, April 26, 2018										Sheet 71 of 79																																																																																														
5					4					3					2					1																																																																																				



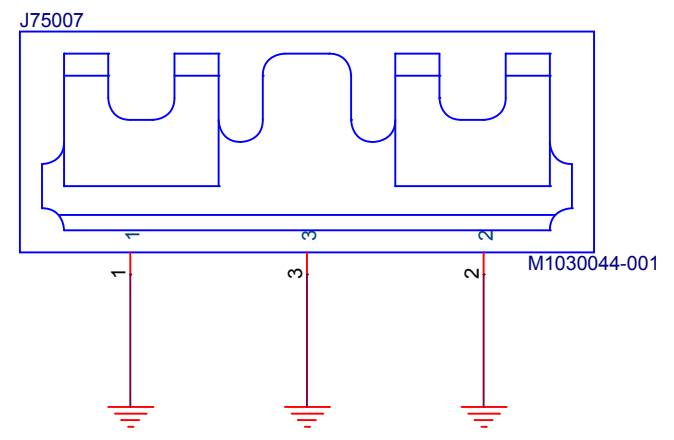
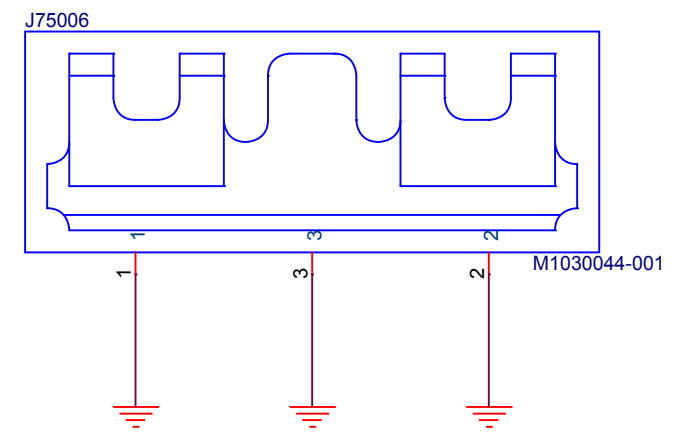
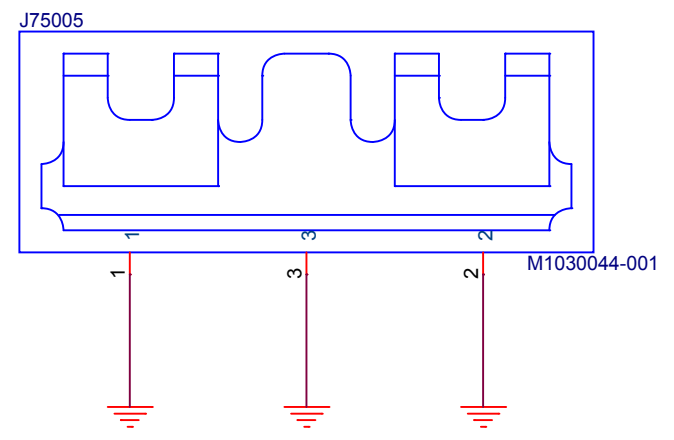
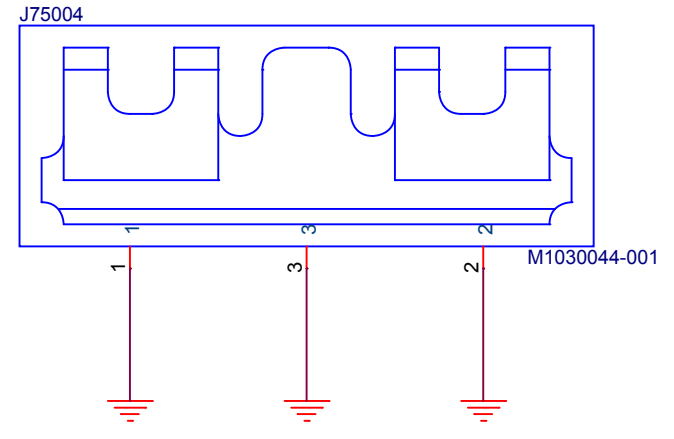
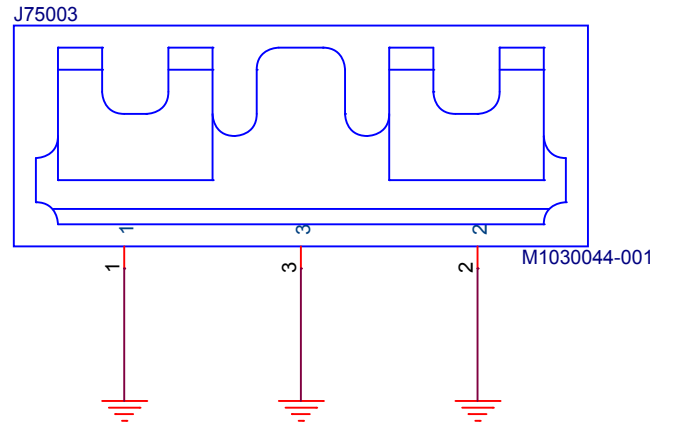
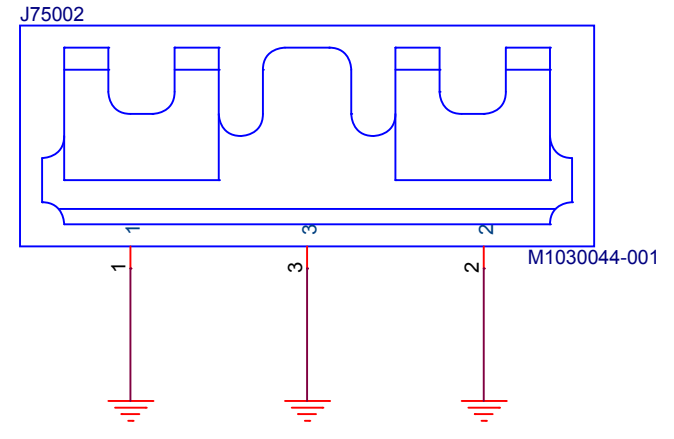
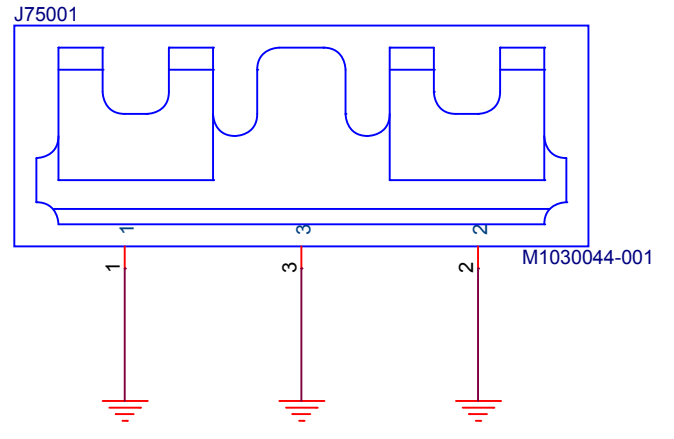
*isolated ground on layer 2 to tie Cin GND, Cout GND, and controller PGND together. Then tie this isolated ground plane to main GND under the exposed pads.*

SMD RND 22.8mil	MTP72004	⌵	BKLT_FB1	[55,72]
SMD RND 22.8mil	MTP72005	⌵	BKLT_FB2	[55,72]
SMD RND 22.8mil	MTP72006	⌵	BKLT_FB3	[55,72]
SMD RND 22.8mil	MTP72007	⌵	BKLT_FB4	[55,72]
SMD RND 22.8mil	MTP72008	⌵	BKLT_FB5	[55,72]

5					4					3					2					1				
D																								
C																								
B																								
A																								
Title: 73. Empty																								
Microsoft Confidential Engineer:																								
Size		Project Name																				Rev		
B		A																				1.0.0.1		
Date:		Thursday, April 26, 2018											Sheet		73		of		XX					
5					4					3					2					1				

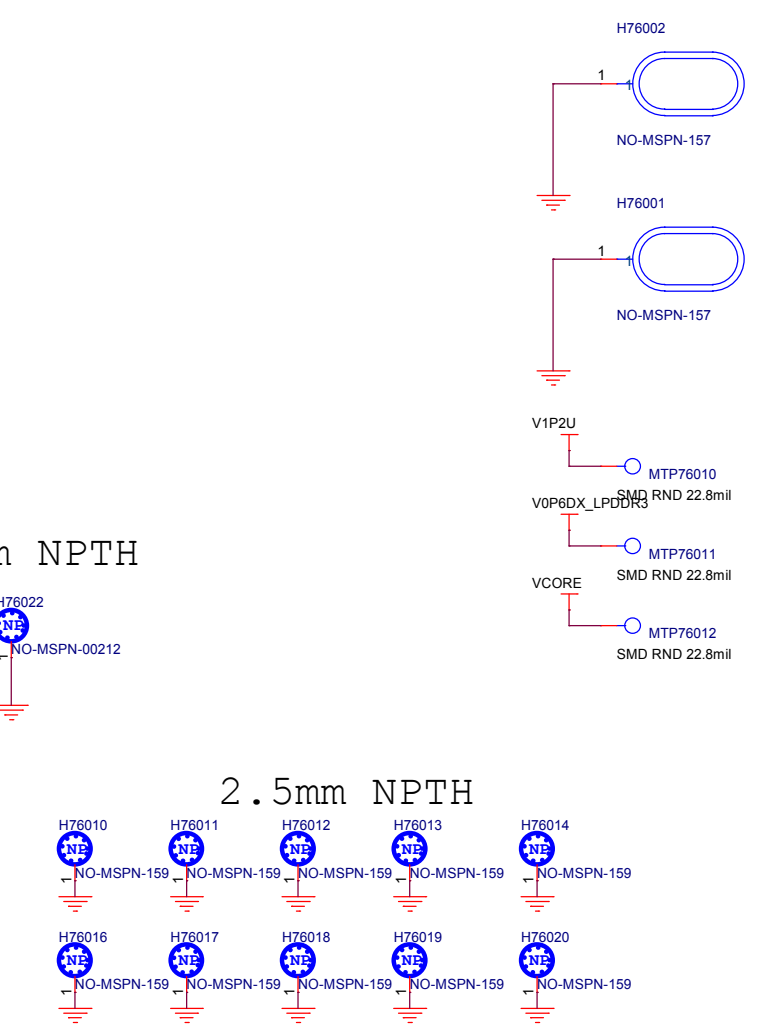
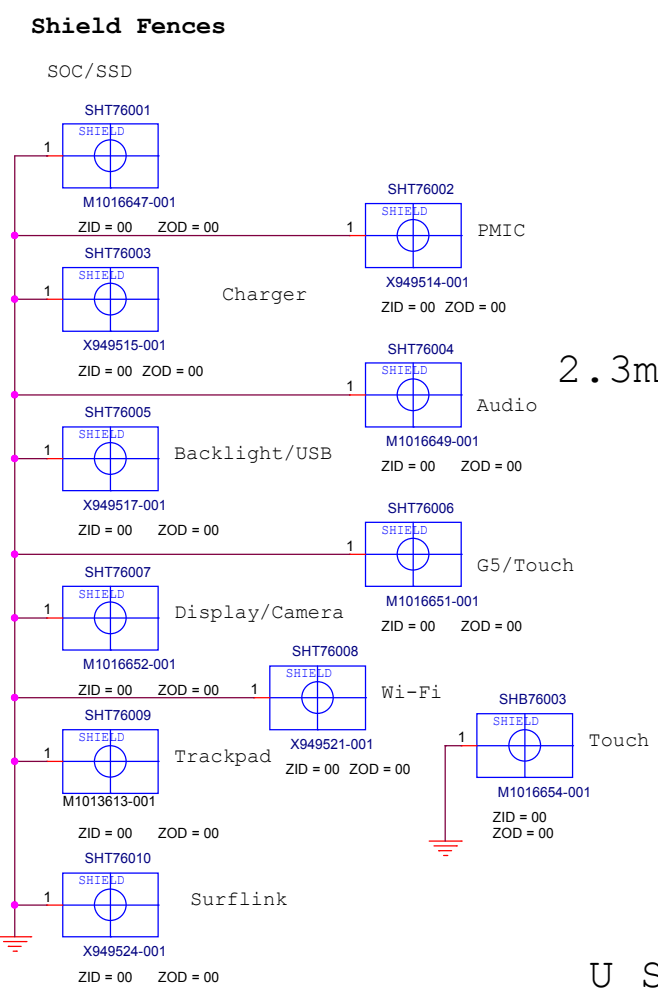
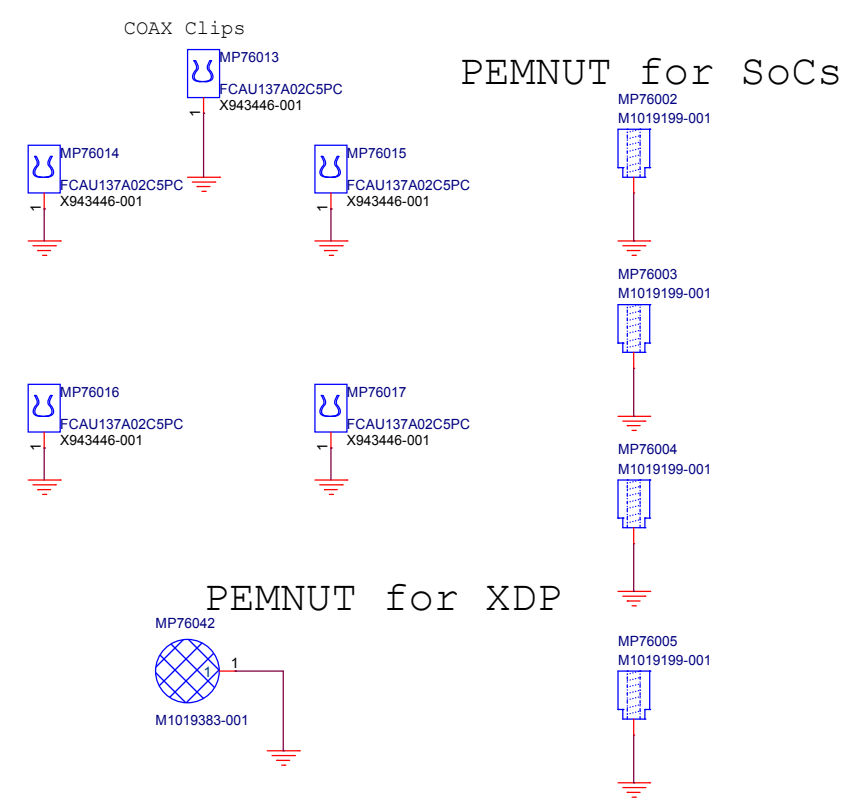
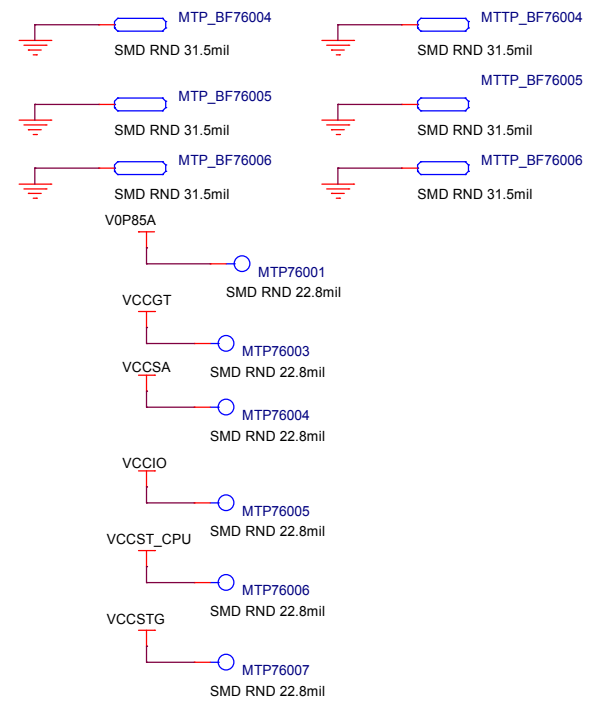
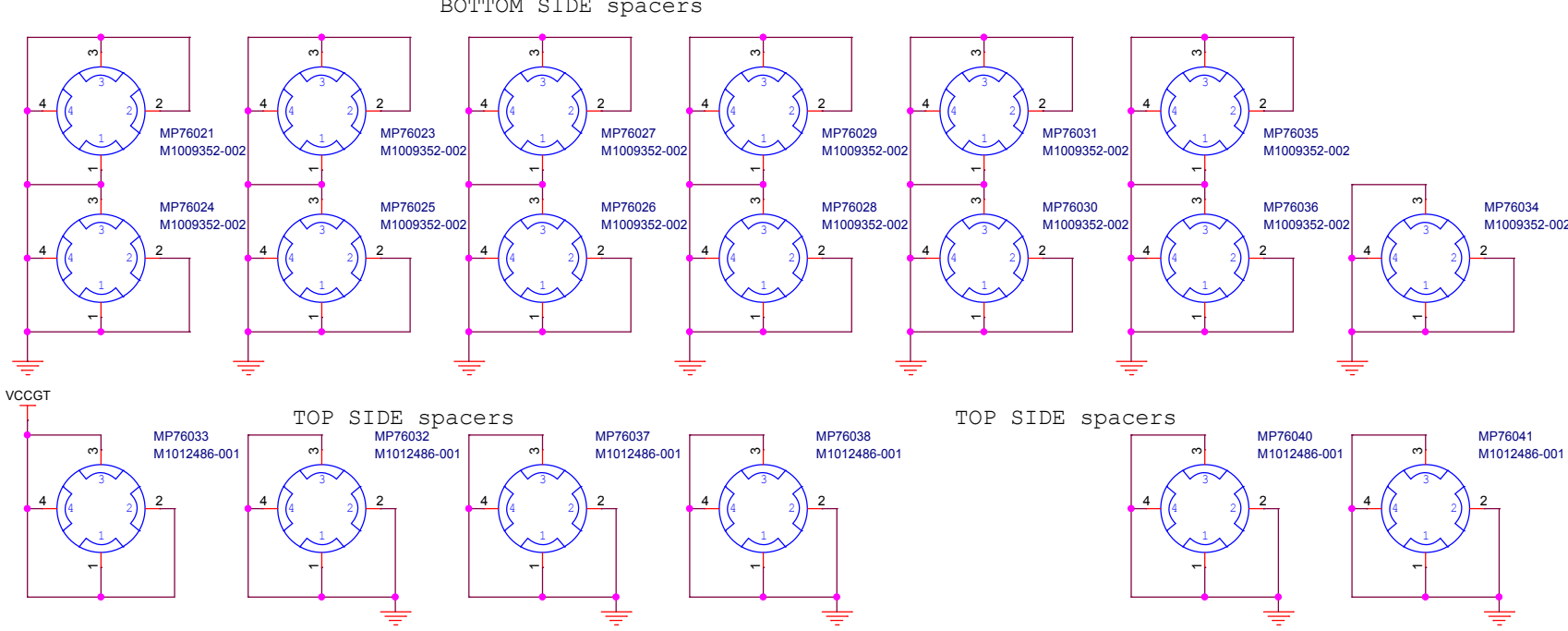


5					4					3					2					1					
D																									
C																									
B																									
A																									
Title: 74. Empty																									
Microsoft Confidential																									
Engineer:																									
Size	Project Name																				Rev				
B	A																				1.0.0.1				
Date:	Thursday, April 26, 2018										Sheet	74	of	XX											
5					4					3					2					1					



U SPECIFIC

Title: 75. Clips		
Microsoft Confidential		
Engineer: Surface		
Size B	Project Name A	Rev 1.0.0.1
Date: Thursday, April 26, 2018	Sheet 75 of 79	



Title: 76. TP's and Mech			
Microsoft Confidential			
Engineer: Surface		Rev	
Size C	Project Name A	1.0.0.1	
Date: Thursday, April 26, 2018	Sheet 76 of 79		

U SPECIFIC